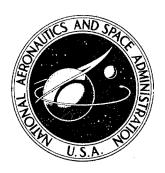
#### NASA CONTRACTOR REPORT



#### NASA CR-1115

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# GENERATION OF LONG TIME CREEP DATA OF REFRACTORY ALLOYS AT ELEVATED TEMPERATURES

by J. C. Sawyer and E. A. Steigerwald

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Prepared by
TRW EQUIPMENT LABORATORIES
Cleveland, Ohio
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## GENERATION OF LONG TIME CREEP DATA OF REFRACTORY ALLOYS AT ELEVATED TEMPERATURES

By J. C. Sawyer and E. A. Steigerwald

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Prepared under Contract No. NAS 3-2545 by TRW EQUIPMENT LABORATORIES TRW INC.
Cleveland, Ohio

for Lewis Research Center

NATIONAL AERONAUTICS AND SPACE ADMINISTRATION

#### **FOREWORD**

The work described herein was performed by TRW Inc. under NASA Contract NAS 3-2545. The purpose of this study was to obtain design creep data on refractory metal alloys for use in advanced space power systems.

The program was administered for TRW Inc. by E. A. Steigerwald, Program Manager. J. C. Sawyer was the principal investigator, and R. R. Ebert contributed to the program. The Technical Manager was Paul E. Moorhead, Space Power Systems Division, NASA-Lewis Research Center. The report was originally issued as TRW Report ER-7203.

#### ABSTRACT

Creep tests were conducted on selected refractory alloys in a vacuum environment (<1 x 10-8 torr) for times between 100 and 15,000 hours. Since the ultimate program goal was to provide design data for space electric power systems, particular emphasis was placed on measuring creep extension below 1%. The resulting data were evaluated in terms of the relative properties of columbium, molybdenum, tantalum, and tungsten-base alloys. Larson-Miller and Manson-Haferd techniques were used to present the data in parametric form. In the 1800°F (982°C) to 2200°F (1204°C) temperature range, the molybdenum-base alloys TZC and TZM possess the best creep properties for potential turbine applications. The variability of the creep properties as a function of heat of material was determined for the T-111 alloy.

In addition to comparison of alloy creep properties, chemical analysis, metallography, and tensile test data are presented to characterize each of the materials before and after creep testing.

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#### I INTRODUCTION

Material requirements for space electric-power systems necessitate the use of alloys which provide both high-temperature strength and resistance to liquid-metal corrosion. Alloys based on the refractory metals columbium, molybdenum, tantalum, and tungsten are currently the most suitable materials which meet these specifications.

The design of space electric-power systems which operate for a year or more requires a thorough knowledge of the elevated temperature creep properties of the alloys involved under conditions which simulate the service environment. While turbine and clad components of space power systems are not necessarily exposed to the vacuum of space, they do operate in environments such as metal vapor or liquid metals where the partial pressure of reactive gases is extremely low. Consequently, to obtain representative creep data it is necessary to perform tests in a vacuum environment of  $< 1 \times 10^{-8}$  torr which causes little or no interstitial contamination over long periods of time.

The initial work of this program was to generate 1,000 hour creep data on selected refractory alloys which have potential use in advanced space electric-power systems. The materials examined were obtained in the form of rolled sheet, forged or rolled plate, and vapor-deposited tubing. The sheet and vapor-deposited tubing were representative of materials to be used for cladding and tubing applications while the plate provided material comparable to the form employed for turbine components. Following the initial tests, the alloys with the greatest creep strength were selected for additional evaluation aimed at developing 5,000 - 15,000 hour creep data for design purposes.

### II EQUIPMENT

#### A. Creep Chambers

Creep testing of the refractory alloys was carried out in fourteen vacuum test chambers, seven of which are shown in Figure 1. The control console, shown in Figure 2, contains the necessary temperature controllers, ion pump power supplies, pressure readout, and other instrumentation for all fourteen systems (1)\*.

Figure 3 and 4 are a photograph and schematic diagram of a single creep chamber with a double walled, water cooled removable bell. The only penetrations are a 4-inch diameter optically flat sight port slanted 5 degrees and a magnetically rotated shutter protecting the window. The spool piece, immediately below the main flange, is also double walled for water cooling. The spool piece penetrations consist of high and medium current feedthroughs, octal-tublar thermocouple feedthrough, cold cathode vacuum gage, roughing valve, and residual gas analyzer. The integral ion pump, beneath the spool piece, consists of sixteen cubicles which provide a pumping speed of at least 400 liters per second. An integral pump was used rather than an appendage pump because of the advantages of space conservation and possible higher pumping speeds. The external weight pan capable of applying 2000 pounds of dead-weight load to the specimen in the test chamber is located in the lower part of the unit. Lead weights are applied to the specimen by means of a hydraulic jack built into the weight support. The pull rod passing through the chamber utilizes a stainless steel bellows to isolate the penetration from the atmosphere. Because barometric pressure changes acting on the bellows cause the absolute magnitude of the load to vary, the minimum external weight for 1 percent accuracy of load is about 350 pounds. For lower loads, the internal weights of stainless steel are used, thus eliminating the bellows in the load train. In this case the pull rod attached to the external weight pan is replaced by an internal weight pan support which is actuated by the external hydraulic jack. With this arrangement, the internal weights can be applied to the specimen by the external jack acting through the bellows.

<sup>\*</sup> Numbers in parentheses refer to references in the Bibliography.

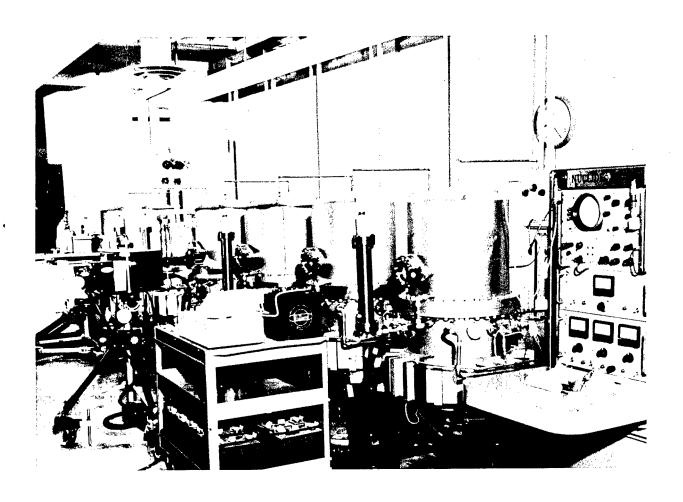


FIGURE 1 SEVEN OF FOURTEEN ULTRA-HIGH VACUUM CREEP UNITS



FIGURE 2 CONTROL CONSOLE FOR ULTRA-HIGH VACUUM CREEP LABORATORY

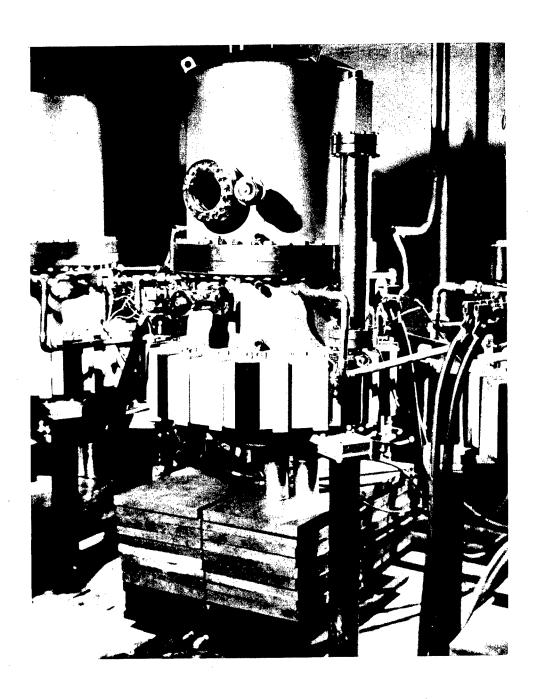


FIGURE 3 ULTRA-HIGH VACUUM CREEP CHAMBER

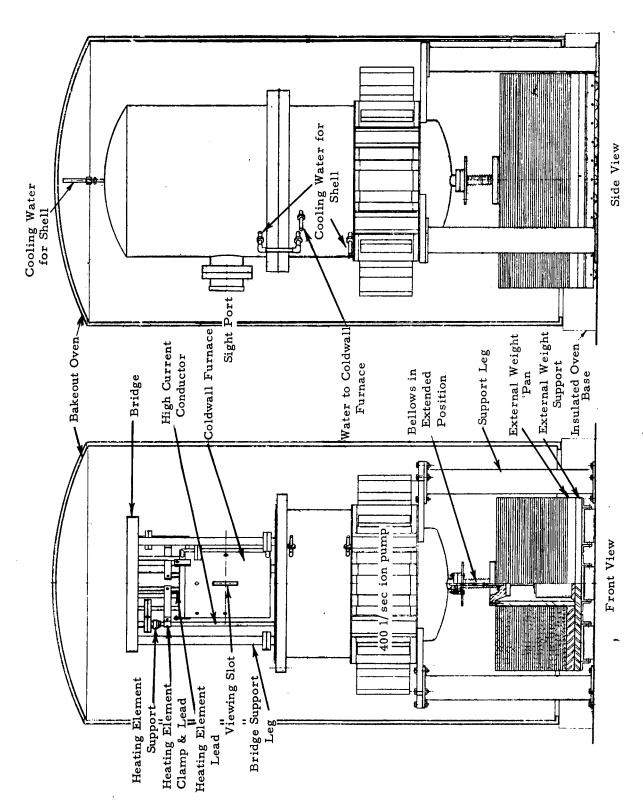


FIGURE 4 SCHEMATIC OF ULTRA HIGH VACUUM CREEP UNIT

The unit with the bell removed, to expose the bridge and furnace construction, is shown in Figure 5. The bridge is the uppermost support for the specimen with the load being carried by three tubular legs which also serve as a means of conveying cooling water to the furnace. By unbolting three flanges, the furnace coldwall and shield pack can be removed exposing the (8" x 2" dia.) heating element (Figure 6). With this element design and six tantalum radiation shields, the temperature gradients over the 2-inch gage length lie within the limits of:

1800°F ( 982°C)	0-5°F (0-3°C)
2000°F (1093°C)	0-7°F (0-4°C)
2200°F (1204°C)	0-9°F (0-5°C)

At 2600°F (1427°C), the observed gradient was approximately 10°F (5-6°C).

All fourteen systems are of ultra-high vacuum construction to maintain a pressure of  $< 1 \times 10^{-8}$  torr during testing.

#### B. Temperature Control

The high-current, low-voltage power required to bring the furnace to operating temperature is obtained from a tapped 12 KVA step-down transformer and saturable-core reactor. The control signal for the saturable-core reactor is supplied by a magnetic amplifier and temperature controller at the main console.

The transistorized three-mode controller is capable of holding the furnace temperature cycle to  $\pm 1^{\circ}F$ . Two tungsten-3% rhenium/tungsten-25% rhenium thermocouples located between the heating element and the first radiation shield serve to sense and control the furnace temperature. These thermocouples are wired in parallel at the controller to provide redundancy. A third thermocouple, also located between the heating element and the first radiation shield, is attached to a multipoint recorder for general monitoring purposes. A fourth tungsten-3% rhenium/tungsten-25% rhenium thermocouple is calibrated before use and is attached directly to the specimen. This special thermocouple is used during the initial setting of the furnace temperature. All four thermocouples are connected to a 150°F  $\pm$  1/4°F (52°C) reference junction oven.

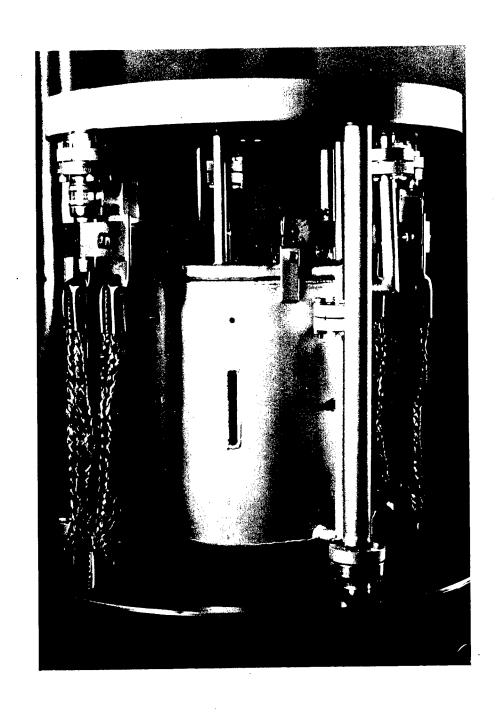


FIGURE 5 CREEP UNIT WITH BELL REMOVED SHOWING BRIDGE AND COLDWALL FURNACE

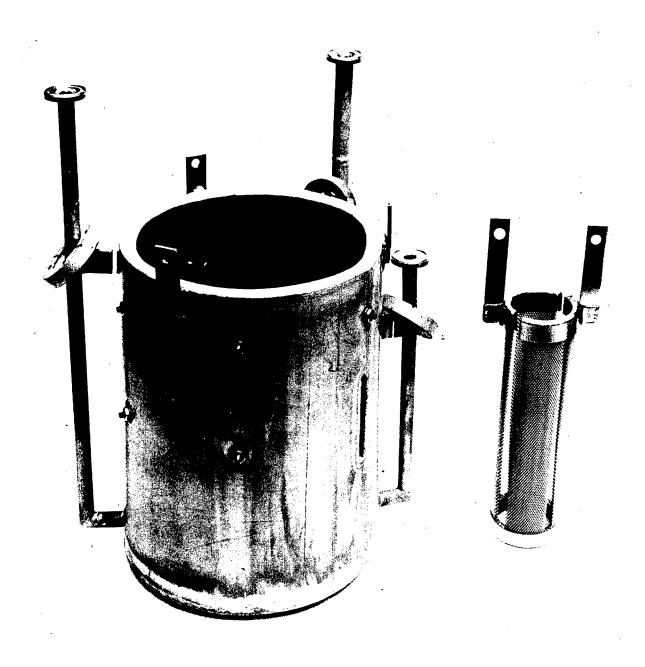


FIGURE 6 FURNACE COLDWALL AND TUNGSTEN MESH ELEMENT

Thermocouples of all types are subject to a time dependent change in EMF output under isothermal conditions. To compensate for these anticipated changes, the absolute temperature during test was maintained by an optical pyrometer. In practice the specimen was brought to the desired test temperature using the calibrated thermocouple attached to the specimen as a temperature standard. The use of this thermocouple was continued during the temperature stabilization period which lasted 50 to 100 hours. At this time a new reference was established using an optical pyrometer having the ability to detect a temperature difference of 1°F. In use the pyrometer was sighted on the specimen with the field of view being 0.050 inch diameter. Filters were introduced in front of the telescope lens until a reading was obtained on the instrument meter. The pyrometer was then sighted on a tungsten filament lamp contained inside the vacuum chamber. This filament was heated by DC current to obtain the same reading as observed with the specimen. The current passing through the filament was then measured to an accuracy of one part in 10,000 thus establishing an internal standard. Periodically the temperature of the specimen was measured at the same spot and based on the readings, corrective adjustments were made at the controller. The reference lamp in the vacuum chamber was also checked to determine whether clouding of the sight port was affecting the accuracy of the temperature readings. No evidence of sightport clouding was observed during this program. Maintenance of the temperature in this manner was based on the assumption that the emissivity of the standard lamp filament and the specimen do not change significantly with time (2). This assumption appears to be valid, for no significant change in input power to the furnace was observed during creep tests lasting more than 10,000 hours.

The use of an optical pyrometer to maintain isothermal conditions allows an assessment of the time dependent characteristics of the calibrated thermocouple attached to the specimen. Figure 7 shows the change in EMF output of tungsten-3% rhenium/tungsten-25% rhenium thermocouples as a function of time at various temperatures. These data reveal that a significant linear decrease occurs in the EMF output at all temperatures, and that the drift is not the same for all tungsten-rhenium thermocouples. Figure 7 also shows that stabilization of the EMF output does not occur even at times up to 12,000 hours. This was complemented by the observation that the EMF output of the control and recorder thermocouples continue to drift downward at about the same rate despite the fact that they have seen previous service.

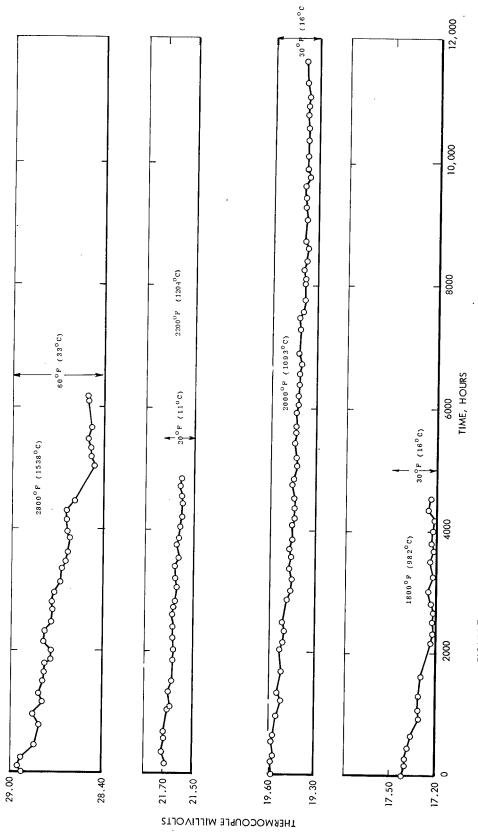


FIGURE 7 TIME DEPENDENT CHANGE IN EMF OUTPUT OF TUNGSTEN - 5% RHENIUM/TUNGSTEN - 25% RHENIUM THERMOCOUPLES AT VARIOUS TEMPERATURES.

#### C. Creep Measurement

The extensometer, Figure 8, used to measure creep consisted of two telescopes mounted one above the other with the lower telescope movable by means of a micrometer screw. The two images produced were optically superimposed and magnified 40X. A mercury lamp in combination with a condensing lens and mirror provided illumination of the field of view. At 2600°F (1427°C) and higher, where the specimen spectral emission overrides the external illumination, the mercury lamp was operated at twice its normal wattage to provide the additional intensity.

The fiducial marks used were horizontal lines 2.00 inches apart scribed on the specimen surface. By adjusting the micrometer screw, the images of the two lines could be superimposed and the distance between them read directly from the micrometer. The accuracy achieved was equal to the sensitivity of the equipment, i.e., 50 micro-inches.

#### D. Residual, Gas Analysis

At least six of the vacuum creep units were equipped with a residual gas analyzer. These may be seen in Figures 1 and 3 as a large tublar member to the right of the removable bell. The instrument was a time-of-flight mass spectrometer schematically illustrated in Figure 9. The principle of operation is based on the property that the time for a given ion to traverse a spatial distance is proportional to the square root of the mass. Referring to Figure 9, the ions are generated by electron bombardment of the residual gas in the ionizing region. Batches of ions are accelerated into the flight tube 10,000 times each second. The termination of the flight is sensed by the electron multiplier at the right end of the tube and recorded as shown in Figure 10.

Monitoring of the residual gas composition during various tests, Table 1, shows that the bulk of the gas was composed of  $H_2O$ ,  $CO-N_2$ , and A. The gas content as a function of holding time for a T-111 specimen (Table 1-B) tended to decrease in water vapor and increase in hydrocarbon. During heating to  $3000^{\circ}F$  (1649°C) an appreciable increase in hydrogen evolution occurred presumably as a result of specimen outgassing. In general the pattern of residual gas composition was not constant and depended on the specific unit and specimen being tested.

12

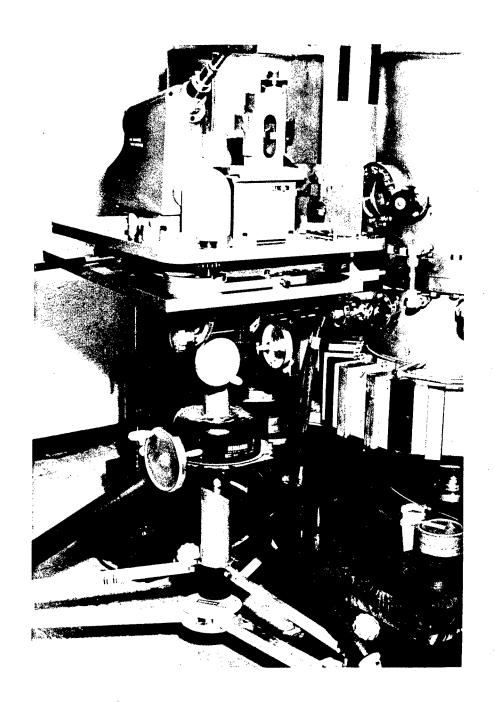


FIGURE 8 OPTICAL EXTENSOMETER

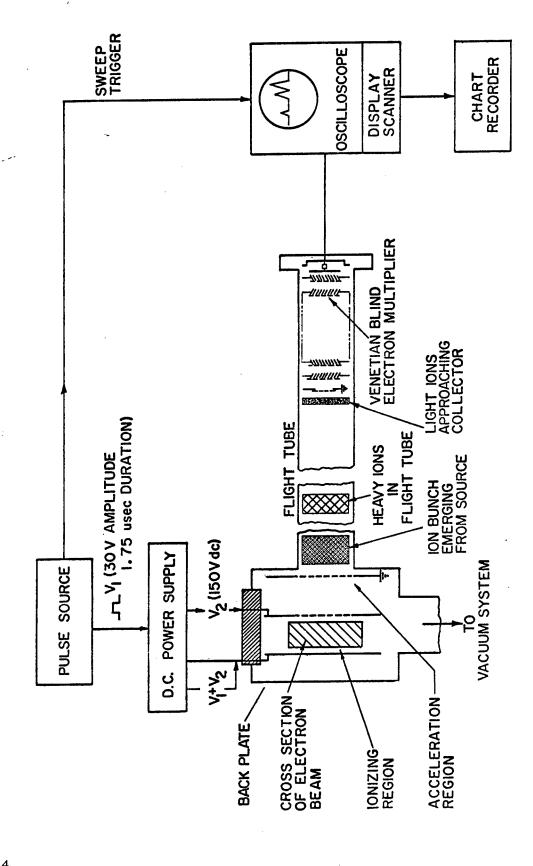


FIGURE 9 SCHEMATIC DIAGRAM OF RESIDUAL GAS ANALYZER

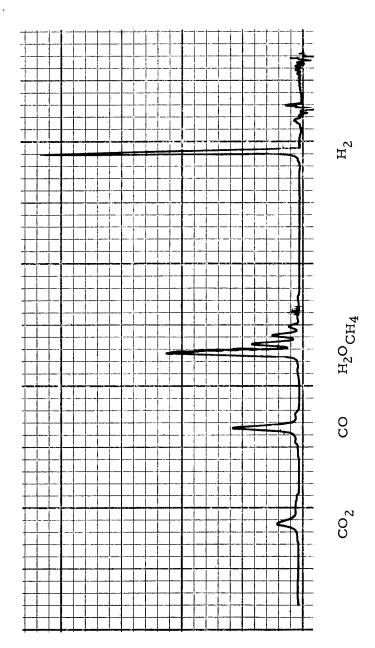


FIGURE 10 RECORD OF 10-8 TORR RESIDUAL GAS ANALYSIS

TABLE 1 - Residual Gas Analysis

A. Composition of Residual Gas in Vacuum Creep Chambers

202	9	27	6	6	20		17	5	9	5	9	6	11	10	∞	4	9	9	9	6
۸	11		1	14	9		<b>~</b>	10	14	14	13	œ	11	14	15	14	14	12	10	7
CO-N2	22	27	31	34	34		7	17	19	56	23	30	22	31	27	97	28	97	31	65
H <sub>2</sub> O	28	31	17	18	30		. 99	31	27	17	22	34	19	16	18	24	21	22	28	14
Percent CH4-O	9	2	8	7	4	Specimen	9	∞	2	rV.	9	2	9	9	9	9	ις	9	7	0
CH <sub>4</sub>	ı	ı	1	-	٦		7	4	3	3	2	0	2	7	3	7	7	4	0	0
He	. 2	1	1	-	-	t T-111	<b>▽</b>	5	9	9	9	33	5	5	9	<b>∞</b>	9	9	4	0
$\frac{H_2}{H_2}$	24	13	40	16	4.	1 Unit	7	19	17	20	20	6	19	16	16	15	18	17	15	4
Pressure Torr	$4.4 \times 10^{-9}$	$6.8 \times 10^{-10}$	$6.9 \times 10^{-10}$	$1.9 \times 10^{-9}$	$6.6 \times 10^{-9}$	iș of Unbaked	$6.0 \times 10^{-8}$	$7.0 \times 10^{-7}$	0 X	о Х	×	2 X		<b>x</b> 9	∞ ×	$3.2 \times 10^{-8}$	$0 \times 10^{-}$	$4.0 \times 10^{-8}$	$2.4 \times 10^{-8}$	$5.5 \times 10^{-9}$
Time	1535	1912	1175	3340	520	B. Analysis	0.0	0.8	3. 1		6.5	71:8	73.8	73.9	74.9	75.9	76.5	77.5	96.5	268.0
rature	1093	1124	1093	1013	1760		16	204	315	538	648	648	1427	1649	1649	315	1427	1427	1427	1427
Temperatur F	2000	2056	2000	1856	3200		09	400	009	1000	1.200	1200	2600	3000	3000	009	2600	2600	2600	2600
Unit No.	2	က	9	8-1	8-2															

#### E. System Reliability

Creep tests of 1,000 to 15,000 hours duration require that the equipment be capable of maintaining the desired vacuum and temperature throughout the test period. To accomplish this, each individual creep unit was protected such that a failure of any one was an independent event which did not affect the operation of the others.

To allow for failure of city power, a stand-by-diesel engine driving a 100 KVA, 480 volt, three-phase generator was used to supply auxiliary power within seven seconds after loss of city power. This system was checked weekly for proper operation.

Cooling water for the creep chambers was provided by a recirculating system with an external cooling tower and a circulating pump capable of providing 80 gallons of filtered water per minute. Redundant pumping and filtering were used with automatic change-over in the event of failure of either pump or filter. The recirculated water was chromate treated and make-up water was supplied from the city mains through a water softener and deionizer. A weekly check was maintained of the pH, chromate, chloride, and hardness content. Typical values were:

pH - 8-9 ppm Chloride - 4-7 ppm

Chromate - 2000 ppm Hardness - 4 ppm

The laboratory air conditioning was operated constantly to maintain a temperature of 70-73°F (21-23°C) and humidity was controlled to prevent rusting of the instruments. Despite periodic failures of city power, the system has been in operation for over 20,000 hours (2.3 years) without shutdown.

#### III TEST PROCEDURE

#### A. Specimens

Creep tests were conducted with two forms of material, sheet, and plate and the geometries of the test specimens are shown in Figures 11 and 12. As a general rule the orientations of the specimens with respect to the working direction of the material were as follows:

Material Form	Specimen Axis Parallel to:						
Sheet	Rolling Direction						
Plate	Primary Extruding Direction						
Disc Forging	Radius of Disc						

The first operation following machining was to locally polish the specimen surface in preparation for gage mark scribing. The specimen was then placed on a Kentron Hardness Tester and moved under the Knoop diamond indenter. The scribe marks produced by the diamond using 100-200 gram load were transverse to the specimen axis and 2.00 inches apart. The next operation was to attach the calibrated thermocouple to the specimen. For bar specimens, the thermocouple was wired to the gage section using molybdenum wire. With sheet specimens, two 0.020-inch holes were drilled in the specimen just outside the gage section. Thermocouple wires were passed through these holes and spot welded to the specimen surface.

#### B. Test Setup

Installation of the specimen and pumping the vacuum chamber followed a routine procedure. The specimen was first installed in the grips which were equipped with universal joints to provide for axial loading and specimen expansion during heat-up. Thermocouples were attached to lead wires and the load placed on the lower pullrod. In all cases ultra-high vacuum procedures were carefully followed to minimize contamination.

Initial pumping of the system was accomplished by four sorption pumps cooled with liquid nitrogen. After roughing, the ion pump was turned on and the complete system baked at 400°F for at least 8 hours.

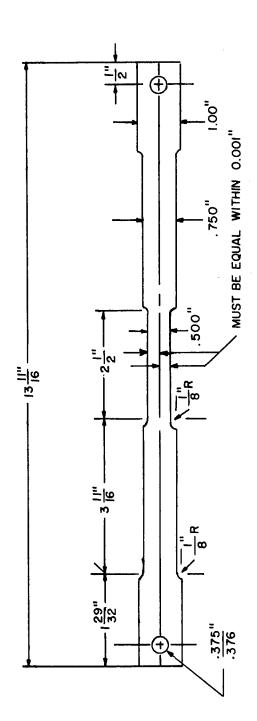
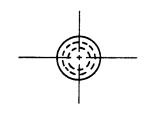
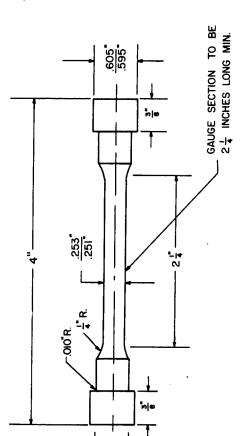


FIGURE 11 CREEP SPECIMEN USED FOR SHEET STOCK





NOTE: ANY TAPER IN GAUGE SECTION MUST BE TOWARDS CENTER

ALL TOLERANCES ± .010" UNLESS OTHERWISE NOTED

FIGURE 12 CREEP SPECIMEN USED FOR PLATE STOCK

#### C. Creep Testing

Following baking and cooling, temperature was manually raised to the desired value with the pressure, which increased during heating, being kept below  $1 \times 10^{-6}$  torr. Depending on the cleanliness of the system, the required time to reach temperature was about eight hours. When necessary, heat treatment was performed in situ.

Following heat treatment the temperature was allowed to decrease to at least 600°F (316°C) prior to reheating to the test temperature. Prior to application of the load, a 1-2 hour stabilization period at temperature was employed. For the first hour of test, creep readings were taken every few minutes. After this, extension measurements were made on a periodic basis depending on the particular creep rate involved. In addition to the creep measurements, data relative to the various test parameters were recorded (see Figure 13).

When a creep test was completed, the furnace was cooled to room temperature under load and the specimen removed for post-test examination. In selected tests, chemical analysis, hardness, and tensile strength determinations were made.

		1	t	i	ı	1	ı	1	ı	1
						1		Ì	1	
	Date	10/13/66	10/14/66	10/17/66	10/18/66	10/19/66	10/20/66	10/21/60	10/24/66	10/25/66
	Time	07.35	07:40	07:30	07:30	07:45	07:35	07:30	07:30	10:35
·	Press	3,5×10	3.7×10	4.2×109	4.0×10 -9	3.2×109	3,8x10	3,1×10-9	3.0×109	4.0×10
•	Volts	15.5	15.6	15.6	15.6	15.6	15.6	15.6	15.6	15,6
•	Amps	378	378	378	378	378	378	378	380	380
•	Set Point	20+270	20+27/	20127/	20+27/	20+27/.	20+27/	20+271	20+27/	20+27/
•	PB%	100	100	100	100	100	100	100	100	100
•	Reset	0	0	0	0	0	0	O	0	0
•	Rate	0.7	0.7	0.7	0.7	0.7	0.7	0.7	0,7	0.7
•	Recorder	35.4	25.4	25,4+	25,4	25.4	25.4	25.4	25.4	25.4
•	Std. T.C.	25.787 25.760				25,776				
•	R.T.	73.0	71.4	72.6	73.0	71.4	73, 2	72.4	74.0	73.8
•	Water, Bell	0	0	0	0	0	0	0	0	0
•	Water, Cent.	2.5	2.5	2.5	2.5	2.5	2.4	2.4	2.4	2.5
•	Water, Right	2./	2 /	2.0	2./	2.1	2.0	2.0	2.0	2.0
35ma 21/2	Opt. Temp.	16125				30				
A	Filters									
•	Std. Cur.									
•	Std. Filters									
-	Length	2.0/660	2.01660	2.01670	2.01670	2.01675	2.0/680	2.0/685	2.01705	2.01710
•	Exten.		.00385					.00410	.00430	
-	Elapsed Time	568.4			688.3		736.4		832.3	859.4
-		.192%	1929		.1987		. 202%			.213%

Unit # 3 Temperature 2600°F

Test # S-28 Stress 500 PSL

Material T-111 Initial Length (no load) 2.01275
T-111-0-1670
1Hr, 8000 F Initial Length under Load 2.01275

FIGURE 13 TYPICAL LOG OF RECORDED DATA

# IV MATERIALS

## A. Materials and Processing

The materials tested during this program consisted of the following alloys:

	Columbium-Base	Molybdenum-Base	Tantalum-Base	Tungsten-Base
Ch Cr	AS-30 (1)* Cb-132M (1)	TZC (3)   TZM (3)   Cb-Modified TZM(1)		Arc-Melted W (1) Vapor-Deposited W (1) W-25% Re (1) Sylvania A (1)

Whenever possible detailed processing information was obtained for each material and these data are summarized in Appendix I. To facilitate locating the data for a particular material, an index is provided on the Appendix I title page. Tension test data for some of the materials tested are presented subsequently in subdivision E of this section.

TZC, a molybdenum -base alloy for turbine application, was fabricated by several methods. The first heat (M-80) was found to have low room temperature ductility presumably due to the method of processing which involved finishing a 2 inch x 4 inch sheet-bar by rolling at 2935°F (1585°C) using small reductions (approximately 4%) on each pass. Subsequently, Heat M-91 was prepared with the same chemistry, but a lower finishing temperature of 2372°F (1300°C) and larger reductions to provide room temperature ductility. A third lot of TZC plate (Heat 4345) was prepared by a second vendor. In this case a round extrusion was first upset then broad forged at 2400°F (1316°C) to the desired thickness. This method of processing also produced room temperature ductility in a conventional tension test.

<sup>\* ( )</sup> number of heats examined.

The TZM molybdenum-base alloy was obtained from two different sources. One lot of material designated Heat 7502 was purchased in the form of a disc forging approximately 11 inches diameter and 3/4 inch thick. A second lot of material (Heat KDTZM-1175) consisted of a section from a disc forging obtained from an AiResearch Corp. program. This sample was processed for improved creep resistance (3) through the development of a fine carbide dispersion. In order to produce this effect, it was necessary to work with a carbon level above 0.02%. Columbium-modified TZM was included as a relatively new alloy offering potential as a turbine material. Since disc forgings of this alloy were not available, it was tested in the form of a 5/8 inch diameter wrought bar. Commercial TZM bar 5/8 inch diameter (Heat 7463) was included in the studies to determine the influence of material form on the creep properties.

Tantalum-base alloys T-111 and T-222 were evaluated in sheet form. The T-111 which represents one of the most promising materials for tubing application was extensively tested using 5 different heats.

The tungsten and tungsten-base alloys were tested in sheet form. Pure tungsten and tungsten-25% rhenium were prepared by arc-melting while Sylvania A, a tungsten-hafnium-carbon alloy, was processed by powder methods. It was found during testing that cracking of the Sylvania A specimens frequently occurred outside of the gage section after 40-100 hours of creep, but no metallurgical causes could be found to account for this brittle behavior. The vapor-deposited tungsten was prepared by General Atomics Corporation (4) and machined into bar specimens from a longitudinal strip cut from a vapor-deposited tube. \*

#### B. Chemistry of Materials

The detailed chemical analyses of the materials used in this program are given in Appendix II and a condensed summary is presented in Table 2.

Evaluating the chemical data requires recognition of the inherent variability in quantitative analysis of refractory materials. "Round Robin" analyses conducted by the Materials Advisory Board (5) serves as an illustration. Samples from the same lot of molybdenum-base TZM were analyzed by various cooperating laboratories and the following results were obtained:

<sup>\*</sup> These were a 1/8" diameter specimen of special design for adaptation to available grips.

TABLE 2

Chemical Composition of Alloys Being Evaluated in Creep Program (Weight %) (1)

			(2)	(2)	(2)		(3)	
Ŧ	15	2 10	<b>V-64</b>	φ rν ω 4	~	= 7		~
mad 0	9 7	41 37 19	20 34 39	55 72 20 130	100	38		Q
2	100 24	18 34 9	30 31	20 20 34 50	20	26 30		91
Zr	1.04	.17	.10 .08 .12					
i-		1.02	. 64 . 64 . 64 . 64					
ပ	. 09 91.	.127	.010 .016 .035	.0044 .001 .0034 .003	· 004	.012	.250	.0053
Ħ				2.30 2.17 2.28 2.30	1.95	2.93	0.7	
e	19.7			Bal. Bal. Bal.	Bal.	Bal.	Bal.	
Ş.	4.72	Bal. Bal.	Bal. Bal. Bal.					
ප	Ba] Bal		1.00					
%   							1.0	
3	21.0			8.50 7.9 7.9 8.70	8.60	9.57	8.0	Bal.
Material	AS-30 (Heat C5) Cb-132M(Heat KC1454)	TZC (Heat M-80) (Heat M-91) (Heat 4345)	TZM (Heat 7502) (Heat 7463) (Heat KDTZM-1175) Cb Modified - (Heat 7503)	T-111 (Heat 70616) (Heat D-1670) (Heat D-1102) (Heat 65079) (Heat MCN	02A065)	T-222 (Heat Al-Ta-43) 9.57 (Heat Ta-43-SF2)8.77	Astar 811C	Tungsten (Arc-Melted) Bal. (Heat KCl357)

TABLE 2 (Continued)

H2	1-3 (2)	13	3
N2 02	15 12-14 1-3 (2)	61	20
N <sub>2</sub>	15	2	17
Zr			
Ti			
O	.0012	.0070	. 0300
Hŧ			. 52
Ta			
Mo			
Cb			
Re		24 88	
*	Bal.	Bal.	Bal.
Material	Tungsten (Vapor Deposited)	Tungsten -25% Rhenium (Arc-Melted) (Heat 35-75002)	Sylvania A

<sup>(1) -</sup> TRW Analysis(2) - Vendor Analysis(3) - Nominal Composition

- 1. Cooperating laboratories, using their own particular methods for analysis could duplicate their own results. However, comparison of results between laboratories showed considerable variation.
- 2. When all cooperating laboratories used the same method, the variation between laboratories was reduced.

A typical example of the scatter experienced in the MAB Program in analyzing molybdenum-base TZM is shown with 95% confidence limits:

Carbon - 0.029 ± 0.017% Zirconium - 0.105 ± 0.075% Nitrogen - 20 ± 8 ppm

It follows that considerable judgement must be exercised in comparing chemical analyses of refractory alloys.

Post-test analyses of selected specimens were undertaken to determine the effect of both heat treatment and vacuum environment on the chemistry and these results are included in Appendix II. To facilitate evaluation of the results, the pertinent data have been summarized in Table 3. The distribution of the changes in the carbon content suggest variation of analytical results rather than a true change of composition. This is substantiated by the observation that the first five carbon values, representing the greatest change, are associated with a carbon content of approximately 0.1%. The remaining values, which show much less change, are associated with a carbon content of approximately 0.01%. The distribution of the changes in both the hydrogen and oxygen contents indicate a decrease due to heating in the vacuum environment. Nitrogen, like carbon, reflects analysis variability.

The results of these tests indicate that heating refractory metals in a vacuum environment of  $< 1 \times 10^{-8}$  torr for 16,000 hours does not cause interstitial contamination.

TABLE 3

Chemical Composition Changes Due to Testing

Material	Heat No.	Unit No.	Test No.	Time Hours	Test T	Temp.	Change	e in Com H2	Change in Composition, ppm C H <sub>2</sub> O2 H <sub>2</sub>	ppm H2
AS- 30	C5	=	B-6	1, 193	2000	1093	- 200	9-	-20	-83
Cb-132M KC1454	KC1454	10	B-13	568	2056	1125	- 100	-2	1	4
TZC	M-80	10	B-5, A, B	1,985	2000	1093	+ 700	ı R	- 18	9 +
TZC	M-80	7	B-9	16,002	2000	1093	- 300	61	-18	∞ 1
TZC	M-80	13	B-12	14, 239	2056	1125	+300	8-	- 14	-11
TZM	7502	9	B-3	10,048	2000	1093	+ 20	0	+11	+30
T-111	70616	7	S-16	1,675	2600	1426	9 +	+4	-45	+20
T-111	70616	7	S-19	4,870	2200	1204	- 24	- 3	-27	- 14
W	KC1357	2	S-5	32	3200	1760	- 25	+2	+	9
M	KC1357	rv	S-9	3,886	3200	1760	- 18	0	+28	- 10
W-25%Re 3.5-7	e 3.5-75002	3	S-4	26	3200	1760	- 10	8	-51	+ 3
W-25%Re 3.5-7	e 3.5-75002	4	S-8	1, 306	3200	1760	+ 10	-2	-22	-12

# C. Metallography of Materials

The materials used in the refractory alloy creep program were metallographically examined in the as-received condition and after applying the heat treatment used prior to creep testing. These treatments are summarized in Table 4.

#### 1. AS-30, Heat C5

The microstructure of the as-received AS-30 alloy, shown in Figure 14 is representative of the condition after rolling at 2100°F (1149°C) without further heat treatment. Since uniform cross-rolling was used in processing, the structures of edges parallel and perpendicular to rolling were identical.

#### 2. Cb-132M, Heat KC1454

Figure 15 shows the as-received Cb-132M alloy. The microstructure is representative of the condition after rolling at 2400°F (1315°C) without further heat treatment. Figure 16 shows the microstructure after annealing at 3092°F (1700°C) for one hour. Only partial recrystallization occurred at this heat treatment.

#### 3. TZC, Heat M-80

Figure 17 illustrates the structure of the TZC, Heat M-80, material in the as-received condition. Annealing at 3092°F (1700°C) for one hour resulted in only partial recrystallization, Figure 18.

#### 4. TZC, Heat M-91

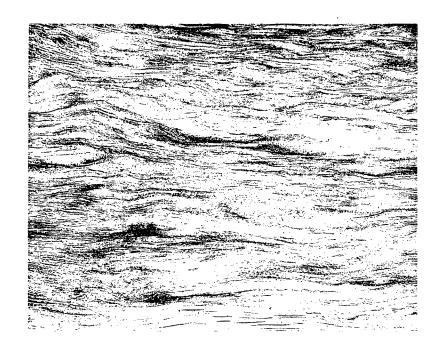
The as-received microstructure of the TZC, Heat M-91, material finish rolled at 2372°F (1300°C) is shown in Figure 19.

The two cross sections of the plate exhibited the same structure due to the uniform cross-rolling that was employed. Annealing at 3092°F (1700°C) for one hour, Figure 20, caused complete recrystallization. Subsequent aging for 5 hours at 2400°F (1315°C) produced no apparent change in the microstructure as observed at 100X. However, a comparison of the aged and unaged structures at 6000X shows that aging produced a slight increase in the size of the precipitate, Figure 21. A pretest stress relief treatment of 2400 or 2500°F (1315 or 1371°C) did not significantly change the appearance of the as-received material.

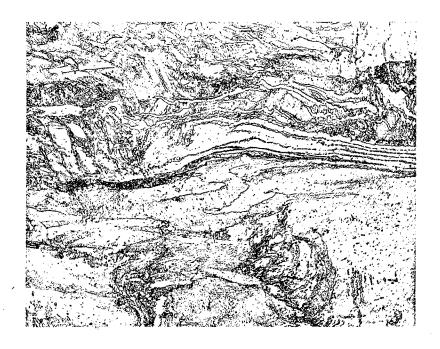
TABLE 4

Heat Treatments Applied Prior to Creep Testing

		Tempe °F	erature °C	Time Hours
<u>Material</u>	Heat No.	<u> </u>		110 41 -
AC 20	<b>C</b> 5	None	-	-
AS-30	KC1454	3092	1700	1
Cb-132M	K01454			
TZC	M-80	None	-	-
120	M-80	3092	1700	1
	M-91	3092	1700	1
	M-91	<b>5</b> + 3092	1700	1
	, -	<b>1</b> 2400	1315	5
	M-91	2500	1371	1
	M-91	2400	1315	1
	4345	2500	1371	1
TZM	7502	None	-	-
1 27101	7502	2850	1566	1
	KDTZM-1175	None	-	-
	7463	None		-
	Cb-Modified	None	-	-
	4305-4	None	=	-
		-/	1.427	1
T-111	70616	2600	1427	1
	70616	3000	1649	1
	65079	3000	1649	1
	D-1670	3000	1649	1
	D-1102	3000	1649	1
	MCN02A065	3000	1649	1
T-222	A1-TA-43	2800	1538	1
1-222	A1-TA-43	3000	1649	1
Astar 811C		3600	1982	1/2
Astar offic				
Tungsten	KC1357	3200	1760	1
Tungsten	KC1357	2800	1538	1
	Vapor Deposited	3200	1760	1
	Vapor Deposited	2800	1538	1
W-25%Re	3. 5-75002	3200	1760	1
W-2576Re Sylvania A	3.3 ,3002	3200	1760	1

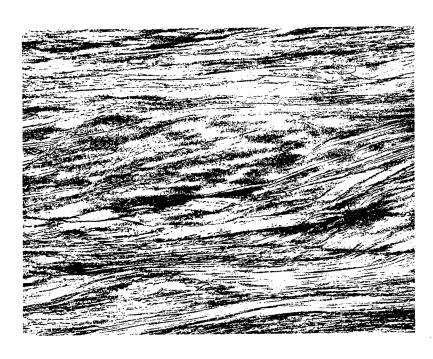


EDGE OF PLATE

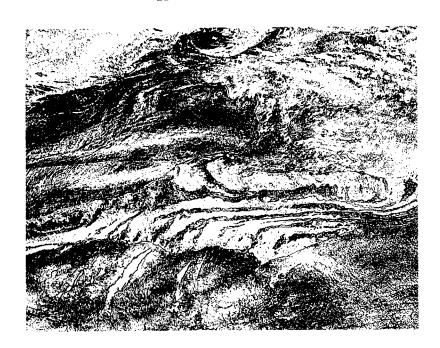


SURFACE OF PLATE

FIGURE 14 MICROSTRUCTURE OF AS-30 PLATE (HEAT C-5) IN AS-RECEIVED CONDITION. ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O. 100 X

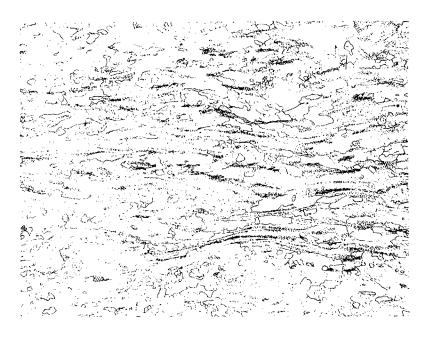


EDGE OF PLATE



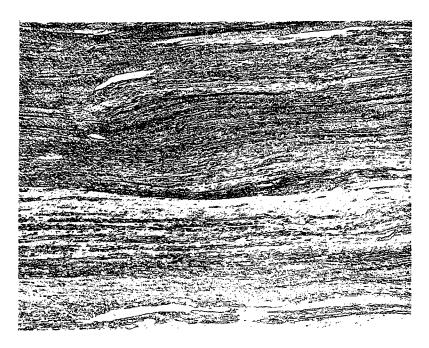
SURFACE OF PLATE

FIGURE 15 MICROSTRUCTURE OF Cb-132M PLATE (HEAT KC 1454)
IN AS-RECEIVED CONDITION.
ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O. 100 X

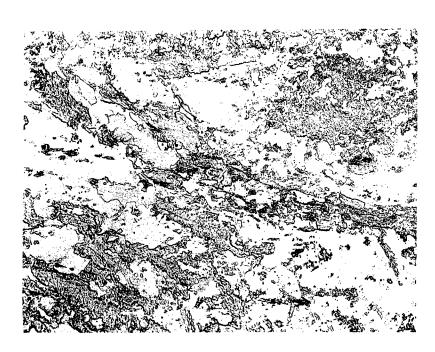


EDGE OF PLATE

FIGURE 16 MICROSTRUCTURE OF Cb-132M PLATE (HEAT KC 1454)
AFTER ANNEALING AT 3092°F (1700°C), 1 HOUR
ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O.
100 X



EDGE OF PLATE



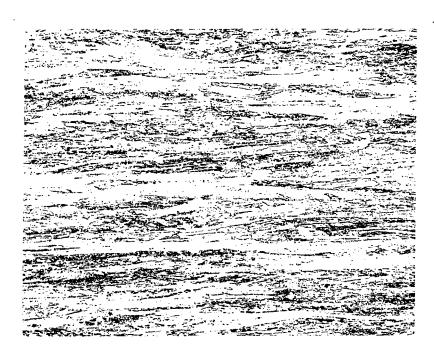
SURFACE OF PLATE

FIGURE 17 MICROSTRUCTURE OF TZC PLATE (HEAT M-80) IN AS-RECEIVED CONDITION. ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O. 100 X

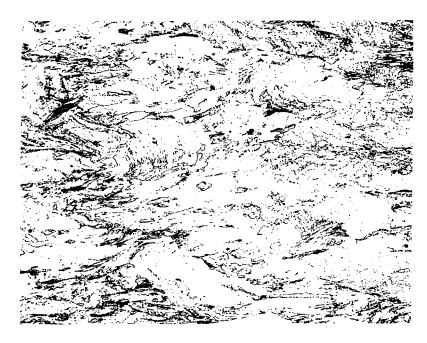


EDGE OF PLATE

FIGURE 18 MICROSTRUCTURE OF TZC PLATE (HEAT M-80) AFTER ANNEALING 3092 F (1700 C), ONE HOUR. ETCHANT: 15% HF, 15%  $\rm H_2SO_4$ , 8%  $\rm HNO_3$ , 62%  $\rm H_2O$ . 100 X

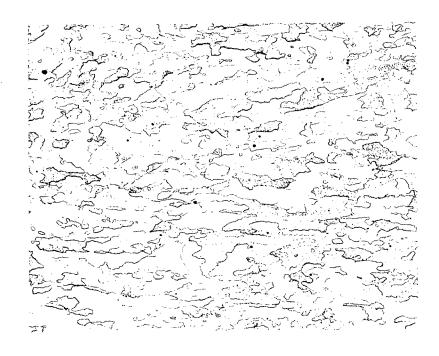


EDGE OF PLATE



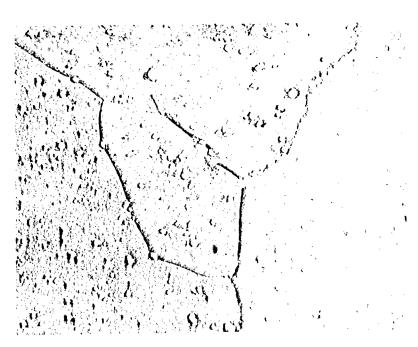
SURFACE OF PLATE

FIGURE 19 MICROSTRUCTURE OF TZC PLATE (HEAT M-91) IN AS-RECEIVED CONDITION. ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O. 100 X



EDGE OF PLATE

FIGURE 20 MICROSTRUCTURE OF TZC PLATE (HEAT M-91) AFTER ANNEALING 3092°F (1700°C), ONE HOUR. ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O. 100 X



ANNEALED UNAGED



AGED 2400°F (1315°C) 5 HOURS

FIGURE 21 CROSS SECTION MICROSTRUCTURE TZC PLATE (HEAT M-91)
ANNEALED 3092°F (1700°C), ONE HOUR.
ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O.
6000X

#### 5. TZC Heat 4345

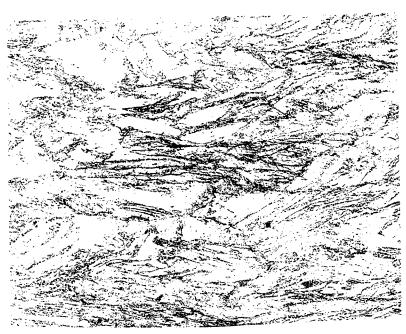
Figures 22 and 23 show the microstructure of the TZC, Heat 4345, material in the as-received condition. Both edges as well as the face of the plate are shown because of the variation of the microstructure. Stress relieving at 2500°F (1371°C) prior to testing, produced no change in the microstructure.

#### 6. TZM Heat 7502

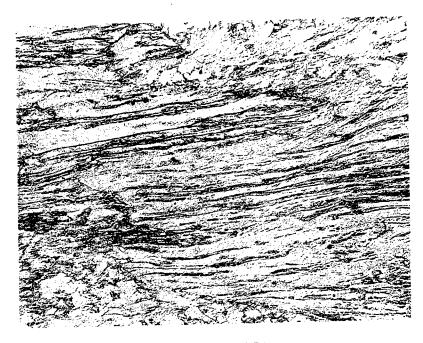
TZM Heat 7502 was supplied in the form of a pancake forged disc approximately 11 inches in diameter and 3/4 inch thick. By virtue of the processing, the macrostructure was not uniform throughout the cross section as shown by Figure 24. The 100X microstructures as a function of position in the disc are shown in Figure 25. Even greater differences could be observed if the areas examined were located near the top or bottom surfaces of the disc. Figure 26 shows the variation of microstructure between surfaces parallel and perpendicular to the radius while Figure 27 illustrates the microstructure of the disc face. This material was tested in both the stress relieved 2200°F (1204°C) and recrystallized 2850°F (1566°C) conditions. Figure 28 indicates that the flow lines still persist despite the one hour treatment at 2850°F (1566°C). Figure 29 illustrates the microstructure at two points along the radius and the attending grain size difference. These results indicate that the microstructure of this particular heat of TZM cannot be simply defined because of the method of producing the stock. Since the orientation of the creep specimen places the gage section at midradius of the disc, a microstructural variation along the two inch gage length existed.

#### 7. TZM Heat KDTZM-1175

The TZM material representing Heat KDTZM-1175 was a section of a pancake forged disc stress relieved at 2300°F (1260°C). Creep tests were performed without further heat treatments. Figure 30 shows the microstructure in three directions. Because of the limited amount of material received, a detailed examination of the microstructure throughout the disc was not made, however, due to the nature of the processing, the upset forging would probably exhibit the same type variations observed with Heat 7502. A detailed description of the processing of this material can be found in Reference 3 covering a molybdenum forging program conducted in supplort of the SPUR-SNAP 50 program.



EDGE OF PLATE PERPENDICULAR TO EXTRUSION DIRECTION



FACE OF PLATE

FIGURE 22 MICROSTRUCTURE TZC PLATE (HEAT 4345) IN AS-RECEIVED CONDITION. ETCHANT: MURAKAMI'S. 100 X



EDGE OF PLATE PARALLEL TO EXTRUSION DIRECTION

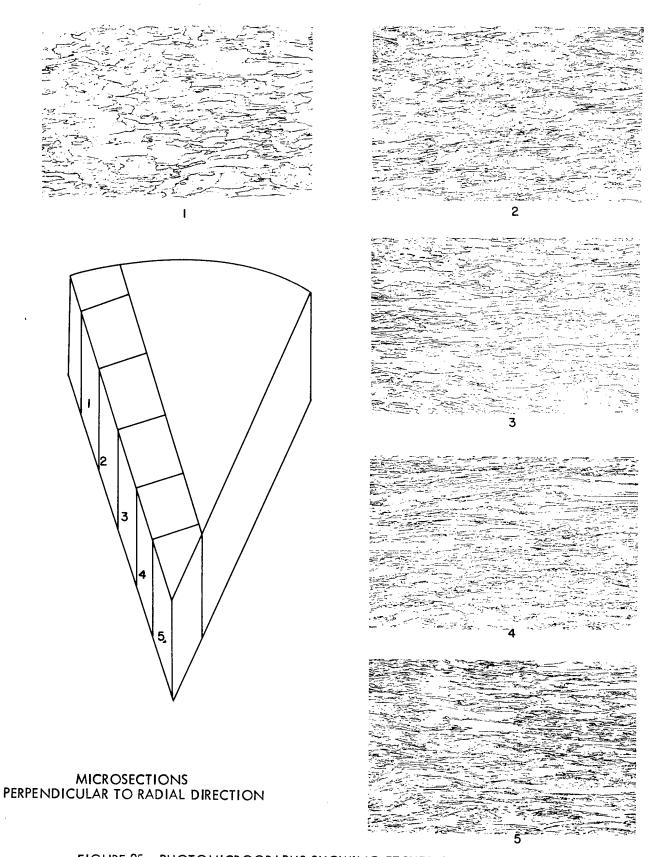
FIGURE 23 MICROSTRUCTURE TZC PLATE (HEAT 4345) IN AS-RECEIVED CONDITION ETCHANT: MURAKAMI'S. 100 X

# CENTER OF FORGING

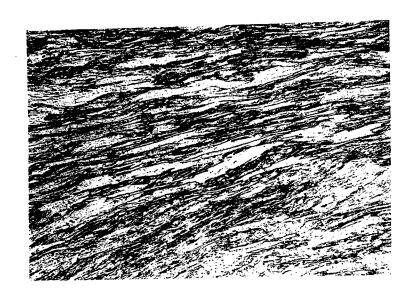


EDGE OF FORGING

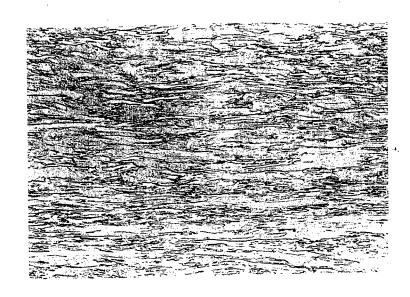
FIGURE 24 PHOTOGRAPH OF MACROETCHED SECTION OF AS-RECEIVED TZM PANCAKE-FORGED DISC (HEAT 7502), SHOWING FLOW LINES DUE TO FORGING. ETCHANT: MURAKAMI'S. 1-1/2X



PHOTOMICROGRAPHS SHOWING ETCHED SECTIONS OF TZM PANCAKE-FORGED DISC (HEAT 7502) IN AS-RECEIVED CONDITION. ETCHANT: MURAKAMI'S. 100 X



EDGE COINCIDENT WITH RADIAL DIRECTION



EDGE PERPENDICULAR TO RADIAL DIRECTION

FIGURE 26 MICROSTRUCTURE OF AS-RECEIVED TZM PANCAKE FORGED DISC (HEAT 7502) AS A FUNCTION OF THE ORIENTATION OF THE FORGING. ETCHANT: MURAKAMI'S. 100X

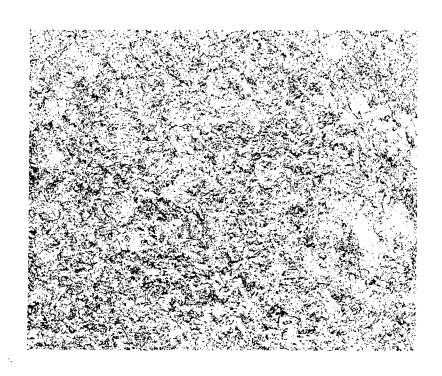


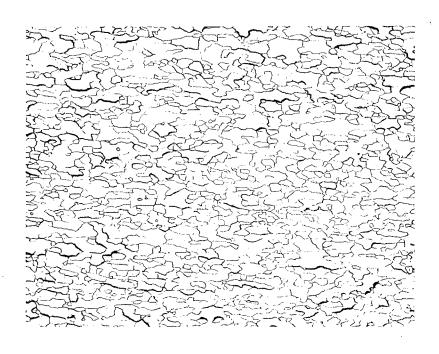
FIGURE 27 MICROSTRUCTURE OF FACE OF TZM PANCAKE-FORGED DISC (HEAT 7502) IN AS-RECEIVED CONDITION. ETCHANT: MURAKAMI'S. 100 X

### CENTER OF FORGING

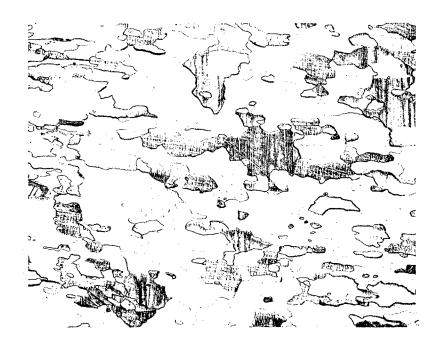


EDGE OF FORGING

FIGURE 28 PHOTOGRAPH OF MACROETCHED SECTION OF TZM PANCAKE-FORGED DISC (HEAT 7502) AFTER RECRYSTALLIZATION AT 2850°F (1566°C), ONE HOUR. ETCHANT: MURAKAMI'S. 1-1/2 X



EDGE OF CROSS SECTION

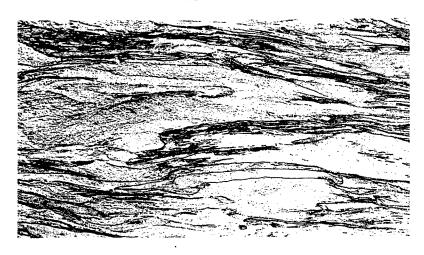


CENTER OF CROSS SECTION

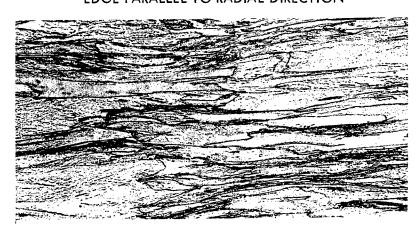
FIGURE 29 PHOTOMICROGRAPHS OF TZM PANCAKE-FORGED DISC (HEAT 7502)
AFTER RECRYSTALLIZING ONE HOUR AT 2850°F (1588°C).
ETCHANT: MURAKAMI'S. 100 X



**SURFACE** 



EDGE PARALLEL TO RADIAL DIRECTION



EDGE PERPENDICULAR TO RADIAL DIRECTION

MICROSTRUCTURES OF AS-RECEIVED TZM PANCAKE-FORGED DISC (HEAT KDT ZM 1175) AS A FUNCTION OF ORIENTATION IN THE FORGING. ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O. 100X

#### 8. TZM Heat 7463 (Commerical Bar)

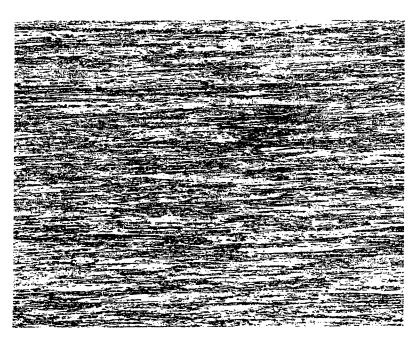
Figure 31 presents the longitudinal and transverse microstructures of commercial TZM Heat 7463. Because the processing method combines extrusion and swaging to the final diameter of 5/8 inch, the microstructure of the cross section is very uniform. At 500X, Figure 32, the improved resolution shows more clearly the nature of the heavily worked microstructure.

#### 9. Columbium-Modified TZM Heat 4305-4

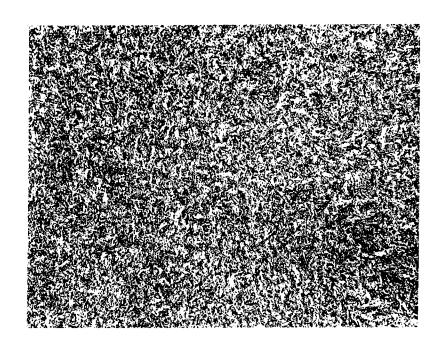
The longitudinal and transverse microstructures of the columbium-modified TZM 5/8 inch diameter bar are shown in Figure 33. The structure was similar to that of the commercial TZM bar although the degree of residual cold work was not as severe. To determine the effect of columbium addition on the recrystallization behavior, specimens were annealed for one hour at various temperatures and the results are presented in Figure 34. The left photomicrograph shows the as-received material, i.e., stress relieved one hour at 2500°F (1371°C). Annealing one hour at 2800°F (1538°C), Figure 34 center, caused recrystallization of a few isolated areas. A slightly greater number of recrystallized areas was apparent after one hour at 3000°F (1649°C), Figure 34 right. The results indicate that the columbium addition tended to raise the recrystallization temperature of the TZM alloy.

#### 10. T-111 Heat 70616

Figure 35 shows the as-received microstructure of T-111 Heat 70616. Although recrystallized at 2400°F (1316°C) prior to shipping, a residual worked structure was still evident in the form of well-defined stringers, Therecrystallized material was studied with the electron microscope and electron microprobe. Examination at 6000X, Figure 37, suggested that the stringers were caused by preferential etching of the specimen to produce parallel troughs which appeared as dark lines at 100X. Figure 37 also shows that grain boundaries cross these areas. From these observations and the electron microprobe analysis which failed to show a chemical difference associated with the trough, it was concluded that the areas do not represent an accumulation of precipitates or inclusions.

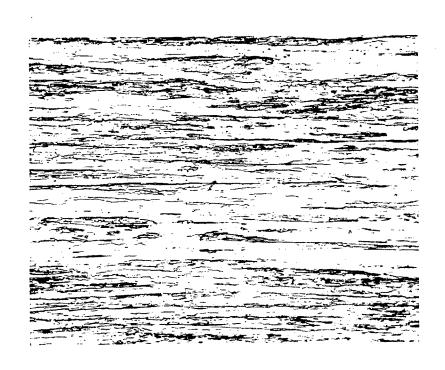


LONGITUDINAL SECTION

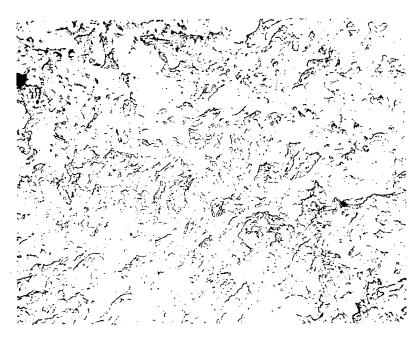


TRANSVERSE SECTION

FIGURE 31 MICROSTRUCTURE OF AS-RECEIVED COMMERCIAL TZM SWAGED BAR (HEAT 7463). ETCHANT: MURAKAMI'S. 100X



LONGITUDINAL SECTION



TRANSVERSE SECTION

FIGURE 32 MICROSTRUCTURE OF AS-RECEIVED COMMERCIAL TZM SWAGED BAR (HEAT 7463). ETCHANT: MURAKAMI'S. 590X

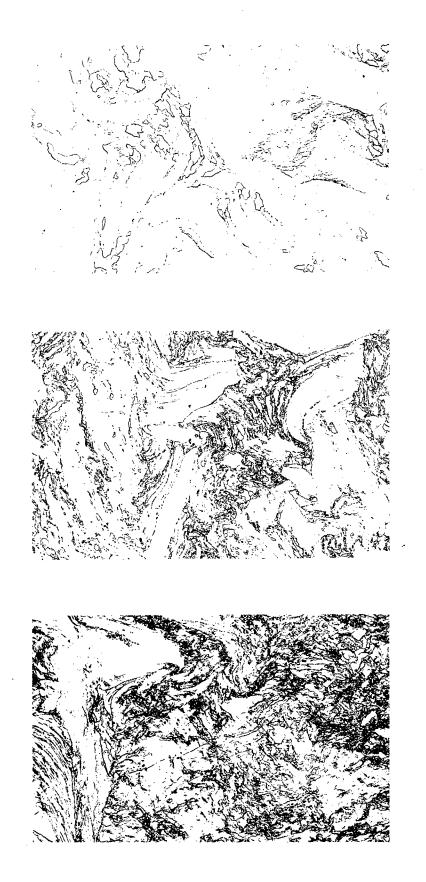


LONGITUDINAL SECTION



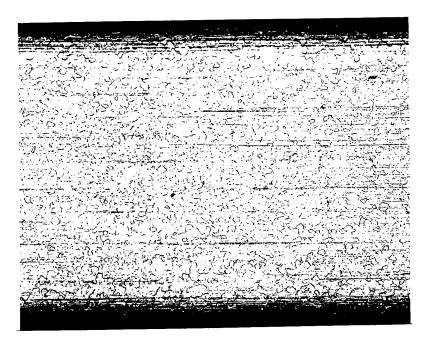
TRANSVERSE SECTION

FIGURE 33 MICROSTRUCTURE OF AS-RECEIVED COLUMBIUM-MODIFIED BAR (HEAT 4305-4). ETCHANT: MURAKAMI'S. 100X

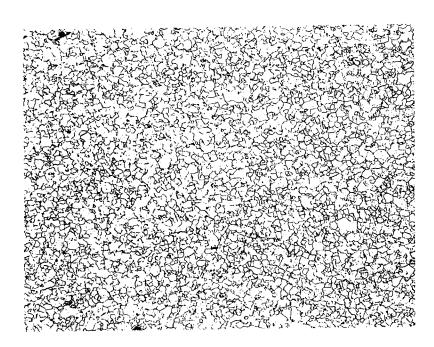


ANNEALED 1 HOUR AT 2800°F (1538°C) ANNEALED 1 HOUR AT 3000°F (1649°C) ANNEALED 1 HOUR AT 2500°F (1371°C)

COLUMBIUM-MODIFIED TZM ANNEALED AT VARIOUS TEMPERATURES. SURFACE PERPENDICULAR TO AXIS OF BAR. ETCHANT: MURAKAMI'S. 100X FIGURE 34

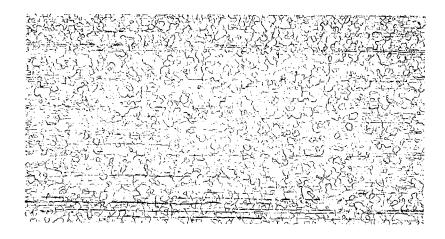


EDGE OF SHEET

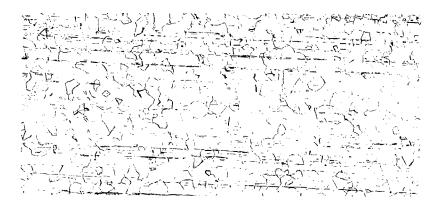


SURFACE OF SHEET

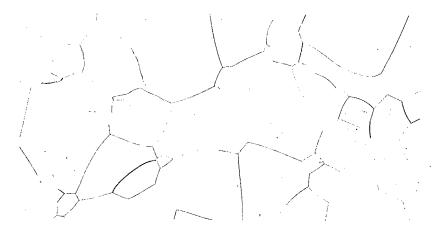
FIGURE 35 MICROSTRUCTURE OF T-111 SHEET (HEAT 70616)
RECRYSTALLIZED 2400°F (1316°C), ONE HOUR.
ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O.
100 X



2600°F (1427°C)



3000°F (1649°C)



3500°F (1877°C)

FIGURE 36 MICROSTRUCTURE OF T-111 SHEET (HEAT 70616)

RECRYSTALLIZED AT VARIOUS TEMPERATURES - ONE HOUR
EDGE OF SHEET. ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>,
62% H<sub>2</sub>O. 100 X

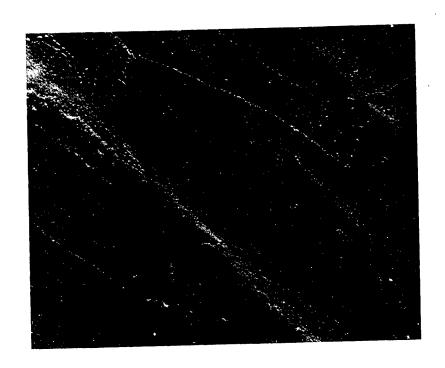


FIGURE 37

ELECTRONMICROGRAPH OF T-111 SHEET (HEAT 70616) ANNEALED AT 2600°F (1427°C) FOR ONE HOUR. CROSS-SECTION SHOWING DETAILS OF STRIATIONS. ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O. 6000X

## 11. <u>T-111 Heats 65079</u>, D-1670, D-1102, MCN02A065

The microstructures of these heats are identical to Heat 70616 with the only difference being the grain size as noted below:

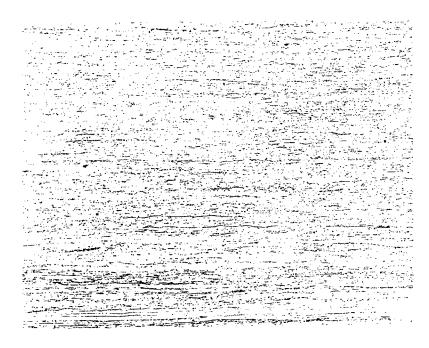
			l Hour An	nealing Trea	tment
	2400°F	2600°F	3000°F	3500°F	
Heat No.	(1316°C)	( <u>1426°C</u> )	( <u>1649°C</u> )	(1877°C)	
70/1/	7 0	_			
70616	7 - 8	7	5-6	1 - 3	
65079		6-8	5-7		
D-1670			*		
D-1102			5-7		
MCN02A065			6-8		

## 12. <u>T-222 Heat AL-TA-43 and Heat Ta-43-SF-2</u>

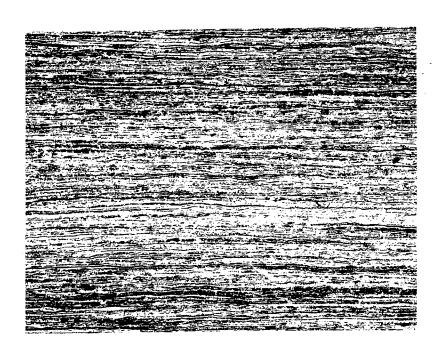
Representative microstructures of the T-222 sheet are shown in Figure 38 for both as-rolled and recrystallized conditions. An increase in grain size was observed with increased recrystallization temperature as shown by Figure 39 and the tabulation below:

<u>Heat</u>	Temp	erature	ASTM
	<u>°F</u>	<u>°C</u>	Grain Size
AL-TA-43	2600	1426	6-8
	2800	1538	6-8
	3000	1649	5-6
Ta-43-SF-2	2300	1260	8
	3000	1649	5-6

<sup>\*</sup> Creep tests still in progress. A limited amount of material was available so that metallographic examination must be performed after testing.

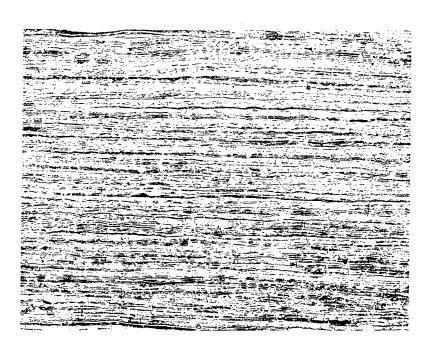


AS-ROLLED

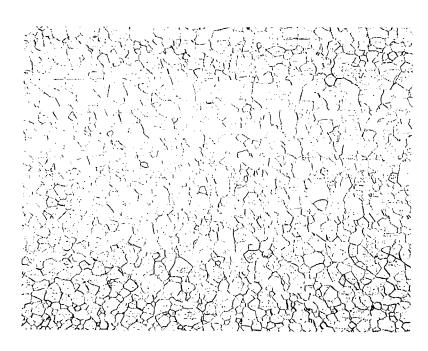


2600°F (1426°C) ONE HOUR

FIGURE 38 T-222 SHEET (HEAT AL-TA-43). ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O. 100 X



2800°F (1538°C) ONE HOUR



3000°F (1649°C) ONE HOUR

FIGURE 39 T-222 SHEET (HEAT AL-TA-43) HEAT TREATED AT TWO TEMPERATURES. ET CHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O. 100X

#### 13. Astar 811C

Only a limited quantity of this material was received and all was used to fabricate creep specimens. Pre-test metallographic analysis was therefore not performed.

# 14. Arc-Melted Tungsten Heat KC1357

Figure 40 shows the microstructure of the as-received tungsten sheet. Annealing for one hour at 2800°F (1538°C) or 3200°F (1760°C) caused recrystallization to equiaxed grains, Figures 41 and 42. At the lower temperature well defined grain boundaries were absent suggesting that the recrystallization process was not complete.

# 15. Vapor Deposited Tungsten

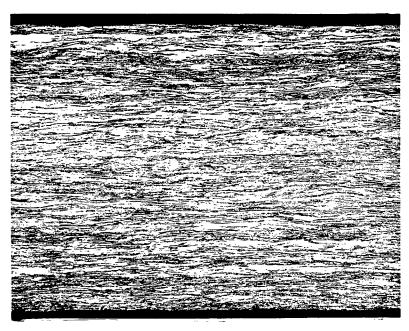
Vapor deposited tungsten was received in the form of a creep specimen. For this reason it was impossible to perform metallographic examination prior to testing.

# 16. Arc-Melted Tungsten-25% Rhenium, Heat 3.5-75002

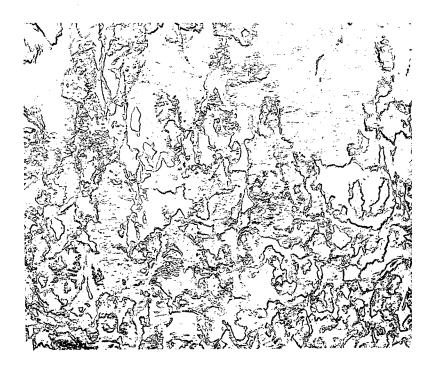
Figure 43 shows the microstructure of the as-received alloy. Annealing one hour at 3200°F (1760°C) produced recrystallization, Figure 44. A comparison of Figures 44 and 42 indicates that the tungsten-25% rhenium alloy possessed reduced grain growth tendencies relative to pure tungsten.

#### 17. Sylvania A

Figure 45 shows the structure of the alloy Sylvania A in the asreceived condition and after recrystallization at 3200°F (1760°C) for one hour. The section selected from the original stock was taken through a delaminated area. While Sylvania A alloy is fully recrystallized at 3200°F (1760°C), it exhibits a finer grain size as compared to both tungsten and tungsten-25% rhenium.



EDGE PERPENDICULAR TO ROLLING DIRECTION

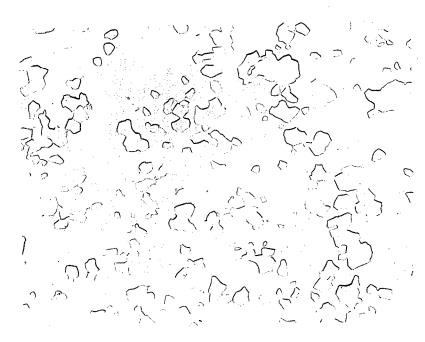


SURFACE OF SHEET

FIGURE 40 MICROSTRUCTURE OF TUNGSTEN SHEET (HEAT KC 1357) IN AS-RECEIVED CONDITION.
ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O. 100 X

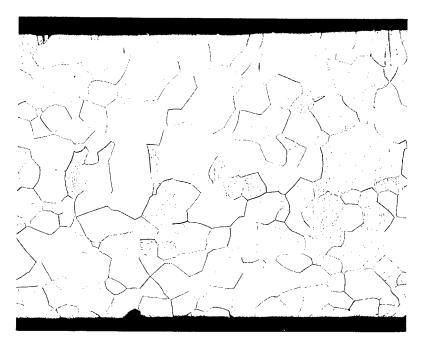


EDGE PARALLEL TO ROLLING DIRECTION

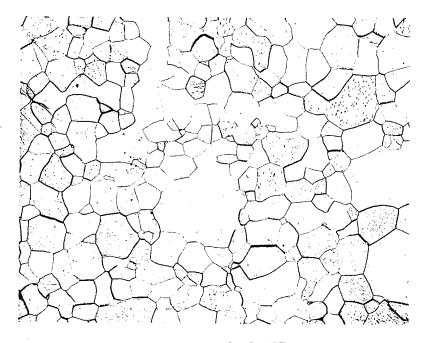


SURFACE OF SHEET

FIGURE 41 MICROSTRUCTURE OF TUNGSTEN SHEET (HEAT KC 1357)
ANNEALED ONE HOUR 2800°F (1538°C).
ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O.
100 X

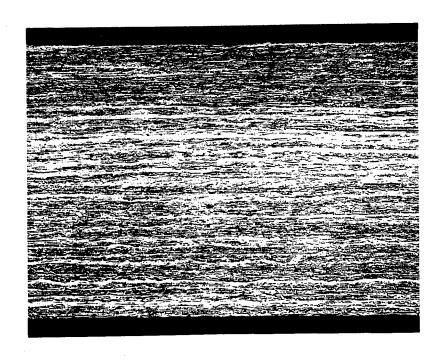


EDGE PERPENDICULAR TO ROLLING DIRECTION

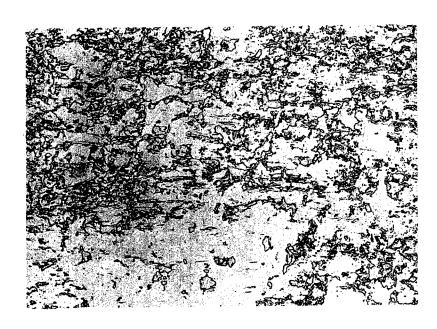


SURFACE OF SHEET

FIGURE 42 MICROSTRUCTURE OF TUNGSTEN SHEET (HEAT KC 1357)
ANNEALED ONE HOUR 3200°F (1760°C).
ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O.
100 X

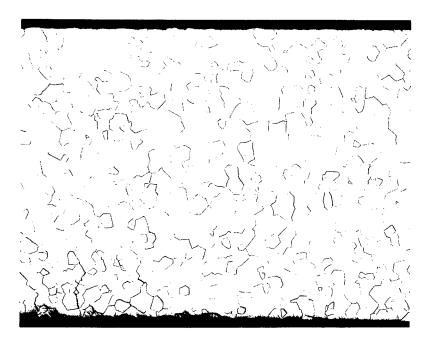


EDGE PERPENDICULAR TO ROLLING DIRECTION

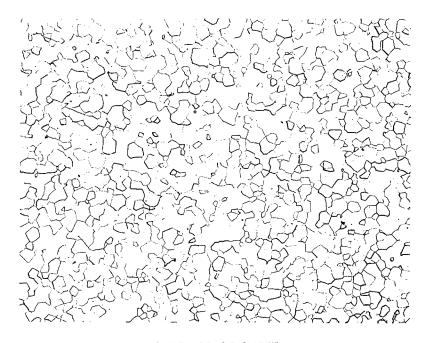


SURFACE OF SHEET

FIGURE 43 MICROSTRUCTURE OF TUNGSTEN - 25% RHENIUM ALLOY SHEET (HEAT 3.5-75002) IN AS-RECEIVED CONDITION. ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O. 100 X

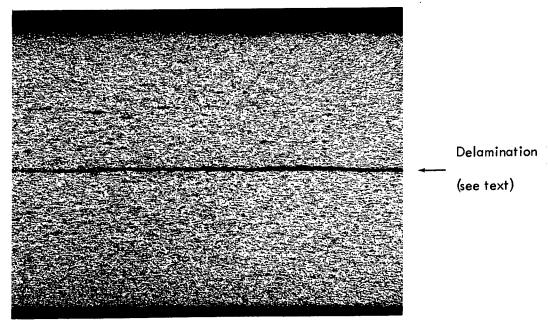


EDGE PERPENDICULAR TO ROLLING DIRECTION

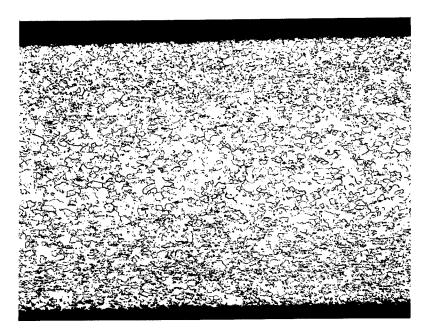


SURFACE OF SHEET

FIGURE 44 MICROSTRUCTURE OF TUNGSTEN - 25% RHENIUM ALLOY SHEET (HEAT 3.5-75002) ANNEALED ONE HOUR 3200°F (1760°C). ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O. 100 X



EDGE PERPENDICULAR TO ROLLING DIRECTION AS-RECEIVED



EDGE PERPENDICULAR TO ROLLING DIRECTION RECRYSTALLIZED ONE HOUR 3200°F (1760°C)

FIGURE 45 MICROSTRUCTURE OF SYLVANIA-A IN AS-RECEIVED AND RECRYSTALLIZED CONDITIONS. ETCHANT: 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub> 62% H<sub>2</sub>O. 100X

# D. Hardness of Materials

The hardness of all materials was taken as a routine part of metallographic examination. The procedure employed was to obtain the data with metallographic specimens using a Kentron hardness tester. A compilation of the results pieven in Table 5, will be used for reference in subsequent discussions. In the case of the TZC alloys, additional comprehensive hardness testing was performed. The results with TZC Heat M-80 showed the following:

- 1. The hardness of the as-rolled plate varied widely from one location to another, the range being 284 to 338 DPH.
- 2. Annealing at 3092°F (1700°C) for one hour caused partial recrystallization. The recrystallized grains had a uniform hardness of 251 to 254 DPH.
- 3. The mean hardness of the unrecrystallized areas, 292 DPH, was statistically lower than the mean hardness of the as-rolled plate, 308 DPH.

TRW Heat M-91 also showed a wide range of hardness in the as-rolled condition, 288 to 390 DPH. Annealing at 3092°F (1700°C) for one hour caused full recrystallization and a substantial decrease in hardness (355 to 240 DPH). When the as-rolled plate was stress relieved at 2500°F (1317°C) for one hour, a small decrease in hardness occurred (335 to 303 DPH).

Because of the range of hardness data, it may be concluded that any change in hardness of TZC due to creep testing may be difficult to significantly identify with creep effects. This is particularly true in the case of stress-relieved material.

T-111 Heats 70616 and 65079 when annealed at 3000°F (1649°C) for one hour had a greater hardness than after a similar treatment at 2600-2800°F (1427-1538°C). Ammon, Filippi, and Harrod (6) have shown that for the similar alloy T-222 these temperatures lie within the solution-precipitation range. Such effects may explain the observed behavior for T-111.

TABLE 5
Hardness of Materials

Material	Heat No.	Heat T	reatment	Time Hours	DPH (100-gm load)
AS-30 Cb-132M	C5 KC1454 KC1454	As Rol As Rol 3092		1	293 336 297
TZC	M-80 M-80	As Rol	led 1700	1	308 240 - 296
	M-91	As Rol	led		335
	M-91	3092	1700	1	240
	M-91	$+\frac{3092}{2400}$	1700 1315	1 5	280 - 319
	M-91	+ 3092 2400	1700 1315	1 10	264
	M-91	2500	1371	1	303
	4345	2400	1315	1	319 - 373
	4345	2500	1371	1	
TZM	7502	2200	1204	1	266 - 342
	7502	2850	1566	1	209
	KDTZM-1175	2300	1260	1	297 - 335
	7463	2250	1232	0.5	300 - 330
	Cb-modified 4305-4	2500	1371	1	278
	11	2800	1538	1	245
	į į	3000	1649	1	279
T-111	70616	2400	1316	1	216 - 368
	70616	2600	1427	1	211 - 266
	70616	3000	1649	1	260 - 287
	70616	3000	1649	16	237 - 271
	70616	3500	1877	1	234 - 242
	65079	2800	1538	1	236
	65079	3000	1649	1	253 - 296
	D-1670	As Rec		,	323 - 342
	D-1670	3000	1649	1	
	D-1102	As Rec		1	
	D-1102 MCN02A065	3000 Not Av	1649 ailable	1	

TABLE 5 (Continued)

Material	Heat No.	Heat T	reatment <u>°C</u>	Time Hours	DPH (100 gm load)
T-222	AL-TA-43	As Roll	ed		413
	AL-TA-43	2600	1426	1	314
	AL-TA-43	2800	1538	1	317
	AL-TA-43	3000	1649	1	357
,	Ta-43-SF-2	2300	1260	1	309 - 353
	Ta-43-SF-2	3000	1649	1	357
Tungsten	KC1357	As Roll	.ed		487
	KC1357	2800	1538	1	421
	KC1357	3200	1760	1	407
W-25%Re	3. 5-75002	2375	1302	1	639
11 23 /0200	3. 5-75002	2550	1399	1	639
	3. 5-75002	3200	1760	1	568
Sylvania A	3, 5 , 7 , 1 , 1	2732	1500	5 min.	579
Dylvailla 11		3200	1760	1	453

#### E. Material Tensile Strength

Tensile tests were performed on samples of TZC Heats M-80, M-91, and 4345 as well as on samples of T-111 alloy Heat 65079. Where elevated temperature tests were made, the ambient vacuum was in the 10<sup>-6</sup> torr range. The data obtained are given in Tables 6 and 7.

TZC Heat M-80 lacked ductility at room temperature. A 25-hour treatment at 2750°F (1510°C) alleviated this condition while two other treatments failed to improve the ductility. One of the two unsuccessful treatments was a 1 hour anneal at 3092°F (1700°C) and the other was a 1 hour anneal at 3092°F (1700°C) followed by a 1 hour anneal at 2400°F (1316°C).

TZC Heat M-91 was ductile at room temperature due to the greater severity of reduction during processing. Stress relieving at 2500°F (1371°C) for one hour had little effect on the tensile properties while recrystallization at 3092°F (1700°C) for one hour produced a substantial decrease in strength. Aging at 2400°F (1316°C) after recrystallizing had little effect on the tensile properties of TZC Heat M-91. TZC Heat 4345 appeared to have slightly better tensile properties than Heat M-91.

T-111 Heat 65079 was the only lot of T-111 alloy selected for tensile testing. As indicated in Table 7, a comparison was made between specimens with tensile axes both parallel and perpendicular to the direction of rolling. The data indicate that the tensile properties of this particular heat of T-111 are independent of the principal directions to rolling.

TABLE 6

TZC Tensile Properties

Heat No.	Condition	Test Temp, °F	Strength, Ultimate	ksi <u>Yield</u>	%E1 <u>1''G.</u> L.	%R. A.
M-80 (1)	2750°F-25 Hrs. 3092°F- 1 Hr. 3092°F- 1 Hr. 2400°F- 1 Hr.	R. T. R. T. R. T.	100 69 95	68 68 90	7 1 1	10 0 0
M-91 (2)	As Rolled 2500°F- 1 Hr. 3092°F- 1 Hr. 3092°F- 1 Hr. 3092°F- 1 Hr. 3092°F- 1 Hr. 2400°F- 5 Hrs. 3092°F- 1 Hr. 2400°F- 1 Hr.	R. T. R. T. 1800°F 2000°F 2200°F R. T.	141 106 85 45 41 35 75	99 99 49 29 25 24 45	7 4 7 34 43 42 8	7 7 7 88 88 88 88 8
4345 (3)	2500°F- 1 Hr. 2500°F- 1 Hr. 2500°F- 1 Hr. 3092°F- 1 Hr. 3092°F- 1 Hr. 3092°F- 1 Hr.	R. T. 1800°F 2200°F R. T. 1800°F 2000°F	123 77 62 88 63 61 54	117 75 61 50 27 24 25	12 17 18 19 29 28 29	19 61 61 17 68 70 66

<sup>(1)</sup> M-80 Extruded 2.3:1 at 3092°F (1700°C) and cross-rolled at 2925°F (1585°C) with 4% reduction per pass.

<sup>(2)</sup> M-91 Extruded 2.3:1 at 3092°F (1700°C) and cross-rolled with large deformations per pass, finishing at 2372°F (1300°C).

<sup>(3) 4345</sup> Extruded at 3000°F (1649°C), upset forged 40% at 2400°F (1316°C), broad forged to 0.825" at 2400°F (1316°C), vacuum annealed at 2400°F (1316°C).

TABLE 7
T-111, Heat No. 65079, Tensile Properties

Condition	Test Temp, °F	Strength, ksi Ultimate Yiel	%E1. <u>1''G. L</u> .
3000°F-1 Hr.	R. T.	94 74 (93)* (72	35 (34)
3000°F-1 Hr.	1800	74 34 (76) (34	10 Landau and 10
3000°F-1 Hr.	2200	49 32 (51) (32	
3000°F-1 Hr.	2600	29 25 (29) (26	

<sup>\* ( )</sup> Indicates specimen axis perpendicular to rolling direction. Otherwise specimen axis parallel to rolling direction.

# V RESULTS AND DISCUSSION

### A. Methods of Presenting the Creep Data

The specific creep data for each test will be presented as total specimen extension plotted as a function of time under load at the selected test temperature. At periodic intervals on the creep curves, the system pressure will be noted to indicate any variations in test environment. To simplify comparisons between different material or material conditions and to aid in design predictions, the data are also presented in the form of Larson-Miller and Manson-Haferd plots (8,9). Although more generalized parametric equations, which combine the time, temperature, and variables are available (8) with limited data they do not provide any improvement in prediction capability.

### B. Columbium-Base Alloys AS-30 and Cb-132M

Three creep tests were made using the as-rolled columbium-base alloy AS-30 and the data are presented in Figure 46. The creep curves show consistent discontinuities which are real effects and not due to scatter in the extension readings. Although similar effects, observed with numberous commercial alloys (9-12), have been associated with an isothermal instability of the material under study no attempt was made to evaluate whether such instabilities existed in the AS-30 alloy.

The creep curves for the Cb-132M alloy which was annealed at 3092°F (1700°C) for one hour prior to testing, are presented in Figure 47. A summary of the pertinent data for both AS-30 and Cb-132M is given in Table 8. Post-test examination indicated that no change in hardness or structure occurred in either alloy as a result of creep exposure.

A comparison of the AS-30 and Cb-132M alloy is presented in Figure 48 on the basis of the Larson-Miller parameter. The results indicate that the Cb-132M has significantly greater creep strength.

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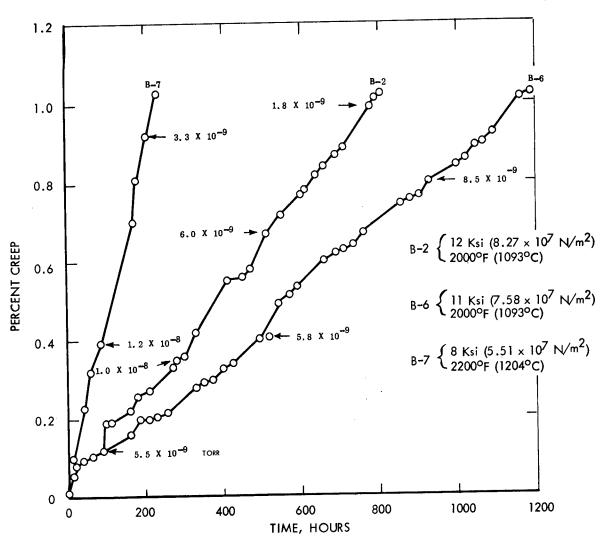
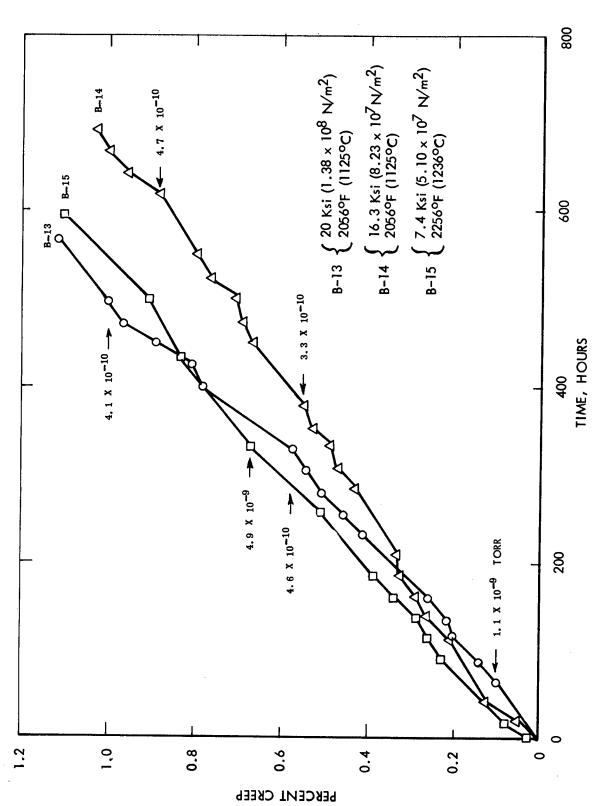


FIGURE 46 CREEP DATA FOR AS-30 PLATE (HEAT C-5) IN AS-ROLLED CONDITION. TESTED IN VACUUM ENVIRONMENT<1 X 10-8 TORR.

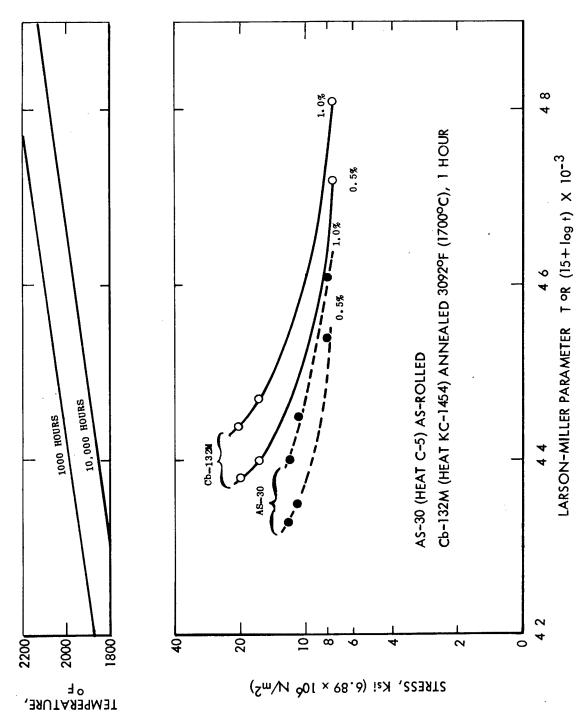


CREEP DATA FOR Cb-132M PLATE (HEAT KC-1454) ANNEALED 3092°F (1700°C), 1 HOUR. TESTED IN VACUUM ENVIRONMENT <1 × 10<sup>-8</sup> TORR. FIGURE 47

TABLE 8

Summary of Creep Data for Columbium-Base Alloys

	ate		ر ر	9	5-		٦٠.	-5	)-5
	Creep Rate		$1.3 \times 10^{-5}$	$8.5 \times 10^{-6}$	$4.5 \times 10^{-5}$		$2.0 \times 10^{-5}$	$1.5 \times 10^{-5}$	$1.8\times10^{-5}$
Miller eter	T°R (15 + logt) x $10^{-3}$ 0.5% 1.0%		44.0	44.5	46.1		44.4	44.7	48.1
Larson-Miller Parameter	T°R (15 + .0.5%		43.3	43.5	45.4		43.8	44.0	47.2
	Creep Hours 0.5% 1%		190	1170	225		495	029	550
	Creep 0.5%		390	450	115		275	340	250
	Stress ksi N/m <sup>2</sup>		$12   8.27 \times 10^7$	$7.58 \times 10^{7}$	$5.51 \times 10^{7}$		20 1.38×10 <sup>8</sup>	16.3 8.23×10 <sup>7</sup>	$7.4   5.10 \times 10^7$
	St <sub>1</sub>		12	11	<b>∞</b>		20	16.3	7.4
	Test Temperature		1093	1093	1204	C1454	1125	1125	1236
	Test Ter	AS-30 Heat C5	2000	2000	2200	Cb-132M Heat KC1454	2056	5056	2256
	Spec. No.	AS-30	B-2	B-6	B-7	Cb-132	B-13	B-14	B-15



LARSON-MILLER PLOT FOR 0.5 AND 1.0% CREEP IN AS-30 AND Cb-132M PLATE. TESTED IN VACUUM ENVIRONMENT<1  $\times$  10<sup>-8</sup> Torr. FIGURE 48

#### C. Molybdenum-Base Alloys

### 1. TZC Heat M-80

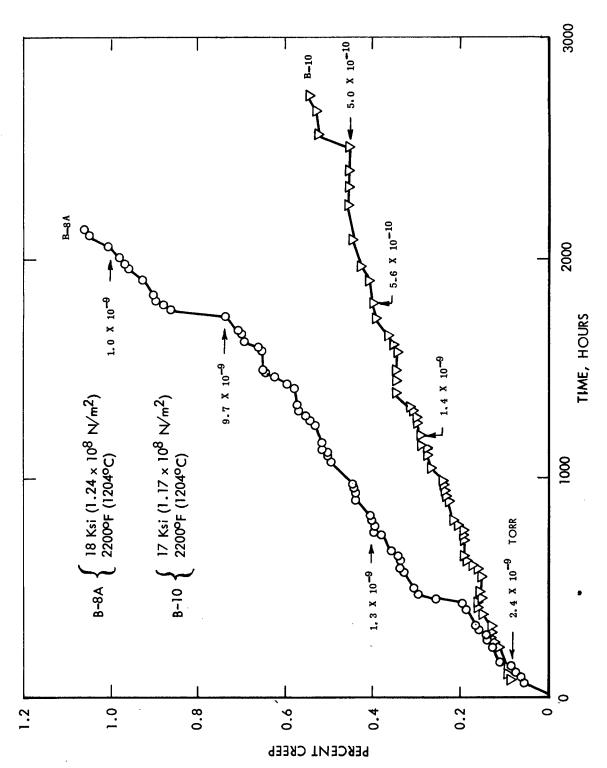
Eight creep tests were made with specimens of TZC Heat M-80 recrystallized at 3092°F (1700°C) for one hour prior to evaluation. The test conditions are shown below and the creep data are plotted in Figures 49 and 50.

	Test Ten	nperature	Stre	
Specimen	<u>°F</u>	°C	ksi	$\frac{N/m^2}{}$
B-5	2000	1093	14	$9.65 \times 10^{7}$
B-5A	2000	1093	20	$1.38 \times 10^{8}$
B-5B	2000	1093	22	$1.52 \times 10^{8}$
B-8A	2200	1204	18	$1.24 \times 10^{8}$
B-9	2000	1093	20	$1.38 \times 10^{8}$
B-10	2200	1204	17	$1.17 \times 10^{8}$
B-11	1856	1013	25	$1.72 \times 10^{8}$
B-12	2056	1125	19	$1.31 \times 10^8$

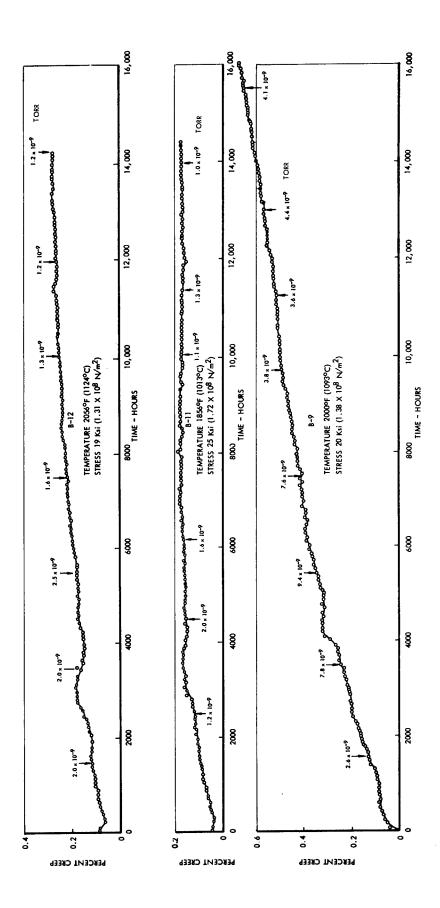
Tests B-5, B-5A, and B-5B were not plotted because the tests were conducted sequentially on the same specimen to establish approximate condition for further testing. In Figure 50 the discontinuties in the creep curve do not appear after 5000 hours due to stabilization of the microstructure.

In an effort to identify the microstructural changes that may be occurring during creep testing, a detailed examination was made of specimen B-8A, tested for 2128 hours at 2200°F (1204°C) and 18 ksi (1.24 x  $10^8$  N/m²). Metallographic examination showed that the gage section surface was thermally etched following testing, Figure 51. The microstructure of the gage cross section, Figure 51, indicated that the partially-recrystallized structure remained unchanged throughout the test with the exception of possible precipitation.

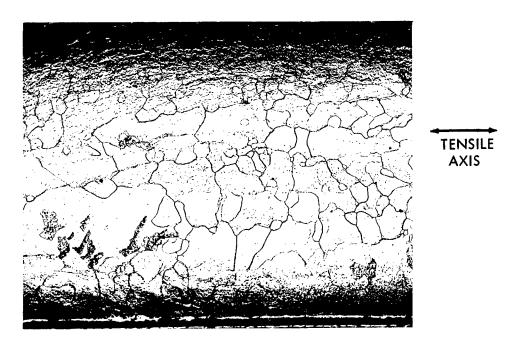
A comprehensive hardness examination was also made of specimen B-8A. The average hardness of the recrystallized grains in the unstressed button head was 242 DPH. This was 11 points lower than the hardness of similar grains in a sample recrystallized but not tested, 253 DPH. The average hardness of the unrecrystallized areas in the button head was 289 DPH which is not significantly different than similar areas in the recrystallized but untested specimens, 292 DPH. From these data it is concluded that prolonged heating at 2200°F (1204°C) caused a decrease in the hardness of the original recrystallized grains presumably due to agglomeration of a precipitate. No change occurred in the hardness of the unrecrystallized areas.



CREEP DATA TZC PLATE (HEAT M-80) RECRYSTALLIZED ONE HOUR AT 30920F (17000C). TESTED IN VACUUM ENVIRONMENT<1  $\times$  10<sup>-8</sup> TORR. FIGURE 49



CREEP TEST DATA, TZC PLATE (HEAT M-80), ANNEALED 3092°F (1700°C), 1 HOUR. TESTED IN VACUUM ENVIRONMENT <1 X 10<sup>-8</sup> TORR. FIGURE 50



THERMAL ETCHED SURFACE OF CREEP SPECIMEN IN GAGE SECTION

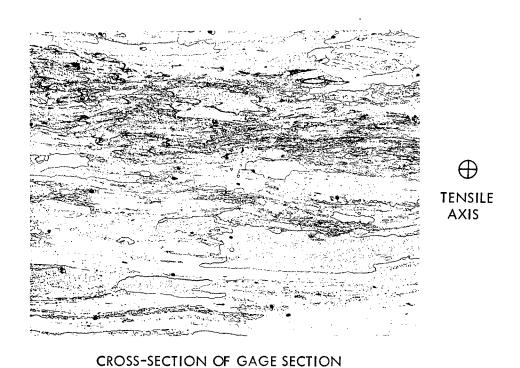


FIGURE 51 TZC PLATE (HEAT M-80) SPECIMEN B-8A. TESTED 2128 HOURS AT 2200°F (1204°C). ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O. 100 X

Examination of the recyrstallized grains in the gage section showed a hardness of 264 DPH compared to 242 DPH for the unstressed button head. This would indicate that work hardening occurred in the stressed area during testing. The unrecrystallized areas showed no appreciable hardness change which suggests that the major creep contribution occurred preferentially in the recrystallized grains.

Specimen B-9 tested for 16,002 hours to 0.670% elongation at 2000°F (1093°C) was tensile tested at room temperature. The results were identical to a heat treated but untested specimen with the exception of a slight increase in the percent elongation and reduction of area.

#### 2. TZC Heat M-91

Eight creep tests were made with specimens of TZC Heat M-91 subjected to various heat treatments prior to testing.

Spec.	Test Ter	nperature	Stre	ess	Hea	at Treatr	nent
No.	<u>°F</u>	°C	ksi	$N/m^2$	<u>°F</u>	<u>°C</u>	Hrs.
B-20	2000	1093	20	1.38 x 10 <sup>8</sup>	3092	1700	1
B-20 B-31	2200	1204	14	$9.65 \times 10^{7}$	3092	1700	1
B-22	2000	1093	20	1.38 x 10 <sup>8</sup>	3092	1700	1
				0	2400	1316	5
B-30	2200	1204	22	$1.52 \times 10^8$	2500	1371	1
B-32	1935	1057	20	$1.38 \times 10^{8}$	2500	1371	1
B-33	1900	1038	22	$1.52 \times 10^{8}$	2500	1371	1
B <b>-</b> 19	1800	982	44	$3.03 \times 10^{8}$	2300	1260	1
B-28	2000	1093	28	$1.93 \times 10^8$	2300	1260	1

The creep data plotted in Figures 52, 53, and 54 show many indications of non-uniform specimen extension. These deviations in the creep curve are real as they are greater than the scatter due to errors in measuring extension.

The results obtained with specimen B-22, annealed and aged prior to testing are open to question. Post-test examination of this specimen revealed a longitudinal crack in the gage section, Figure 55, and visual examination showed a high degree of localized distortion had occurred in some areas which may have influenced the average creep readings. The area of extensive deformation, shown at 500X in Figure 56, consists of grains exhibiting pronounced slip. A review of the creep curve, Figure 54, gives no indication that cracking occurred during test. Since cracking during heat treatment has been reported for the same heat of material (13), it was concluded that the specimen cracked during the heat treatment which was performed in situ prior to creep testing.

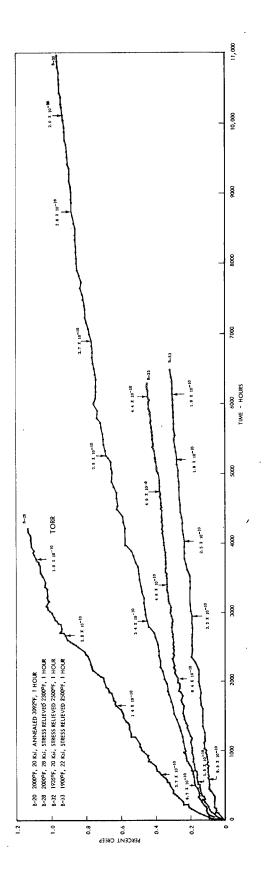


FIGURE 52 CREEP DATA, TZC (HEAT M-91) TESTED IN VACUUM ENVIRONMENT <1 X 10-8 TORR.

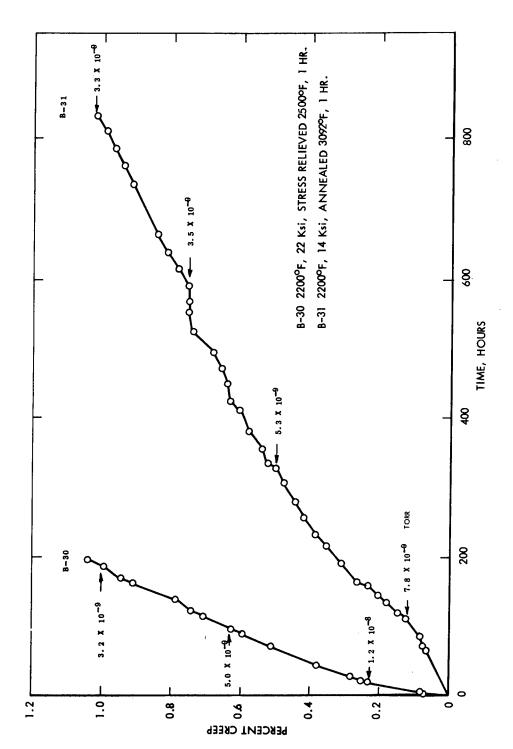


FIGURE 53 CREEP DATA FOR TZC PLATE (HEAT M-91). TESTED IN VACUUM ENVIRONMENT <1 x 10<sup>-8</sup> TORR.

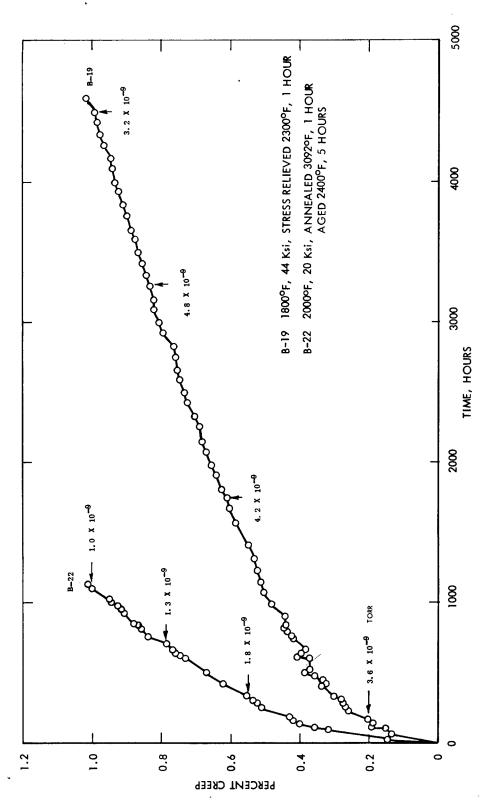
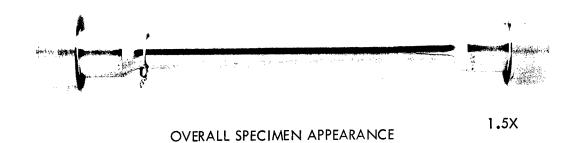
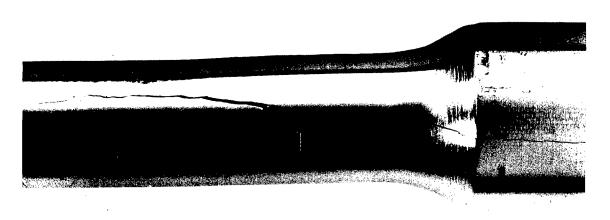


FIGURE 54 CREEP DATA TZC PLATE (HEAT M-91) TESTED IN VACUUM ENVIRONMENT  $<1\times10^{-8}\,$  TORR.





CLOSE-UP OF LONGITUDINAL CRACK

3X

FIGURE 55 TZC SPECIMEN B-22 (HEAT M-91) CRACKED DURING CREEP TESTING



FIGURE 56 TZC SPECIMEN B-22 (HEAT M-91). MICROGRAPH SHOWS LOCAL AREA OF SLIP AS SEEN ON SURFACE OF SPECIMEN AFTER TESTING, POLARIZED LIGHT. 500 X

The microstructure of B-22 was examined in an effort to identify the mode of cracking. Figure 57 which shows the defect at 100 and 500X indicates that the crack was preferentially located in the grain boundaries. Since the chemistry of Heat M-91 did not exhibit any abnormalities and since cracks of a similar type were not observed in Heat M-80, it appears that the high degree of warm working applied to Heat M-91, rendered the alloy susceptible to cracking during the recrystallization operation.

Post-test examination of Heat M-91 specimens showed no significant change in the microstructure. A comprehensive hardness examination of stress relieved specimen B-28, tested for 4214 hours at 2000°F (1093°C), showed no difference in hardness between button heat (345 DPH) and gage section (342 DPH). Both of these values were not significantly different than that of the original material, 335 DPH. Specimen B-31 recrystallized at 3092°F (1700°C) and tested for 912 hours at 2200°F (1204°C) had a button head and gage hardness of 226 and 228 respectively. This is not significantly different than the alloy recrystallized and untested (240 DPH).

## 3. TZC Heat 4345

TZC Heat 4345 was received late in the program and the first specimen is on test at  $2000^{\circ}F$  ( $1093^{\circ}C$ ) and 22 ksi ( $1.52 \times 10^8 \text{ N/m}^2$ ) (see Figure 58). The heat treatment applied prior to testing was one hour stress relief at  $2500^{\circ}F$  ( $1371^{\circ}C$ ).

A summary of all creep data from Heats M-80, M-91 and 4345 is given in Table 9. To compare the creep strength of the three heats, Larson-Miller and Manson-Haferd parameters were calculated for 0.5% creep and the values are listed in Table 9. The constants used in preparing the parameters were determined from Heat M-80 creep data using a computer program to obtain the parameters which would yield the best fit. The results plotted in Figure 59 show that the Heat M-80 recrystallized at 3092°F (1700°C), Heat M-91 stress relieved at 2300°F (1260°C) and Heat 4345 stress relieved at 2500°F (1371°C) have comparable creep strengths. Heat M-91 fully recrystallized by annealing one hour at 3092°F (1700°C) had comparatively the poorest creep strength.

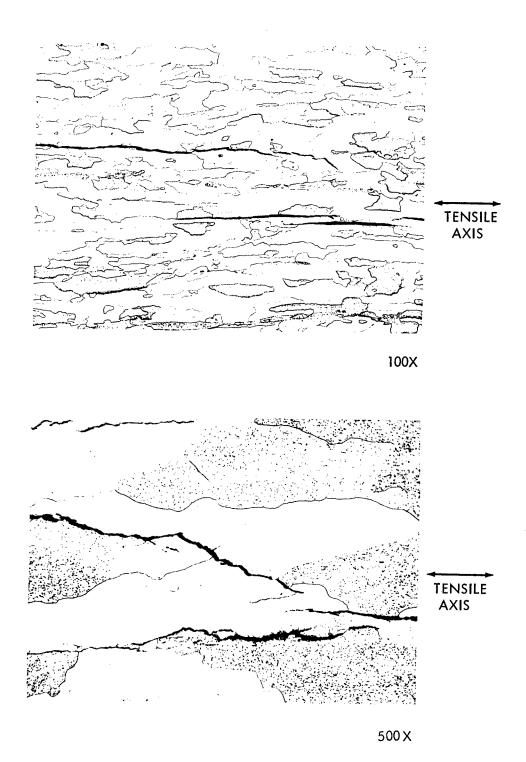


FIGURE 57 PHOTOMICROGRAPHS OF CRACK IN TZC (HEAT M-91) SPECIMEN B-22. ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O.

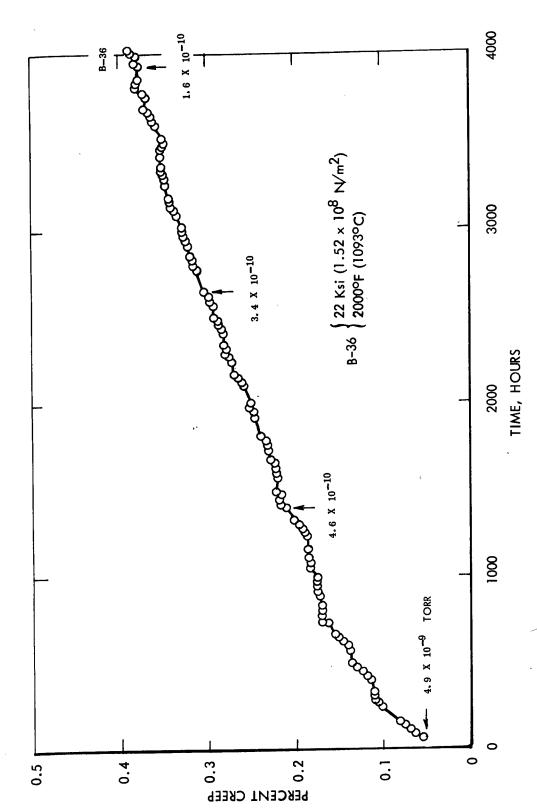


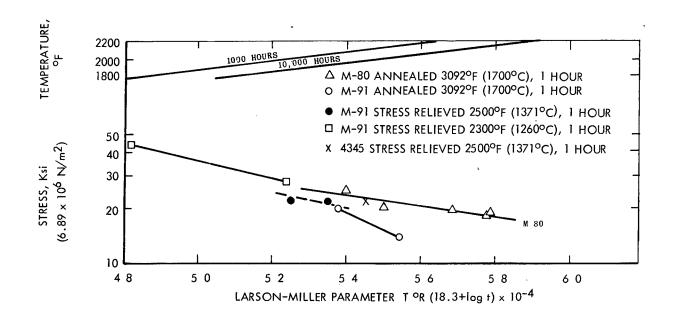
FIGURE 58 CREEP DATA FOR TZC PLATE (HEAT 4345), STRESS RELIEVED 2500°F (1371°C). TESTED IN VACUUM ENVIRONMENT<1  $\times$  10<sup>-8</sup> TORR.

TABLE 9

Summary of Creep Data for TZC

Creep Rate in-in - hr	4. 6 × 10 <sup>-6</sup> 4. 8 × 10 <sup>-7</sup> 2. 0 × 10 <sup>-6</sup> 4. 2 × 10 <sup>-8</sup> 1. 1 × 10 <sup>-7</sup>	1. 4 x 10-6 1. 5 x 10-5 7. 2 x 10-5 3. 4 x 10-7 5. 9 x 10-7 4. 7 x 10-6 4. 6 x 10-6	$6.7 \times 10^{-7}$
Manson-Haferd Parameter 0.5% Creep $\frac{\log t - 22.8}{T} \times 10^3$	-9.00 -9.41 -8.84 -9.57 -8.84	-9. 62 -9. 23 -9. 52 -9. 64 -9. 93 -10. 98	-9.96
Larson-Miller Parameter 0.5% Greep T°R (18.3+log t)x 10-3	56.9 55.0 57.8 54.2 57.9	გი გ	54.5
Hours to 0.5% Creep	1, 100 10, 400 2, 500 120, 000* 46, 000*	3,650 325 ( 70 14,500* 8,500* 1,060 1,100	7,500*
Stress	18 20 17 25 19	20 22 20 22 44 44	22
Test Temp, °F	2200 2000 2200 1856 2056	. 2000 2200 2200 1935 1900 2000	2000
Heat Treatment	3092°F-1 Hr. 3092°F-1 Hr. 3092°F-1 Hr. 3092°F-1 Hr.	3092°F-1 Hr. 2500°F-1 Hr. 2500°F-1 Hr. 2500°F-1 Hr. 2300°F-1 Hr.	2500°F- 1 Hr.
Specimen No.	B-8A B-9 B-10 B-11 B-12	B-20 B-31 B-30 B-32 B-13 B-19	B-36
Heat No.	M-80	M-91	4345

\* Extrapolated Value



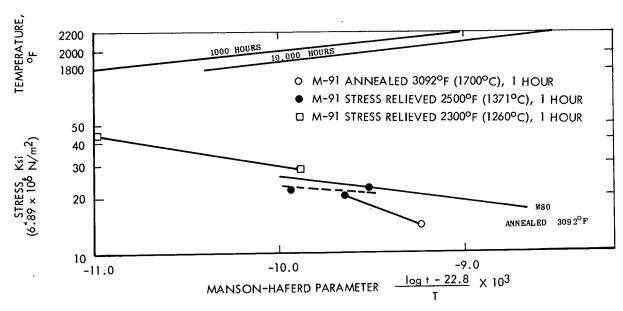


FIGURE 59 PARAMETRIC PLOTS OF 0.5% CREEP DATA FOR TZC PLATE. TESTED IN VACUUM ENVIRONMENT <1 x 10<sup>-8</sup> TORR.

#### 4. TZM Heat 7502

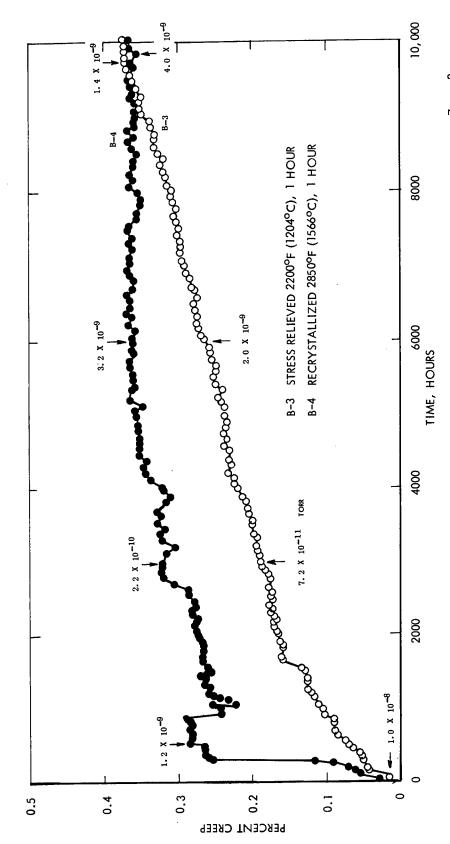
TZM Heat 7502 was an eleven inch diameter disc forging with radial cut specimens. All but one specimen was tested in the as-received condition, i.e., stress relieved one hour at 2200°F (1204°C). The single exception was specimen B-4 which was recrystallized for one hour at 2850°F (1566°C). The conditions evaluated are listed below:

Specimen No.	Test Ter	nperature °C	Str <u>ksi</u>	ess N/m <sup>2</sup>
D 1	2000	1000		0.07
B-1	2000	1093	12	8. 27 x $10^{7}$
B-3	2000	1093	10	$6.89 \times 10^{7}$
B-4	2000	1093	10	$6.89 \times 10^{7}$
B-29	2000	1093	41	$2.82 \times 10^{8}$
B-35	1800	982	44	$3.03 \times 10^{8}$

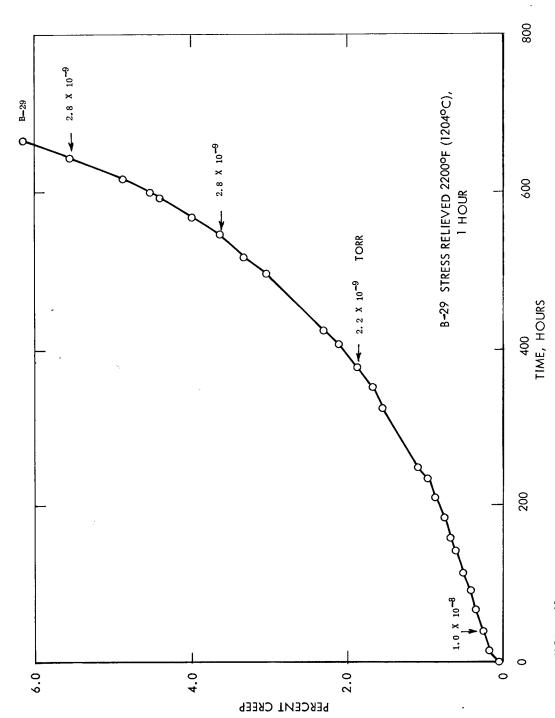
The creep data from these tests are plotted in Figures 60, 61, and 62. Specimens B-3 and B-4, Figure 60, constitute a comparison of the 2200°F (1204°C) stress relief and 2850°F (1566°C) recrystallization heat treatments. The creep curves show that the recrystallized material underwent a rapid extension of almost 0.3% during the first 500 hours, and then exhibited a relatively constant creep rate of 8.0 x 10<sup>-8</sup> in-in<sup>-1</sup>-hr<sup>-1</sup>. While the stress relieved material showed no initial extension but a greater steady state creep rate of 2.67 x 10<sup>-7</sup> in-in<sup>-1</sup>-hr<sup>-1</sup>. The net effect was that the two tests reached approximately the same amount of extension after 10,000 hours. The appearance of some negative creep in the recrystallized specimen B-4 suggests that precipitation may be occurring during testing of materials so pre-treated.

Post-test examination showed that thermal etching of the specimen occurred even at 2000°F (1093°C) and less than 650 hours, however, no significant change was noted in either the microstructure or hardness.

The test with specimen B-29 was continued to slightly more than 6% extension to evaluate the mode of creep deformation as shown in Figure 63. The deformation at 2000°F (1093°C) and 41 ksi (2.82 x  $10^8$  N/m²) proceeds principally by transgranular slip. This is further confirmed by the absence of grain boundary slip which would be evident by localized displacement of the scribe marks.



Creep data tzm forged disc (heat 7502). Tested at 2000°F (1093°C) and 10 Ks; (6.89  $\times$  10<sup>7</sup> N/m²) in vacuum environment<1  $\times$  10<sup>-8</sup> Torr. FIGURE 60



Creep Data TZM forged DISC (HEAT 7502). TESTED AT 2000°F (1093°C) AND 41 Ksi (2.82  $\times$  10<sup>8</sup> N/m²) in Vacuum environment <1  $\times$  10<sup>-8</sup> Torr. FIGURE 61

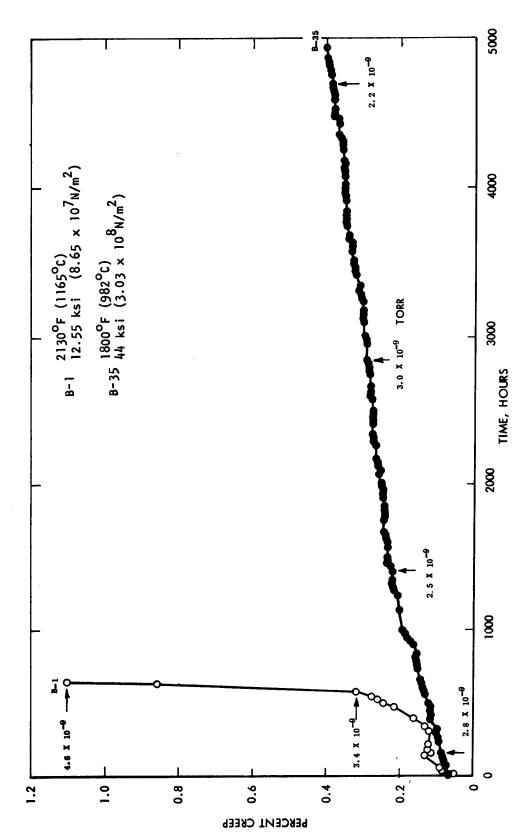


FIGURE 62 CREEP DATA TZM FORGED DISC (HEAT 7502) STRESS RELIEVED 2200°F (1204°C) ONE HOUR. TESTED IN VACUUM ENVIRONMENT < 1 x 10<sup>-8</sup> TORR.

# TRANS GRANULAR SLIP LINES



2.5 X

TZM FORGED DISC (HEAT 7502) STRESS RELIEVED 2200°F (1204°C).
TESTED AT 2000°F (1093°C) AND 41 Ksi IN VACUUM ENVIRONMENT
<1 X 10-8 TORR. 6.215% CREEP OBTAINED IN 664.3 HOURS.
NOTE THE LINES INDICATING TRANSGRANULAR SLIP.

## 5. TZM Heat KDTZM-1175

Four tests, listed below, were made using Heat KDTZM-1175 in the as-received condition, i.e. stress relieved at 2300°F (1260°C) for one hour.

	Test Ter	nperature	Str	ess
Specimen No.	<u>°F</u>	_°C	<u>ksi</u>	$N/m^2$
B-16	1855	1013	23. 4	1.61 x 10 <sup>8</sup>
B-18	1600	871	55	$3.79 \times 10^{8}$
B-21	1600	871	65	$4.48 \times 10^{8}$
B-25	1800	982	44	$3.03 \times 10^{8}$

The preparation of specimens of this heat were different in that all were electro-polished using Globe Chemical Co. electropolishing solution No. 4 in a lead-lined pyrex container with a C.P. Lead cathode. Polishing was accomplished with a current density of 10 amps/in<sup>2</sup> at 14 volts.

The creep data for the four tests, plotted in Figure 64, show that at 1600°F (871°C) essentially no creep occurred even at stresses as high as 65 ksi  $(4.48 \times 10^8 \text{ N/m}^2)$ .

Post-test examination of specimens from Heat KDTZM-1175 indicated that no significant changes in either the microstructure or hardness occurred as a result of the test exposure.

#### 6. TZM Heat 7463 (Commercial Bar)

A single specimen from 5/8 inch diameter commercial TZM bar, Heat 7463, was tested in the as-received condition, i. e. stress relieved at 2250°F (1232°C) for 1/2 hour. The data obtained for the test temperature of 2000°F (1093°C) and a stress of 41 ksi (2.82 x  $10^8$ N/m²) are plotted in Figure 65.

A summary of creep data from TZM Heats 7502, KDTZM-1175, and 7463 is given in Table 10. Also included are the times for 0.5% creep, the creep rate and the Larson-Miller parameter based on a constant of 20.1 determined by computer procedures. The parametric comparison made in Figure 66 shows thats Heats KDTZM-1175 and 7463 have greater creep strengths than Heat 7502. Since the chemistry of Heats 7502 and 7463 are essentially the same, it is concluded that the method of processing the molybdenum-base TZM bar alloy has a significant effect on the creep strength.

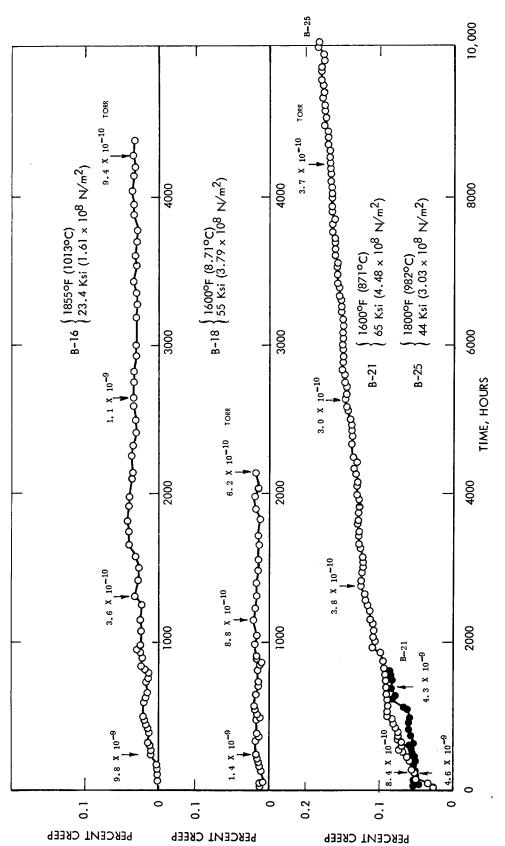
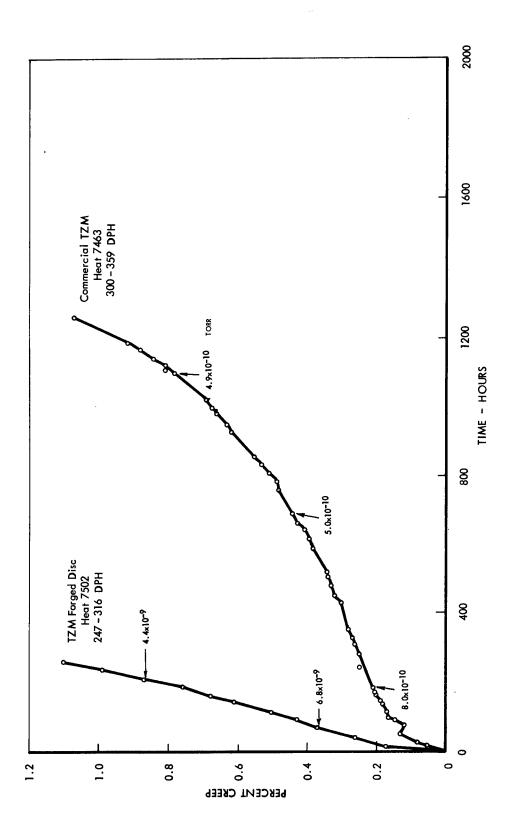


FIGURE 64 CREEP DATA TZM FORGED DISC (HEAT KDTZM-1175) STRESS RELIEVED 2300°F (1260°C) ONE HOUR. TESTED IN VACUUM ENVIRONMENT < 1  $\times$  10<sup>-8</sup> TORR.



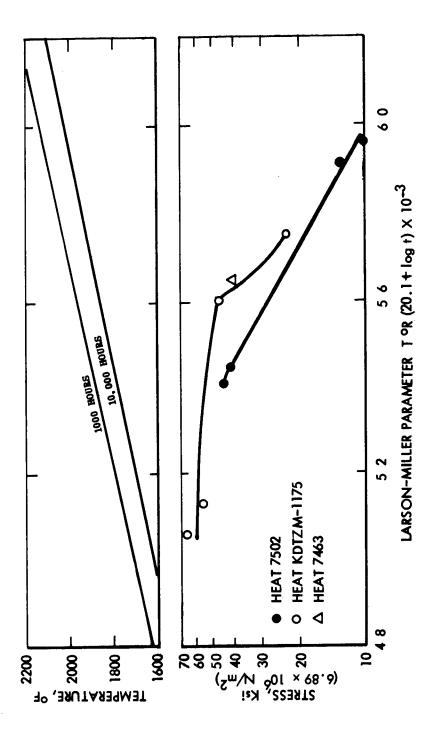
CREEP DATA FOR TZM COMMERCIAL BAR (HEAT 7463) STRESS RELIEVED AT 2250°F (1232°C) 1/2 HOUR. TESTED AT 2000°F (1093°C) AND 41 Ksi (2.82x10<sup>8</sup> N/m²) IN VACUUM ENVIRONMENT < 1 X 10<sup>-8</sup> TORR. FIG URE 65

TABLE 10

Summary of Creep Data for TZM

Creep Rate	8.3 × 10 <sup>-6</sup> 3.5 × 10 <sup>-7</sup>	2.0 × 10 / 4.4 × 10 <sup>-5</sup> 7.1 × 10 <sup>-7</sup>	8.0 × 10-8 8.3 × 10-8 5.2 × 10-7 1.0 × 10-7	$6.2 \times 10^{-6}$
Larson-Miller Parameter 0.5% Creep TOR(20.1+log*t) x 10 <sup>-3</sup>	59.3 59.6	60.3 54.5 54.1	57.5 51.3 49.6 56.0	56.5
Hours to 0.5% Creep	605,14,200*	25,000* 115 7,000*	62,500* 60,000* 9,600* 50,000*	800
ss N/m 2			1.6.×108 3.79×108 4.48×108 3.03×10	2.82×10 <sup>8</sup>
Stress ksi N	12.55	0 1 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7	23.4 65 65 44	<b>1</b>
Temperature	1165	1093 1093 982	1013 871 871 982	1093
Test Ter	2130	2000 1800 1800	1855 1600 1600 1800	2000
Heat Treatment	2200 <sup>o</sup> F - 1 Hr. 2200 <sup>o</sup> F - 1 Hr.	2200°F - 1 Hr. 2200°F - 1 Hr. 2200°F - 1 Hr.	2300°F - 1 Hr. 2300°F - 1 Hr. 2300°F - 1 Hr. 2300°F - 1 Hr.	2250 <sup>0</sup> F - ⅓ Hr.
Specimen No.	8-3 8-3	8-29 8-35	B-16 B-18 B-21 B-25	B-34
Heat	7502		1175	7463

\* Extrapolated Values



LARSON-MILLER PLOT OF 0.5% CREEP DATA FOR TZM STRESS RELIEVED 2200-23009F (1204–1260°C). TESTED IN VACUUM ENVIRONMENT < 1  $\times$  10<sup>-8</sup> TORR. FIGURE 66

t 16-

## 7. Columbium Modified TZM Heat 4305-4

Two specimens of columbium-modified TZM Heat 4305-4 were tested in the as-received state, i. e., stress relieved one hour at 2500°F (1371°C).

Specimen	Test Te	mperature	St	ress 2	Time	
<u>No.</u>	°F	<u>°C</u>	ksi	N/m <sup>2</sup>	Hours	%Creep
				8	( - (	
B-23A	2000	1093	20	1. 38 x $10^8$	686	0.032
B-23B	2000	1093	28	$1.93 \times 10^{8}$	307	0.028
B-23C	2000	1093	40	$2.76 \times 10^{8}$	185	0.188
B-23D	1800	982	46	3. 17 x $10_{\circ}^{8}$	403	0.078
B-23E	2100	1149	34	$2.34 \times 10^{\circ}$	329	0.170
B-27	2000	1093	41	$2.82 \times 10^8$	1587	1.040

The purpose of the first five tests made on the same specimen (B23A-E) was to accumulate enough data to estimate the time required for 0.5% creep. From this an approximate parametric creep curve was obtained with one specimen. Because of the short times involved, the creep data for these tests are not plotted; however, the creep curve for specimen B-27 tested at 2000°F (1093°C) and 41 ksi (2.82 x  $10^8 \text{N/m}^2$ ) is plotted in Figure 67. Included with Figure 67 are the creep curves for TZM Heats 7502 and 7463 tested under identical conditions. Although a significant part of the improved creep strength of the columbium modified TZM is due to the method of processing, the comparison with the data obtained from the TZM bar stock indicates that the columbium addition improved creep resistance.

Table 11 and Figure 68 show the Larson-Miller creep data based on the general constant of 15. The curve should be used with some discretion, since it is approximate and based on extrapolated values obtained from a series of tests on a single specimen.

#### D. Tantalum-Base Alloys

#### 1. T-222 Heat AL-TA-43

Three tests were made with T-222 Heat AL-TA-43 using the two heat treatments shown below. The creep data plotted in Figures 69 and 70 show that the higher recrystallization temperature may provide better creep strength.

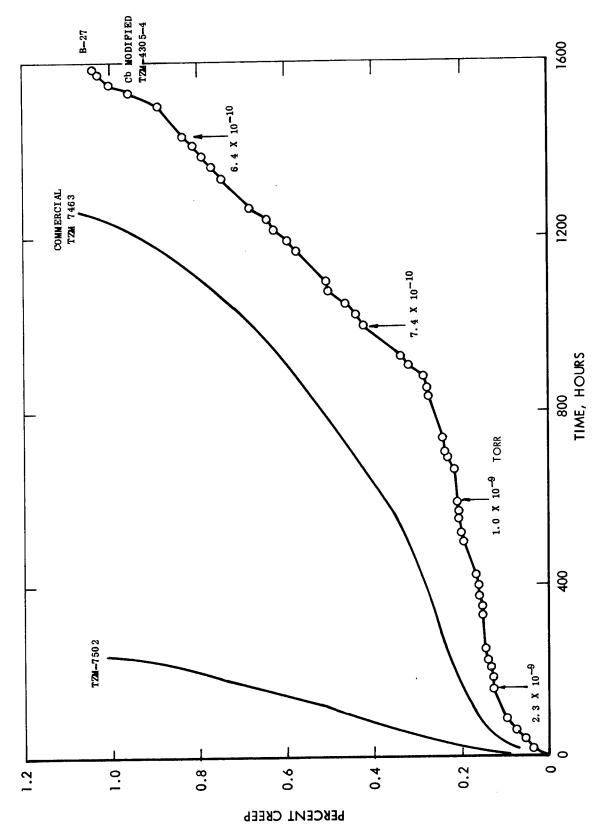


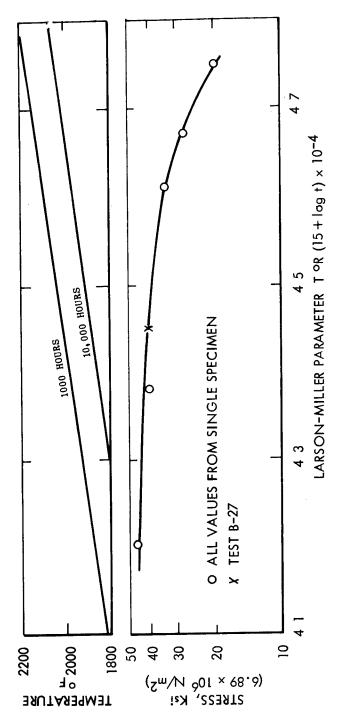
FIGURE 67 CREEP DATA FOR COLUMBIUM MODIFIED TZM (HEAT 4305-4). TESTED AT 2000°F (1093°C) AND 41 Ksi (2.82  $\times$  108 N/m²) IN VACUUM ENVIRONMENT < 1  $\times$  10<sup>-8</sup> TORR.

TABLE 11

Summary of Creep Data for Columbium-Modified TZM Heat 7503-4

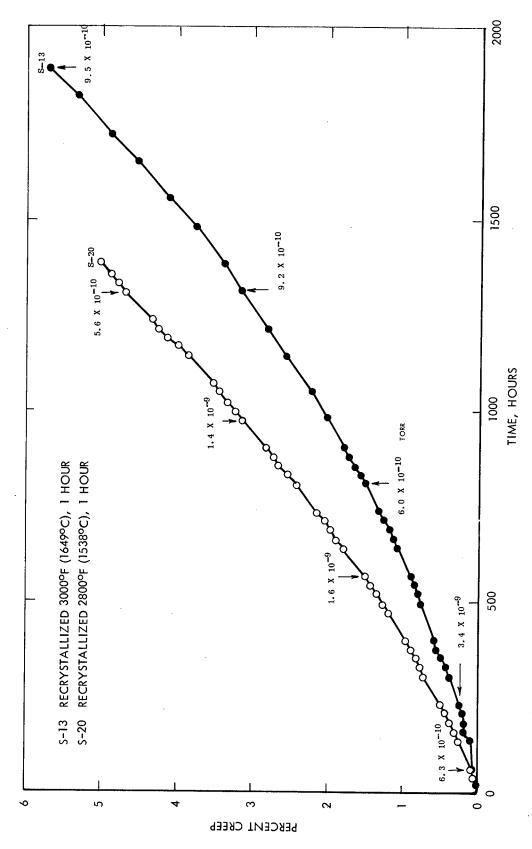
Specimen No.	Test Temperature	erature °C	Str ksi	Stress i N/m <sup>2</sup>	Hours to 0.5% Creep	Larson-Miller Parameter 0.5% Greep T°R (15.0+log t) x 10 <sup>-3</sup>
B-23A	2000	1093	20	1.38 x $10^8$	*000,00	47.5
B-23B	2000	1093	28	$1.93 \times 10^{8}$	10,000*	46.7
B-23C	2000	1093	40	$2.76 \times 10^{8}$	630*	43.8
B-23D	1800	982	46	$3.17 \times 10^{8}$	4,000*	42.0
В-23Е	2100	1149	34	$2.34 \times 10^{8}$	1,000*	46. 1
B-27	2000	1093	41	$2.82 \times 10^{8}$	1,090	44.5

\* Extrapolated Values

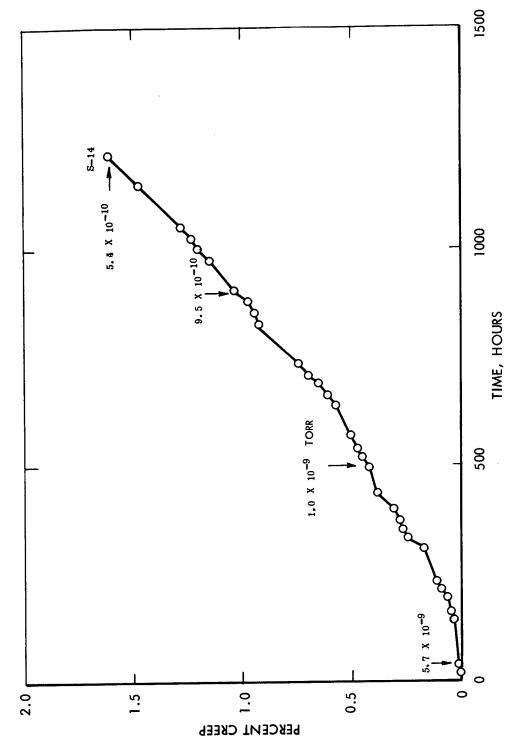


LARSON-MILLER PLOT OF 0.5% CREEP DATA FOR COLUMBIUM MODIFIED TZM (HEAT 7503-4) STRESS RELIEVED 2500°F (1371°C) ONE HOUR. TESTED IN VACUUM ENVIRONMENT <1 × 10<sup>-8</sup> TORR. FIGURE 68

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CREEP DATA FOR T-222 SHEET (HEAT AL-TA-43). JESTED AT 2200°F (1204°C) AND 12 Ksi (8.26  $\times$  10<sup>7</sup> N/m<sup>2</sup>) IN VACUUM ENVIRONMENT <1  $\times$  10<sup>-8</sup> TORR. FIGURE 69



CREEP DATA FOR T-222 SHEET (HEAT AL-TA-43) RECRYSTALLIZED ONE HOUR, 3000°F (1649°C). TESTED AT 2056°F (1124°C) AND 19.2 Ksi (1.32  $\times$  10<sup>8</sup> N/m²) IN VACUUM ENVIRONMENT<1  $\times$  10<sup>-8</sup> TORR. FIGURE 70

Specimen	Heat T	reatment		Test Te	mperature	Str	ess ,
<u>No.</u>	<u>°F</u>	<u>°C</u>	Hrs.	°F_	°C	ksi	$N/m^2$
							7
S-13	3000	1649	1	2200	1204	12	$8.26 \times 10^{\prime}$
S-14	3000	1649	1	2056	1124	19.2	$1.32 \times 10^{8}$
S-20	2800	1538	1	2200	1204	12	8. 26 x 10 <sup>7</sup>

Post-test examinations of the specimens showed that the scribe marks used for creep measurement had been displaced at the thermally etched grain boundaries (see Figure 71). Under polarized light, fine slip lines could be found within the grains of the same area, Figure 72. These observations indicate that creep proceeds in this test by grain boundary sliding as well as by transgranular slip.

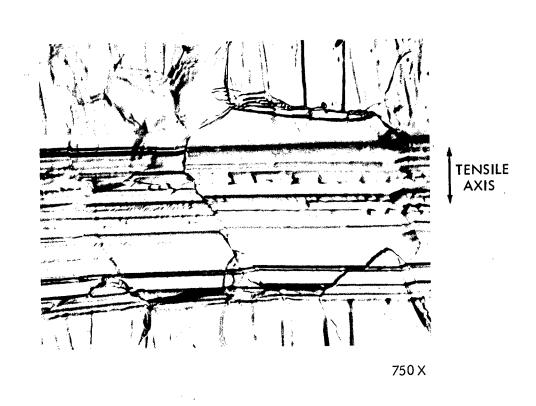
T-222 Heat AL-TA-43 after recrystallization for one hour at 3000°F (1649°C) had a hardness of 357 DPH. Specimen S-13 after testing for 1890 hours at 2200°F (1204°C) had a hardness of 236 DPH indicating that softening took place during testing. Specimen S-14 also exhibited a hardness decrease to 264 DPH after 3229 hours at a lower test temperature of 2056°F (1124°C).

#### 2. T-111 Heat 70616

Several heats of tantalum-base T-lll were tested with Heat 70616 being the most extensively investigated.

Specimen	Heat T	reatment		Test Te	mperature	St	ress
No	°F	<u>°C</u>	<u>Hrs</u> .	°F	°C	ksi	N/m <sup>2</sup>
Š-16	2600	1427	1	2200	1204	8	5. 15 x 10 <sup>7</sup>
S-19	3000	1649	1	2200	1204	8	5. 15 x $10^7$
S-21	3000	1649	1	2200	1204	12	$8.26 \times 10^{7}$
S-22	3000	1649	1	2000	1093	20	1. 38 x $10^{8}$
S-23	3000	1649	1	2120	1160	12	$8.26 \times 10^{7}$
S-24	3000	1649	1	1860	1016	20	$1.38 \times 10^{8}$

The first two tests, S-16 and S-19, were made to determine the effect of the recrystallization temperature on the creep strength of the alloy. The creep data for the specimens recrystallized at 2600°F (1427°C) and 3000°F (1649°C) are plotted in Figure 73. The results clearly show that the higher recrystallization temperature provided the better creep strength. The two tests at 12 ksi (8.26 x  $10^7 \text{N/m}^2$ ) are plotted in Figure 74 and those at 20 ksi (1.38 x  $10^8 \text{N/m}^2$ ) are shown in Figure 75. It will be noted in the three figures that all curves for the material recrystallized at 3000°F (1649°C) exhibit a pronounced upward curvature.

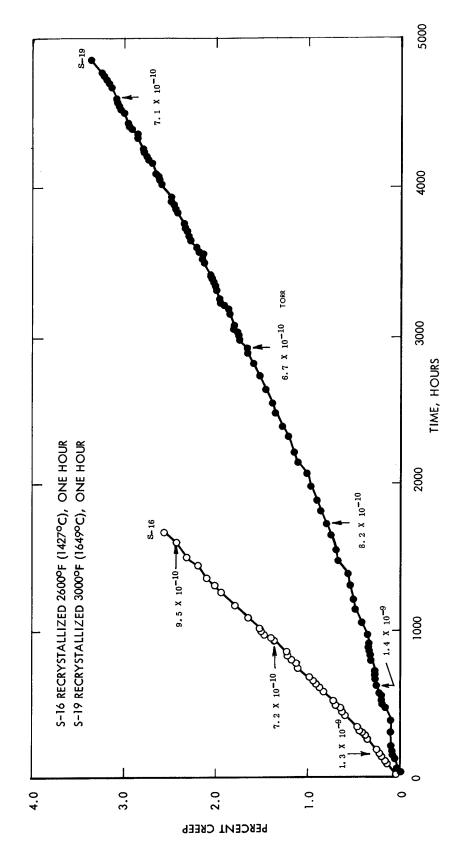


SURFACE OF T-222 SHEET SPECIMEN AFTER TESTING AT 2200°F (1204°C), 12 Ksi (8.26 × 10<sup>7</sup>N/m²) FOR 1890 HOURS. 5.72% TOTAL EXTENSION. PHOTOMICROGRAPH SHOWS GRAIN BOUNDARY SLIDING. THERMALLY ETCHED SURFACE°



1000 X

SURFACE OF T-222 SHEET SPECIMEN AFTER TESTING AT 2200°F (1204°C), 12 Ksi (8.26 x 10<sup>7</sup>N/m²) FOR 1890 HOURS. 5.72% TOTAL EXTENSION. PHOTOMICROGRAPH ILLUSTRATES FINE SLIP PRESENT IN THE GRAIN. POLARIZED LIGHT.



CREEP DATA FOR T-111 SHEET (HEAT 70616) TESTED AT 2200°F (1204°C) AND 8 Ksi (5.51  $\times$  10<sup>7</sup> N/m<sup>2</sup>) IN VACUUM ENVIRONMENT <1  $\times$  10-8 TORR. FIGURE 73

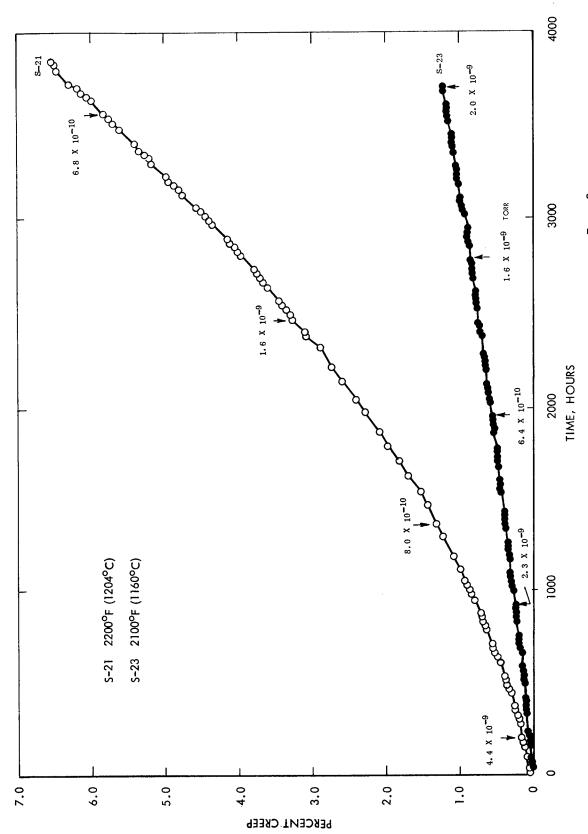


FIGURE 74 CREEP DATA FOR 1-111 SHEET (HEAT 70616). TESTED AT 12 Ksi (8.26  $\times$  10<sup>7</sup> N/m²) IN VACUUM ENVIRONMENT < 1  $\times$  10<sup>-8</sup> TORR.

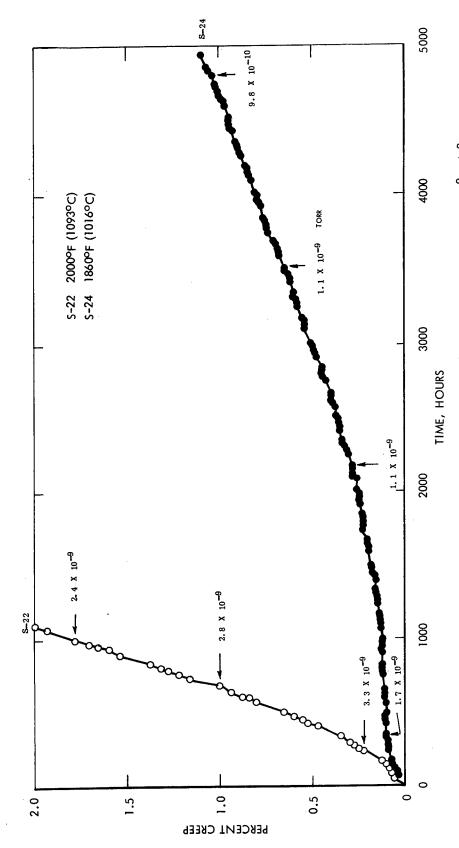


FIGURE 75 CREEP DATA FOR T-111 SHEET (HEAT 70616). TESTED AT 20 Ksi (1.38  $\times$  10<sup>8</sup> N/m²) IN VĄCUUM ENVIRONMENT<1  $\times$  10<sup>-8</sup> TORR.

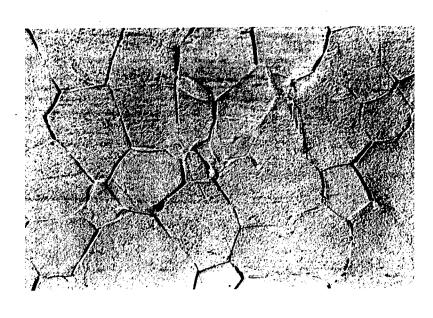
Post-test metallography of the specimens tested to 3-6% extension showed the presence of small grain boundary manifestations which appeared to be voids (Figure 76). However, an electron microprobe analysis on Specimen S-19, tested to 3% elongation at 2200°F (1204°C) indicated these areas to be rich in hafnium (Figure 77). Similar areas could not be detected in the untested material. Titran and Hall (14) observed a similar structure and interpreted it as a grain boundary precipitate. The true nature of the manifestation is thus not clear at the present time. Examination of the specimens after testing showed the presence of both grain boundary and transgranular slip as was observed with T-222 alloy. Post-test hardness measurements of T-111 Heat 70616 showed that prolonged heating during test caused the hardness of the original recrystallized material (260-287 DPH) to decrease to 226-230 DPH.

## 3. T-111 Heat 65079

Three tests of Heat 65079 were conducted with the specimens being taken both parallel and perpendicular to the direction of rolling. All specimens were recrystallized at 3000°F (1649°C) for one hour prior to testing. Two tests were made at the same temperature and stress to determine whether the creep strength varied as a function of orientation even though there was no difference in tensile properties in the two directions.

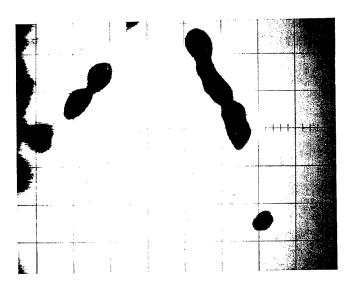
Specimen	Test Tem	perature	St	ress	,
No.	°F	°C	ksi	$N/m^2$	Axisoof Specimen
S-30 S-31 S-35	2400 2200 2200	1316 1204 1204	3. 5 5	$2.41 \times 10^{7}$ $3.44 \times 10^{7}$ $3.44 \times 10^{7}$	Perpendicular to rolling Perpendicular to rolling Parallel to rolling

The creep data for the two specimens S-31 and S-35 tested at  $2200^{\circ}F$  ( $1204^{\circ}C$ ) and 5 ksi (3.44 x  $10^{7}$  N/m<sup>2</sup>) are shown in Figure 78. While these tests are still in progress a small difference in creep resistance can be observed with the creep strength of the sample perpendicular to rolling direction being slightly greater than that parallel to rolling. The creep curve for the specimen tested at  $2400^{\circ}F$  ( $1316^{\circ}C$ ) is plotted in Figure 79.

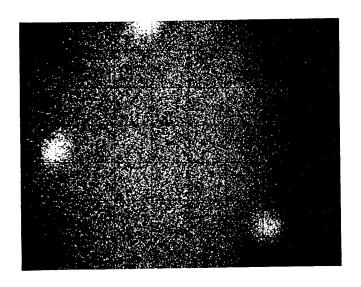


500 X

FIGURE 76 T-111 SHEET SPECIMEN S-21, TESTED AT 2200°F AND 12 Ksi 3840 HOURS. 6.55% CREEP. ETCHANT: 75% HF, 25%  $\rm H_2O$ .



SPECIMEN CURRENT IMAGE 2400 X



Hf X-RAY IMAGE 2400X

FIGURE 77 ELECTRON PROBE X-RAY MICROGRAPH OF T-111 SHEET SPECIMEN S-19 SHOWING HAFNIUM CONCENTRATION.

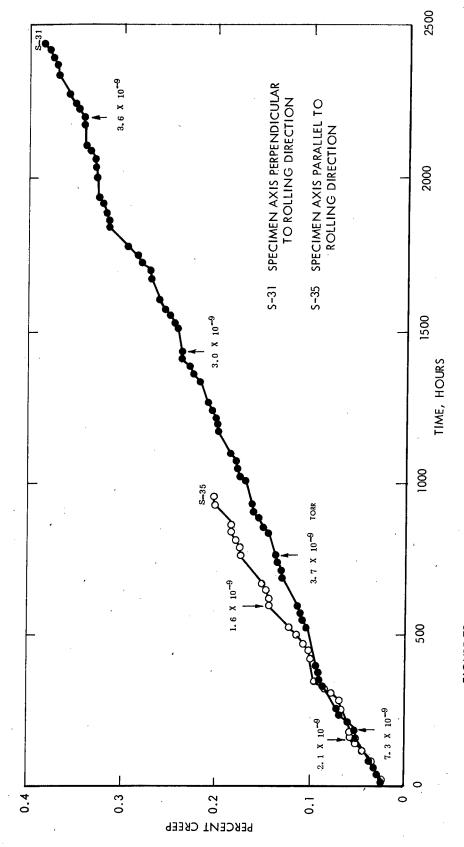


FIGURE 78 CREEP DATA FOR T-111 SHEET (HEAT 65079). TESTED AT 22009F (1204°C) AND 5 Ksi (3.44  $\times$  107 N/m²) IN VACUUM ENVIRONMENT<1  $\times$  10-8 TOR.

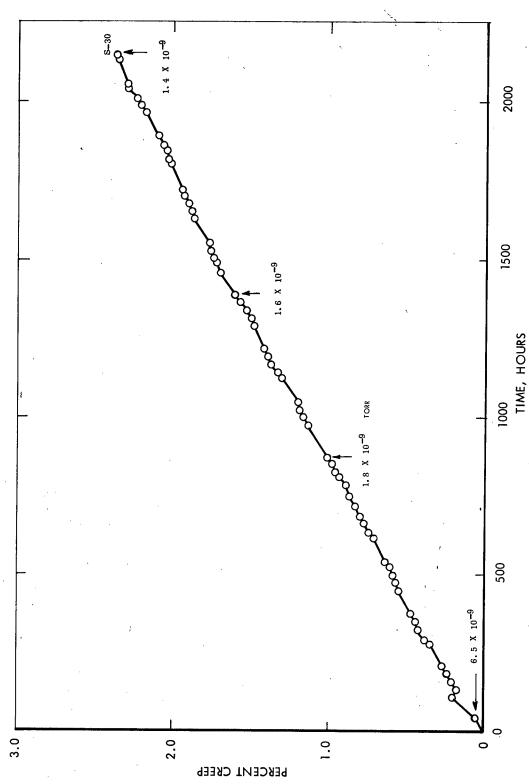


FIGURE 79 CREEP DATA FOR T-111 SHEET (HEAT 65079) SPECIMEN AXIS PERPENDICULAR TO ROLLING DIRECTION.
TESTED AT 2400°F (1316°C) AND 3.5 Ksi (2.41 × 10<sup>7</sup> N/m²) IN VACUUM ENVIRONMENT<1 × 10<sup>-8</sup> TORR.

# 4. T-111 Heat D-1670

Four creep tests were made with T-111 Heat D-1670 recrystallized one hour at 3000°F (1649°C).

Specimen	Test Ter	nperature	Stre	
No	<u> </u>	<u>°C</u>	<u>ksi</u>	<u>N/m²</u>
S - 25 S - 25A S - 26 S - 28	2000 2600 1800 2600	1093 1427 982 1427	17	1.03 x 10 <sup>8</sup> 1.03 x 10 <sup>7</sup> 1.17 x 10 <sup>8</sup> 3.44 x 10 <sup>6</sup>

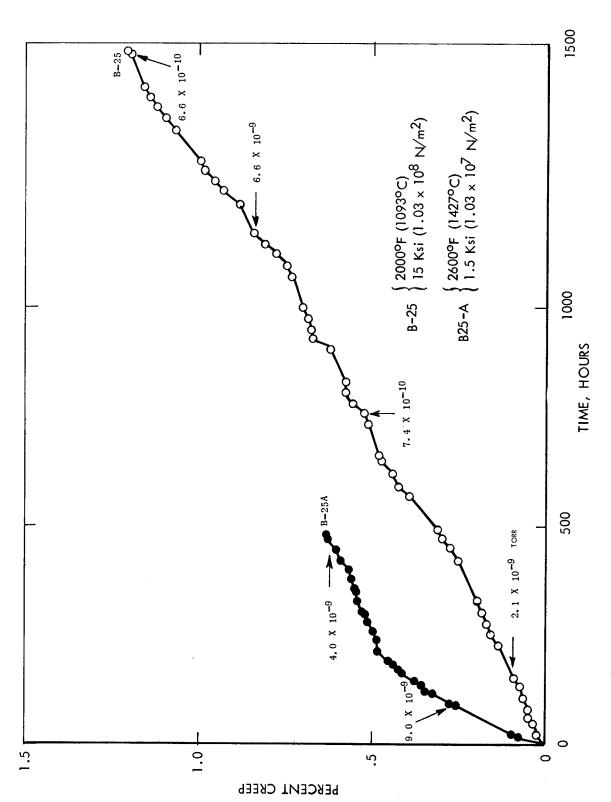
Tests S-25 and S-25A were made using the same specimen. Before each test the specimen was recrystallized at 3000°F (1649°C) for one hour. The creep data for all tests of Heat D-1670 are plotted in Figures 80, 81, and 82. While the test at 1800°F (982°C), Figure 81, exhibited a time dependent increase in creep rate, the other three did not. In fact both Test B-25A and B-28 at 2600°F (1427°C), Figures 80 and 82 respectively, showed a marked tendency for the creep rate to decrease with time.

# 5.. T-111 Heat D-1102

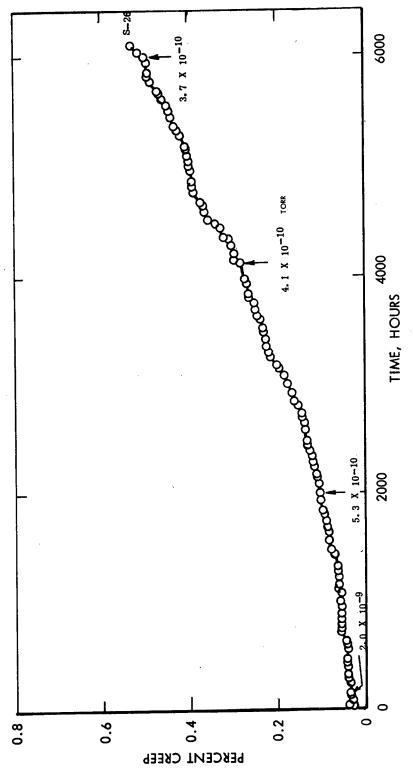
Two creep tests of specimens from Heat D-1102 were run and the creep data are plotted in Figure 83.

Specimen	Test Tem	perature	Str	ess
No.		<u>°C</u>	<u>ksi</u>	_N/m <sup>2</sup>
S- 27	2000	1093	13	$8.95 \times 10^{7}$
S- 32	2200	1204	5	$3.44 \times 10^{7}$

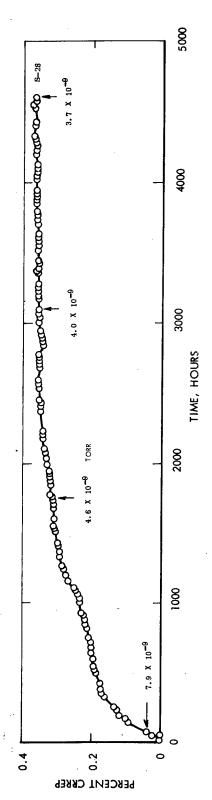
The test parameters used with specimens S-32 (Heat D-1102) and S-35 (Heat 65079) were identical, i.e.,  $2200\,^{\circ}\text{F}$  (1204°C) and 5 ksi (3.44 x  $10^7\text{N/m}^2$ ). A comparison of the creep data for these tests, Figures 78 and 83, shows that Heat 65079 had greater creep resistance.



CREEP DATA FOR 1-111 SHEET (HEAT D-1670) RECRYSTALLIZED ONE HOUR, 3000°F (1649°C). TESTED IN VACUUM ENVIRONMENT < 1  $\times$  10<sup>-8</sup> torr. FIGURE 80



CREEP DATA FOR T-111 SHEET (HEAT D-1670) RECRYSTALLIZED ONE HOUR , 3000°F (1649°C). TESTED AT 1800°F (982°C) AND 17 Ksi (1.17 ×  $10^8$  N/m²) IN VACUUM ENVIRONMENT <1 ×  $10^{-8}$  TORR. FIGURE 81



CREEP DATA FOR T-111 SHEET (HEAT D-1670) RECRYSTALLIZED ONE HOUR 3000°F (1649°C). TESTED AT 2600°F (1427°C) AND 0.5 Ksi (3.44  $\times$  106 N/m²) IN VACUUM ENVIRONMENT < 1  $\times$  10<sup>-8</sup> TORR. FIGURE 82

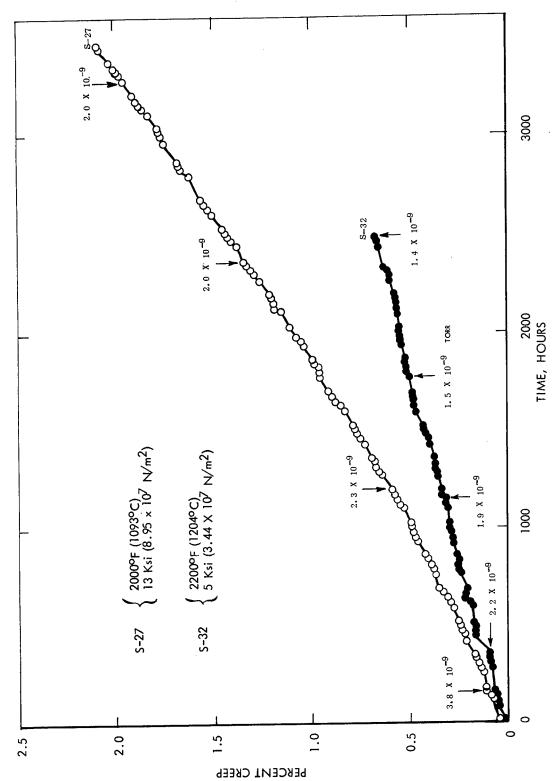


FIGURE 83 CREEP DATA FOR T-111 SHEET (HEAT 1102) RECRYSTALLIZED ONE HOUR AT 3000°F (1649°C). TESTED IN VACUUM ENVIRONMENT <1 X 10-8 TORR.

## 6. T-111 Heat MCN02A065

Two tests on specimens of T-111 from Heat MCN02A065 are now in progress and the creep data are shown in Figure 84. A comparison of test S-33 at 2200°F (1204°C) and 8 ksi (5.51 x  $10^7 N/m^2$ ) with test S-19 for Heat 70616 (see Figure 73) indicates that Heat MCN02A065 may be more creep resistant than Heat 70616.

A summary of the creep data from all heats of T-111 is given in Table 12. The data for tantalum-base T-222 are also included for comparative purposes. The constant of 11.1 used in computing the Larson-Miller parameters shown in Table 12 and plotted in Figure 85 was obtained by a computer fit of the data. In solving for constants for the Manson-Haferd parameters, four tests (S-21, S-22, S-23 and S-24) run at two different stresses were used. The constants determined from an exact solution of the parametric equation were then used to plot all the data shown in Figure 85. The results from tests S-16 and S-20 have not been plotted since the material was not recrystallized at 3000°F (1649°C). The results show that T-111 heats 70616 and MCN02A065 have creep strengths comparable to that of T-222 Heat AL-TA-43. The other heats of T-111 (Heats 65079, D-1670, and D-1102) exhibited a lower creep resistance. The results indicate the difference in creep strength which can occur between various heats of T-111 alloy with the same nominal composition.

## 7. <u>Astar 811C</u>

A single test of this alloy is now in progress at 2600°F (1427°C) and 2 ksi  $(1.38 \times 10^7 \text{ N/m}^2)$ . The creep data for the material recrystallized 1/2 hour at 3600°F (1982°C) are given in Figure 86. The extrapolated time to reach 1% creep of approximately 16,500 hours is indicative of a creep strength considerably greater than that of T-111 (see Figure 87).

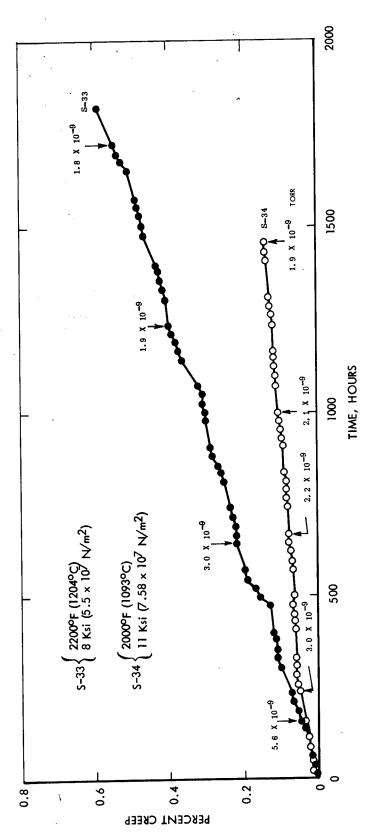
# E. Tungsten and Tungsten Alloys

#### 1. Arc-Melted Tungsten Heat KC-1357

Five tests were made with arc-melted tungsten sheet recrystallized for one hour at the test temperature.

Specimen	Test Tem	perature	Str	ess
No.	<u>°F</u>	<u>°C</u>	ksi	N/m <sup>2</sup>
S-5	3200	1760	3	$2.07 \times 10^{7}$
S-7	3200	1760	0.4	$2.76 \times 10^6$
S-9	3200	1760	1	$6.89 \times 10^{6}$
S-17	2800	1538	4	$2.76 \times 10^{7}$
S-18	2800	1538	3	$2.07 \times 10^{7}$

The creep data for these tests are given in Figure 88.



CREEP DATA FOR T-111 SHEET (HEAT MCN 02A065) RECRYSTALLIZED ONE HOUR AT 30009F (1649°C). TESTED IN VACUUM ENVIRONMENT < 1  $\times$  10-8 TORR. FIGURE 84

TABLE 12

Summary of Creep Data for Tantalum-Base T-111 and T-222 Alloys, Recrystallized 3000°F (1649°C), 1 Hour

Larson-Miller Parameter T(*R)(11.1+logt) x 10 <sup>-3</sup>	,	38.4	37.6	34.2	37.6	34.2		40.1	39.7	39.6		35.0	43.3	34.0	46,4		35.4	39.2		38.7	37.2		37.0	35, 3	
Creep Rate in-in-l-hr-	$1.4 \times 10^{-5}$	$5.0 \times 10^{-6}$	$8.8 \times 10^{-6}$	$1.7 \times 10^{-5}$	$3.2 \times 10^{-6}$	$2.1 \times 10^{-6}$	•	$1.2 \times 10^{-5}$	$1.8 \times 10^{-6}$	$2.2 \times 10^{-6}$	,	$7.5 \times 10^{-6}$	$9.1 \times 10^{-6}$	$1.2 \times 10^{-6}$	$1.1 \times 10^{-1}$	•	$5.3 \times 10^{-6}$	$2.6 \times 10^{-6}$	,	3.3 × 10 <sup>-6</sup>	$7.8 \times 10^{-7}$	1	$1.6 \times 10^{-5}$	$1.1 \times 10^{-5}$	$2.4 \times 10^{-5}$
Manson-Haferd Parameter 1% Creep log t - 17.5 x 103 T + 417	-5.60	-5,43	-5.53	-6.08	-5.53	-6.08		-5.18	-5.26	-5.30		-5.95	-4.80	-6.13	-4.15		-5.90	-5,33		-5.37	-5.55		-5.63	-5.89	-5.92
Hours to	700	2,000	1,140	670	3,150	4,730		860	2,600*	4,500*		1,340	1,100*	8,400*	\$6,000		1,880	3,800*		3,000*	12,300*		620	006	420
Stress ksi N/m²	8 5.15 × 10 <sup>7</sup>		$8.26 \times 10^7$		12 8.26 × 10,		1	$3.5  2.41 \times 10^{7}$	$5   3.44 \times 10^{7}$	$5   3.44 \times 10^7$	•	$1.03 \times 10^{8}$		$17   1.17 \times 10^8$	$0.5  3.44 \times 10^6$	•	3 8.95 x 10 <sup>7</sup>	$5   3.44 \times 10^7$		$8   5.51 \times 10^{7}$	1 $7.58 \times 10^7$	1	12 8.26 × 10 <sup>7</sup>	7	12 8.26 × 10 <sup>7</sup>
Test Temperature	1204			1093 2				1316	1204			1093		982			1093	1204		1204	1093		1204	1124	
Test Te	2200	2200	2200	2000	2120	1860		2400	2200			2000	2600	1800	2600		2000	2200	A065	2200	2000	-43	2200	2056	2200
Specimen No.	T-111 Heat 70616 S-16 (1)	S-19	S-21	S-22	S-23	S-24	T-111 Heat 65079	5-30 (2)	S-31 (2)	S-35	T-111 Heat D-1670	S-25	S-25A	S-26	S-28	T-111 Heat D-1102	S-27	S-32	T-111 Heat MCN02A065	S-33	S-34	T-222 Heat AL-TA-43	S-13	S-14	S-20 (3)

\* Extrapolated Value; (1) - Recrystallized one hour 2600°F (1427°C) (2) - Specimen Axis perpendicular to rolling direction (3) - Recrystallized one hour 2800°F (1538°C).

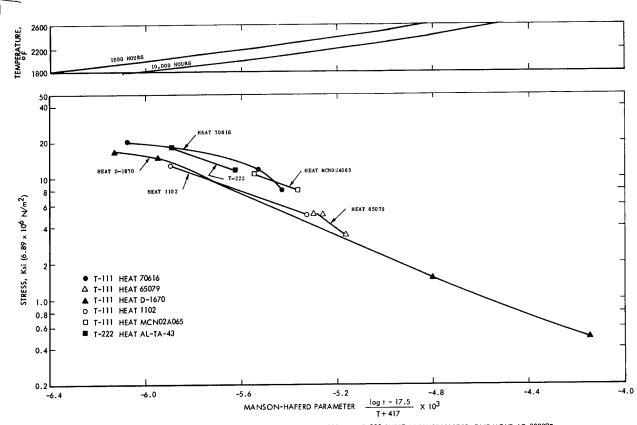


FIGURE 85A PARAMETRIC PLOT OF 1% CREEP DATA FOR T-111 AND T-222 SHEET RECRYSTALLIZED ONE HOUR AT 3000°F (1649°C). TESTED IN VACUUM ENVIRONMENT  $<1\times10^{-8}$  TORR.

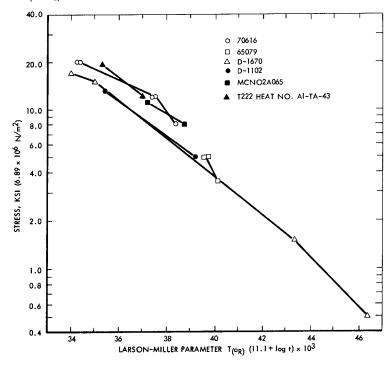
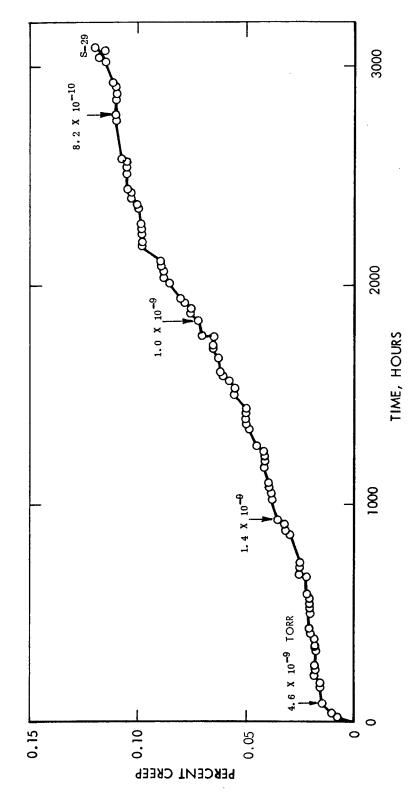
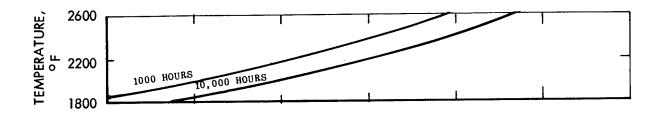


FIGURE 85B PARAMETRIC PLOT OF 1% CREEP DATA FOR T-111 AND T-222 RECRYSTALLIZED ONE HOUR AT 3000°F (1649°C). TESTED IN VACUUM ENVIRONMENT < 1 x 10-8 TORR.



CREEP DATA FOR ASTAR 811C SHEET RECRYSTALLIZED ONE-HALF HOUR AT 3600°F (1982°C). TESTED AT 2600°F (1427°C) AND 2 Ksi (1.38  $\times$  10<sup>7</sup> N/m²) IN VACUUM ENVIRONMENT <1  $\times$  10<sup>-8</sup> TORR. FIGURE 86



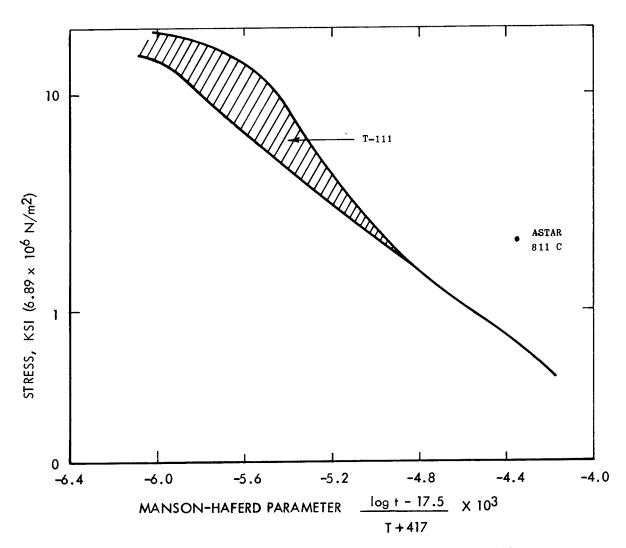


FIGURE 87 PARAMETRIC PLOT OF 1% CREEP DATA FOR ASTAR 811C SHEET RECRYSTALLIZED ONE-HALF HOUR AT 3600°F (1982°C). TESTED IN VACUUM ENVIRONMENT<1 X 10-8 TORR.

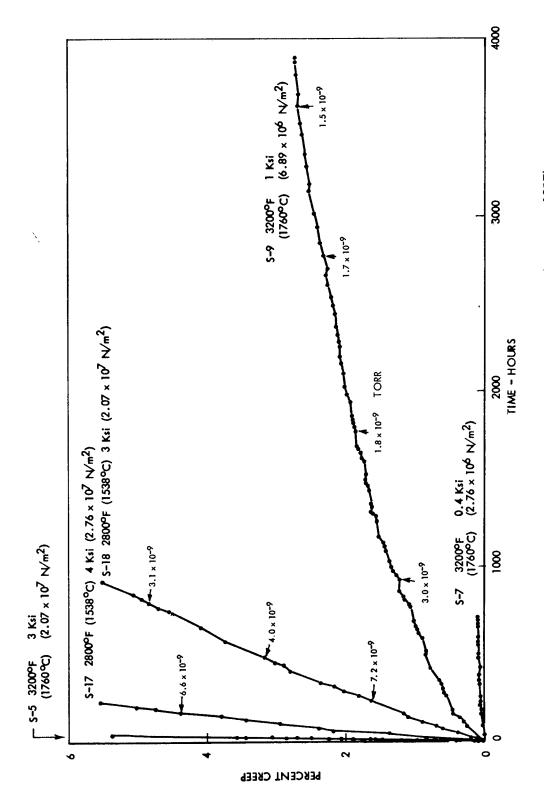


FIGURE 88 CREEP DATA FOR ARC MELTED TUNGSTEN SHEET (HEAT KC-1357) RECRYSTALLIZED 1 HOUR AT TEST TEMPERATURE. TESTED IN VACUUM ENVIRONMENT < 1  $\times$  10<sup>-8</sup> Torr.

Post-test examination showed that grain growth was a dominant feature for test S-9 shown in Figure 89. Visual examination indicated that some grains had completely transversed the 0.030 inch thick specimen. Examination of the thermally etched specimen surface failed to show evidence of creep occurring by grain boundary sliding but grain boundary migration associated with grain growth was observed as shown by Figure 90.

#### 2. Vapor Deposited Tungsten

Two vapor-deposited tungsten specimens were tested and the creep data are plotted in Figure 91. Post-test photomicrographs of vapor-deposited tungsten specimen B-24 are shown in Figure 92. This specimen was tested at  $2800\,^{\circ}\mathrm{F}$  (1538°C) and 2 ksi (1.38 x  $10^{7}\mathrm{N/m^2}$ ) for 6812 hours. During that time, 3.71% extension occurred. The unstressed end of the specimen exhibited columnar grains characteristic of the vapor-deposited material. The stressed gauge section had a similar structure and in addition showed grain boundary porosity probably due to vacancy condensation during test.

A longitudinal section of specimen B-17 taken from the gage area exhibited fine grains alone one edge, Figure 93. Presumably this was the interface between the forming mandral and the tungsten. This large variation of grain size is an intrinsic characteristic of the vapor deposition process, and will be present in the creep specimen to varying degrees depending on how the sample blanks are cut from the as-deposited material. Porosity was apparent, and the grains were equiaxed rather than columnar. The hardness of the vapordeposited tungsten after test was 413 DPH, identical to arc-melted tungsten recyrstallized at 3200°F (1760°C).

### 3. Arc-Melted Tungsten-25% Rhenium, Heat 3.5-75002

Four tests were made with the tungsten-rhenium alloy in the recrystallized condition and the creep data are presented in Figure 94.

Specimen	Test Tem	perature	Stress				
No.	°F	°C	ksi	N/m <sup>2</sup>			
S-3	3200	1760	5	$3.44 \times 10^{7}$			
S-4	3200	1760	3	$2.07 \times 10^{7}$			
S-6	3200	1760	0.5	$3.44 \times 10^{6}$			
S-8	3200	1760	1.5	$1.03 \times 10'$			

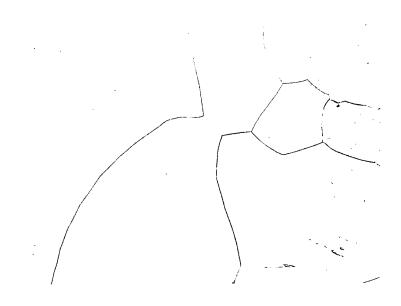


FIGURE 89 GRAIN GROWTH IN ARC MELTED TUNGSTEN CREEP SPECIMEN S-9 TESTED 3886 HOURS AT 3200°F (1670°C).
ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O. 100 X

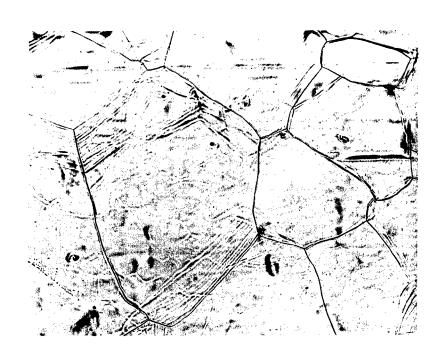
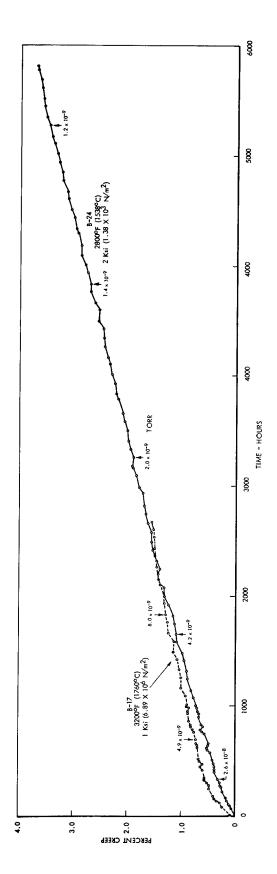
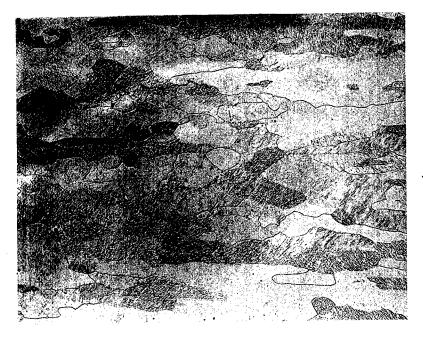


FIGURE 90 ARC-MELTED TUNGSTEN SHEET SPECIMEN S-7 TESTED 720 HOURS AT 3200°F (1670°C) SHOWING GRAIN BOUNDARY MIGRATION. THERMALLY ETCHED DURING TESTING. 100 X

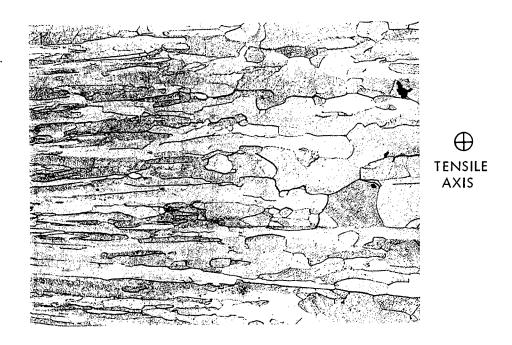


CREEP DATA FOR VAPOR-DEPOSITED TUNGSTEN. TESTED IN VACUUM ENVIRONMENT < 1 x 10<sup>-8</sup> TORR. FIGURE 91



TENSILE AXIS

GAGE SECTION PERPENDICULAR TO SPECIMEN AXIS



HEAD SECTION PERPENDICULAR TO SPECIMEN AXIS

FIGURE 92 VAPOR DEPOSITED TUNGSTEN MICROSTRUCTURE AFTER TEST. ETCHANT: MURAKAMI'S. 100 X

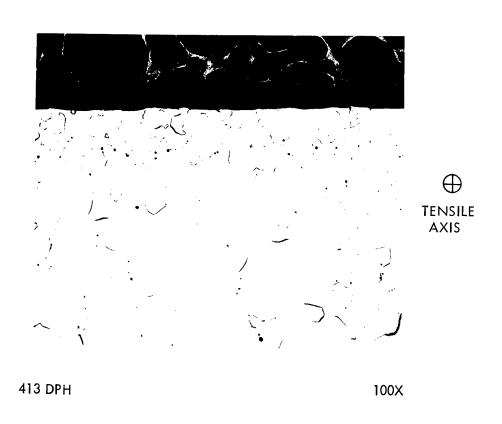
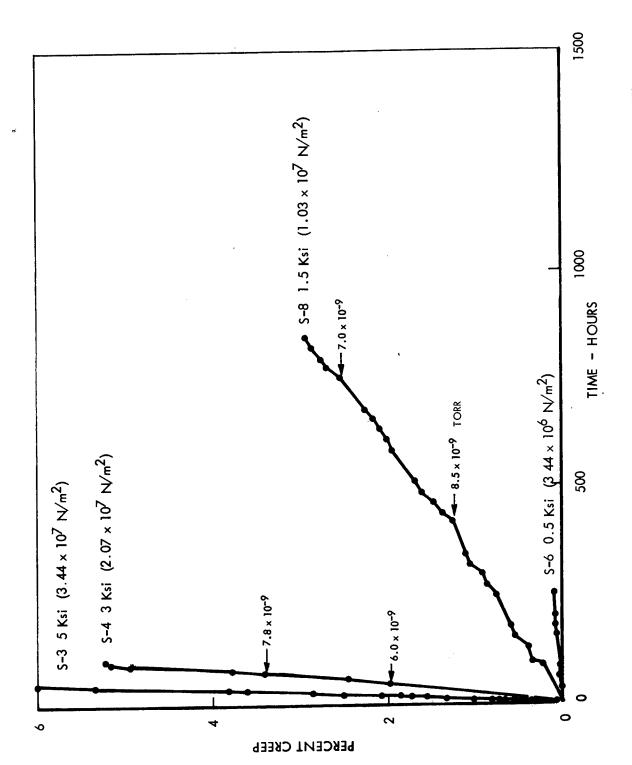


FIGURE 93 VAPOR DEPOSITED TUNGSTEN, CREEP TESTED 2863 HOURS AT 3200°F (1760°C) AND 1000 PSI (6.89  $\times$  106 N/m²), UNETCHED



CREEP DATA FOR ARC MELTED TUNGSTEN – 25% RHENIUM SHEET (HEAT 3.5 – 75002) RECRYSTALLIZED 1 HOUR AT 3200 F (1760 C). TESTED AT  $3200^\circ$ F (1760°C) IN VACUUM ENVIRONMENT < 1 X  $10^{-8}$  TORR. FIGURE 94

Post-test examination of the thermally etched surface of specimen S-4, Figure 95, showed that grain boundary migration had occurred just as with pure tungsten. Comparison of the grain size of specimens S-7 and S-8 revealed a considerable difference despite the similarity of the test time and temperature. If grain boundary migration contributes to creep it would appear that the contribution of the rhenium addition is in restricting grain growth.

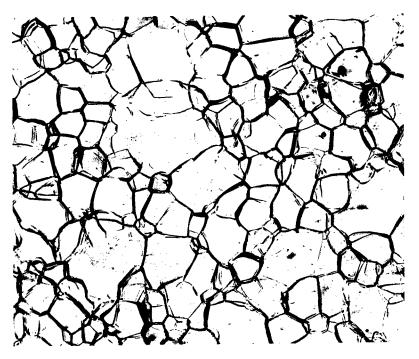
#### 4. Sylvania A

Two tests at 3200°F (1760°C) were made with the Sylvania A in the recrystallized condition and the creep data are presented in Figure 96.

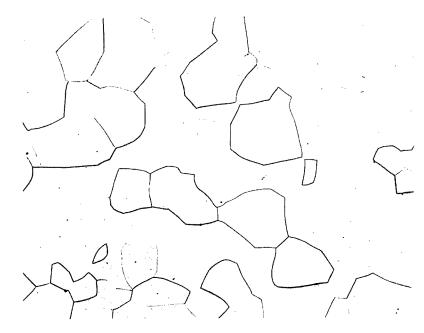
Post-test examination of specimen S-12 revealed a fine-grained microstructure, Figure 97. The second phase observed at 500X was probably responsible in part for the grain boundary pinning and consequent smaller grain size as compared to tungsten or tungsten-25% rhenium materials.

A summary of all creep data for fungsten, fungsten-25% rhenium, and Sylvania A is given in Table 13. The Larson-Miller values for 1% creep in the table are based on a constant of 15. Other results, plotted in Figure 98, show that arc-melted and vapor deposited tungsten have comparable creep strength. The tungsten-25% rhenium alloy had a greater creep strength only at the higher stress levels. While Sylvania A had a superior creep strength to both tungsten and tungsten-25% rhenium, the tendency for Sylvania A to be brittle offsets the higher creep strength.

The results obtained on the arc-melted and vapor-deposited tungsten were compared in Figure 99 to published creep data for pure tungsten (15, 16) using a Larson-Miller parameter for 1% creep. The results of Schmidt and Ogden (15) were obtained with a powder metallurgy product and tests were performed in an argon environment. A powder metallurgy product was also used by the SRI (16), but the test environment was a 10-4 torr vaccuum. The creep strength of the arc-melted and vapor-deposited tungsten is definitely inferior to that of the powder metallurgy product of Reference (15), however, the data from Reference (16) appear to be an extension of that obtained with the arc-melted and vapor-deposited material. In view of the fact that References (15) and (16) do not provide quantitative data relative to interstitial content of the material before or after test, the specific causes for the difference observed cannot be determined. However, it is interesting to note that the tests in argon produced higher creep strengths than the tests conducted in vacuum.

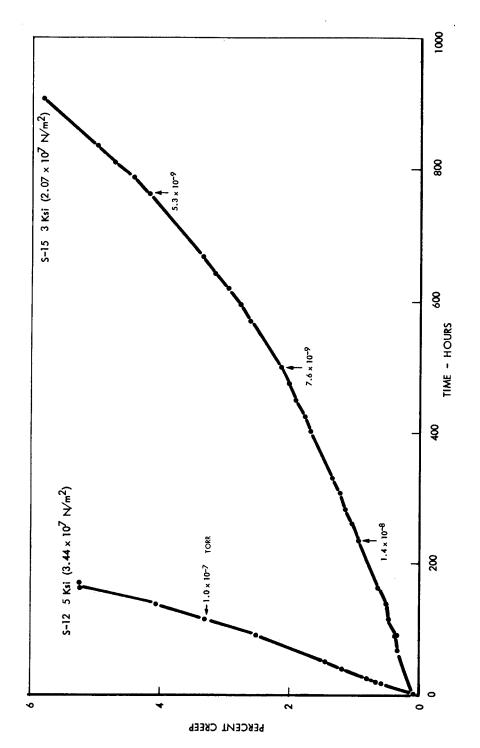


S-4 3 Ksi  $(2.07 \times 10^7 \text{ N/m}^2)$  THERMALLY ETCHED

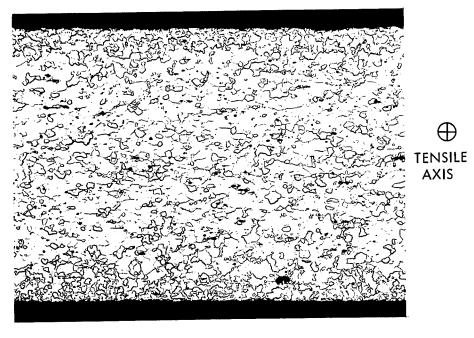


S-8 1.5 Ksi  $(1.03 \times 10^7 \text{ N/m}^2)$  ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O

FIGURE 95 TUNGSTEN - 25% RHENIUM ALLOY AFTER CREEP TESTING AT 3200 F (1760 C) IN VACUUM ENVIRONMENT < 1 X 10<sup>-8</sup> TORR. 100 X



CREEP DATA FOR SYLVANIA-A ALLOY SHEET RECRYSTALLIZED 1 HOUR AT 3200°F (1760°C). TESTED AT 3200°F (1760°C) IN VACUUM ENVIRONMENT < 1 x 10<sup>-8</sup> TORR. FIGURE 96



CROSS-SECTION 100 X

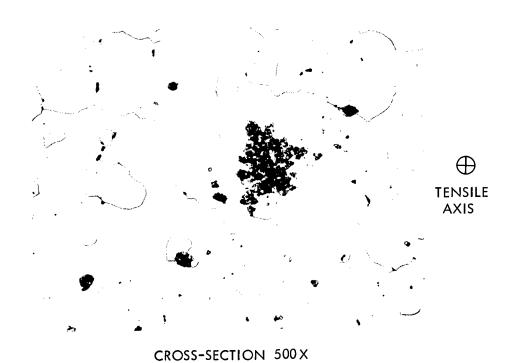


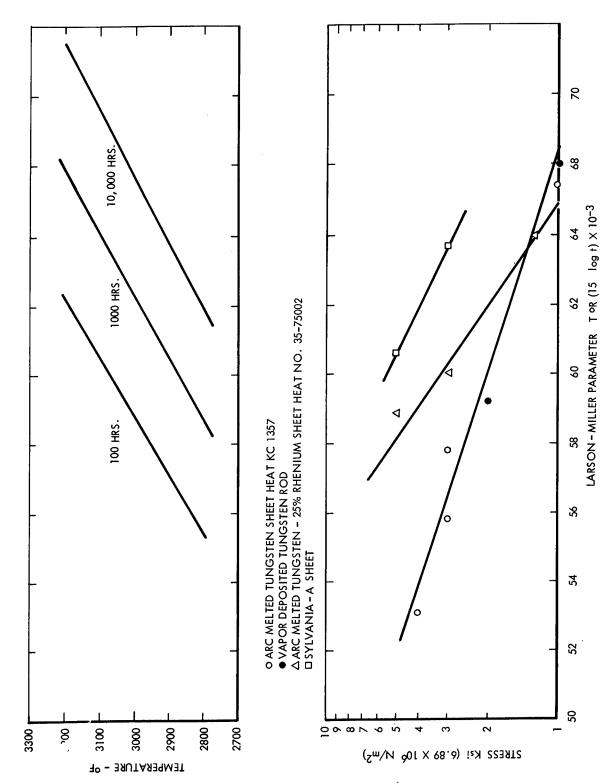
FIGURE 97 GAUGE SECTION SYLVANIA-A ALLOY SHEET AFTER TESTING 170 HOURS AT 3200°F (1760°C) AND 5 Ksi  $(3.44\times10^7~\text{N/m}^2)$  IN VACUUM ENVIRONMENT < 1 X 10<sup>-8</sup> TORR. ETCHANT: 15% HF, 15% H<sub>2</sub>SO<sub>4</sub>, 8% HNO<sub>3</sub>, 62% H<sub>2</sub>O.

TABLE 13

Summary of Creep Data for Tungsten and Tungsten-Base Alloys

Creep Rate in-in-1-hr-1	1	$1.7 \times 10^{\circ}$	$1.7 \times 10^{-6}$	$1.5 \times 10^{-5}$	$5.0 \times 10^{-4}$	$8.0 \times 10^{-5}$	`	$8.8 \times 10^{-6}$	$6.7 \times 10^{-6}$	•	$8.3 \times 10^{-4}$	$4.0 \times 10^{-4}$	$3.6 \times 10^{-6}$	$3.2 \times 10^{-5}$	•	$2.9 \times 10^{-\frac{4}{5}}$	$4.0 \times 10^{-3}$	
Larson-Miller Parameter 1% Creep T°R (15 + log t)x 10-3		5.7.8	*	65.4	5.3. 1	55.8		66.0	59. 2		58.9	60.0	*	64.0		9.09	63.7	
Hours to 1% Creep	,	9	*	675	20	125		1140	1500		12	25	*	315		35	250	
sss N/m <sup>2</sup>	7	$2.07 \times 10'$	$2.76 \times 10^{6}$	$6.89 \times 10^{6}$	$2.76 \times 10^{7}$	$2.07 \times 10^{7}$		$6.89 \times 10^{6}$	1.38 × 10'		$3.44 \times 10'$	$2.07 \times 10^{7}$	$3.44 \times 10^{6}$	$1.03 \times 10^{7}$	1	$3.44 \times 10^{\prime}$	2.07 × 10'	
Stress		3	0.4	_	4	3		7	7	t 3.5-75002	5	3	0.5	1.5		J.	3	
Test Temperature		1760	1760	1760	1538	1538	ungsten	1760	1538	nium Heat 3	1760	1760	1760	1760		1760	1760	
Test Ter	Tungsten Heat KC-1357	3200	3200	3200	2800	2800	Vapor Deposited Tungsten	3200	2800	Tungsten-25% Rhenium Hea	3200	3200	3200	3200	а А	3200	3200	
Spec.	Tungste	S-5	S-7	S-9	S-17	S-18	Vapor 1	B-17	B-24	Tungst	S-3	S-4	9-S	S-8	Sylvania	S-12	S-15	

\* Too little creep to extrapolate



LARSON-MILLER PLOT OF 1% CREEP DATA FOR TUNGSTEN AND TUNGSTEN BASE ALLOYS. TESTED IN VACUUM ENVIRONMENT < 1 x 10-8 torr. FIGURE 98

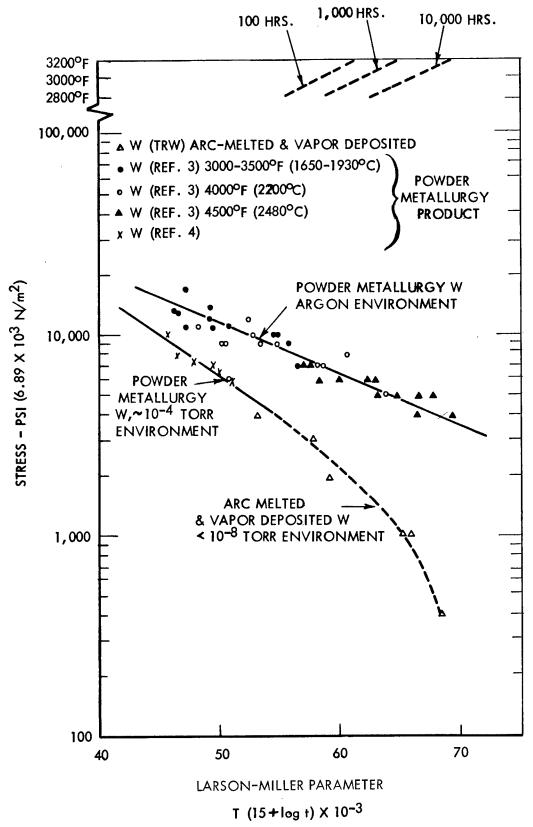


FIGURE 99 LARSON-MILLER PLOT OF TUNGSTEN 1% CREEP DATA.

#### F. Comparison of Various Refractory Alloys

The creep properties of the various classes of materials are compared in Figures 100 and 101. In Figure 100a the potential turbine alloys are presented on a Larson-Miller plot of 0.5% creep using a constant of 20.1.

The results show that molybdenum-base TZC and TZM alloys have creep strengths superior to Cb-132M. However, comparison of these alloys on the basis of strength-to-weight ratios (Figure 100b) tends to minimize this difference. Figure 100 also indicates that molybdenum-base TZM Heat KDTZM-1175 was more creep resistant than TZC Heat M-91.

Four possible cladding materials are compared in Figure 101; tantalumbase T-111, Astar 811C, tungsten and tungsten-25% rhenium. The parametric comparison for 1% creep, shown in Figure 101, is based on the Manson-Haferd constants previously used for tantalum-base T-111 alloy.

Both tungsten and tungsten-25% rhenium are more creep resistant that T-111. The extrapolated data for a single test of the tantalum-base alloy Astar 811C indicates that at 2600°F (1427°C) the creep properties are comparable to tungsten. Although a comparison of these alloys on the basis of strength-to-weight ratios (Figure 101b) tends to minimize the difference between the tungsten and the tantalum alloys, the tungsten base materials still exhibit superior creep resistance.

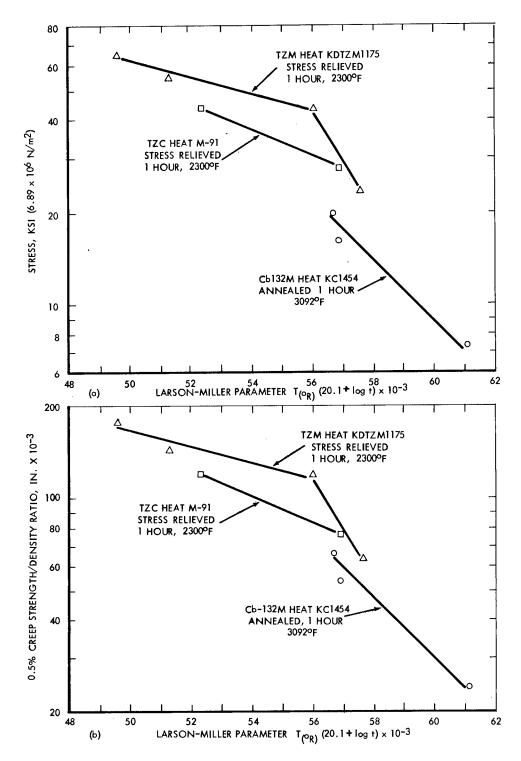


FIGURE 100 PARAMETRIC COMPARISON OF TZM FORGED DISK WITH TZC PLATE AND Cb 132M PLATE; a) 0.5% CREEP STRENGTH, b) 0.5% CREEP STRENGTH-TO-DENSITY RATIO.

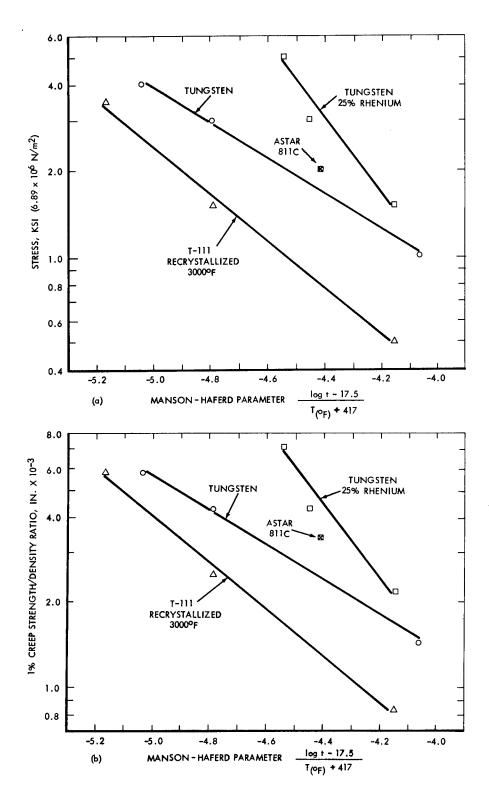


FIGURE 101 PARAMETRIC COMPARISON OF ASTAR 811C, ARC MELTED TUNGSTEN, TUNGSTEN - 25% RHENIUM AND T-111 SHEET; a) 1% CREEP STRENGTH, b) 1% CREEP STRENGTH-TO-DENSITY RATIO.

#### VI SUMMARY AND CONCLUSIONS

Creep tests were conducted with the purpose of defining design properties for refractory metal alloys for times to 10,000 hours in a vacuum environment of less than  $1 \times 10^{-8}$  torr. The specific application would ultimately involve space electric power systems. The tests were performed in specially designed creep units which included methods for accurate temperature and extension measurements.

The following classes of alloys were evaluated in the program:

- 1. Columbium-base (AS-30, Cb132M),
- 2. Molybdenum-base (TZC, TZM, Cb-modified TZM),
- 3. Tantalum-base (T-111, T-222, Astar 811C), and
- 4. Tungsten-base (W, W-25Re, Sylvania A)

Considering the columbium and molybdenum-base materials as representing potential turbine alloys, the stress-relieved TZM and TZC possess the best creep resistance. Typical values indicated that 0.5% creep would be attained at 2000°F (1093°C) in 10,000 hours at a 20 ksi (1.38 x  $10^8 N/m^2$ ) stress level.

A large number of creep tests were performed with the T-111 alloy which is a potential tubing material. Several heats were used to provide an indication of the inherent variability for materials with the same nominal composition. Although the data are limited, the Astar 811C showed the best creep resistance of the tantalum-base alloys.

The creep strengths of arc-melted and vapor-deposited tungsten were similar at 2800°F (1538°C). The tungsten-25% rhenium was superior to the arc-melted tungsten only at the lower stress values (longer test times). Sylvania A had the best creep resistance of the tungsten-base materials; however, the alloy was extremely brittle. Extensive post-test evaluations were made of the materials to define significant property or chemistry changes The tests indicated that prolonged heating in a vacuum environment of <1 x 10<sup>-8</sup> torr does not produce any significant interstitial contamination.

Jan. 1. 1.

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### APPENDIX I

## Processing History of Test Materials

Table No.	Processing History Of:					
II I	Columbium-Base AS-30 C5 Cb-132M KC1454 Molybdenum-Base					
Ш	TZC M-80					
IV	TZC M-91					
V	TZC 4345					
VI	TZM Disc 7502					
VII	TZM Disc KDTZM-1175					
VIII	TZM Bar 7463					
IX	Columbium-Modified TZM 4305-4					
	Tantalum-Base					
X	T-111 70616					
XI	T-111 65079					
XII	T-222 AL-TA-43					
XIII	T-222 Ta-43-SF-2					
	Tungsten-Base					
XIV	Arc-Melted Tungsten KC1357					
XV	Tungsten-25% Rhenium 3.5-75002					
XVI	Sylvania A					

#### TABLE I

## PROCESSING HISTORY OF AS-30 PLATE Heat C5

### Processing History:

- 1. Vacuum arc melt ingot 5.4" diameter.
- 2. Machine to 4.8" diameter.
- 3. Jacket in molybdenum.
- 4. Extrude 3.25:1 ratio at  $2825^{\circ}F$  (1552°C) to  $4^{\circ}$  x  $1.625^{\circ}$  sheet-bar.
- 5. Cross-roll at 2100°F (1149°C) to 0.790 $^{\prime\prime}$ , argon atmosphere.
- 6. Acid etch to remove molybdenum jacket.
- 7. Abrasive saw to final width and length.

### <u>Hardness:</u>

293 DPH (29Rc)

#### TABLE II

### PROCESSING HISTORY OF Cb-132M PLATE

Heat KC1454

#### Processing History:

- Electron-beam melt, electrode diameter 2-1/2", mold size 3-7/8"
- 2. Vacuum arc melt, then can in Mo-0.5Ti.
- 3. Extrude at 3130°F (1721°C) to 1-1/211 diameter.
- 4. Cross-roll from 2400°F (1316°C) in three passes yielding reductions of 20, 10, and 10%. Reheat between each pass. Final thickness 3/4".
- 5. Remove jacket, ship in as-rolled condition.

#### Hardness:

336 DPH (34 Rc)

#### TABLE III

## PROCESSING HISTORY OF TZC PLATE Heat M-80

#### Processing History:

- 1. Vacuum arc melt ingot 5.88" diameter.
- 2. Machine to 5" diameter.
- 3. Extrude 2.30:1 ratio at  $3092^{\circ}F$  (1700°C) to  $4-1/8'' \times 2.22''$  plate.
- 4. Cross-roll on small mill (12" diameter) at 2925°F (1585°C) in 4-1/8" direction to 0.740", hydrogen atmosphere, 4% reduction per pass.
- 5. Grit blast and cut to final length with abrasive saw.

#### Hardness:

308 DPH (29 Rc)

#### TABLE IV

## PROCESSING HISTORY OF TZC PLATE Heat M-91

#### Processing History:

- 1. Vacuum arc melt ingot 5.88" diameter.
- 2. Machine to 5" diameter.
- 3. Extrude 2.30:1 at  $3092^{\circ}F$  (1700°C) to  $4-1/8'' \times 2.22''$  plate.
- 4. Cross-roll on large mill (28" diameter) to produce relatively large degree of deformation per pass and a finishing temperature as low as 2372°F (1300°C).
- Grit blast and cut to final length with abrasive saw.

#### Hardness:

335 DPH (34 Rc)

#### TABLE V

# PROCESSING HISTORY OF TZC PLATE Heat 4345

#### **Processing History:**

- 1. Machine vacuum arc melted ingot to 5.85" diameter.
- 2. Extrude to 3" diameter.
- 3. Heat treat in vacuum 3000°F (1649°C).
- 4. Machine to 2.4 2.811 diameter.
- 5. Upset forge 40% at 2400°F (1316°C).
- 6. Broad forge to 0.825" at 2400°F (1316°C).
- 7. Heat treat in vacuum 2400°F (1316°C), 1 hour.
- 8. Machine to 0.70".

#### Hardness:

319-373 DPH (28-36 Rc)

#### TABLE VI

#### PROCESSING HISTORY OF TZM FORGED DISC Heat 7502

#### Processing History:

- 1. Vacuum arc melt ingot 11-1/2" diameter.
- 2. Machine to 10-3/4" diameter.
- 3. Extrude to 6-1/4" diameter.
- 4. Heat treat at 2700°F (1482°C).
- 5. Upset forge at  $2200^{\circ}F$  ( $1204^{\circ}C$ ).
- 6. Stress relieve at 2200°F (1204°C).

#### Hardness:

266-342 DPH (25-35 Rc)

#### TABLE VII

#### PROCESSING HISTORY OF TZM FORGED DISC Heat KDTZM-1175

#### **Processing History:**

- 1. 11-3/4" diameter ingot, machine to 10-3/4" diameter.
- 2. Extrude to  $6-1/2^{11}$  diameter at  $2250^{\circ}$ F ( $1232^{\circ}$ C).
- 3. Recrystallize at 2800°F (1538°C) for 4 hours.
- 4. Forge to  $4^{\prime\prime}$  diameter billet  $3400^{\circ}$ F to  $2800^{\circ}$ F (1871 to 1538°C).
- 5. Recrystallize at 2950°F (1621°C) for 2 hours.
- 6. Forge to flat disc 3/4" thick, 2800°F (1538°C) starting temperature 11 blows, finish temperature 2160°F (1182°C).
- 7. Stress relieve at 2300°F (1260°C) for 1 hour.

#### Hardness:

297-335 DPH (29-34 Rc)

#### TABLE VIII

# PROCESSING HISTORY OF TZM BAR Heat 7463

#### Processing History:

- 1. Extrude 11-1/2" diameter ingots to 6-7" diameter.
- 2. Recrystallize.
- 3. Roll to 2" diameter.
- 4. Recrystallize
- 5. Roll to l" diameter.
- 6. Swage to 5/8" diameter (75-85% cold work).
- 7. Stress relieve 2250°F (1232°C), 1/2 hour.

#### <u>Hardness</u>:

300-330 DPH (30-34 Rc)

#### TABLE IX

# PROCESSING HISTORY OF COLUMBIUM-MODIFIED TZM Heat 4305-4

#### **Processing History:**

- 1. 3-1/8" diameter machine casting.
- 2. Extrude to 1-3/8" diameter.
- 3. Recrystallize.
- 4. Swage to 5/8" diameter
- 5. Stress relieve 2500°F (1371°C), 1 hour.

#### Hardness:

278 DPH (27 Rc)

#### TABLE X

## PROCESSING HISTORY OF T-111 SHEET Heat 70616

#### Processing History:

- 1. Electron beam melt.
- 2. Arc-cast 5-1/2" ingot.
- 3. Forge to 1-1/2" thick sheet bar 2200°F (1204°C).
- 4. Vacuum anneal 2400°F (1316°C).
- 5. Warm roll 800°F (427°C) to 200 mil thick.
- 6. Vacuum anneal 2400°F (1216°C).
- 7. Cold roll to final thickness.
- 8. Vacuum anneal 2400°F (1316°C).

#### Hardness:

216-368 DPH (95  $R_B - 37 Rc$ )

#### TABLE XI

# PROCESSING HISTORY OF T-111 SHEET Heat 65079

#### Processing History:

- 1. Forge 6-1/2" diameter arc-melted ingot to 1-1/2" sheet bar at 2200°F (1204°C).
- 2. Vacuum anneal 2800°F (1538°C).
- 3. Warm roll 800°F (427°C) to 1/4" thick.
- 4. Vacuum anneal 2800°F (1538°C).
- 5. Cold roll to final thickness.
- 6. Vacuum anneal (1 x 10<sup>-4</sup> torr) 2800°F (1538°C), 1 hour.

#### **Hardness:**

236 DPH (20 Rc)

#### TABLE XII

## PROCESSING HISTORY OF T-222 SHEET Heat A1-Ta-43

#### Processing History:

- 1. Ingot 4-1/2'' diameter x 4-1/2'' long.
- 2. Side forge to 1-1/2" thick (final forging 1-1/2"  $\times$  4-1/2"  $\times$  5-1/2").
- 3. Roll to 5-1/2" direction to 0.700" thick.
- 4. Cut to 0.700" x 4" x 9" size, final rolling direction parallel to 9 " dimension.
- 5. Roll to 0.030" thickness.

#### Hardness:

405 DPH (41 Rc)

#### TABLE XIII

# PROCESSING HISOTRY OF T-222 SHEET Heat Ta-43-SF-2

#### Processing History:

- 1. Double consumable arc melt  $4^{\prime\prime}$  diameter x  $8^{\prime\prime}$  ingot.
- 2. Condition.
- 3. Dynapak broad forge to 1-5/8" thick.
- 4. Vacuum anneal 2750°F (1510°C), 2 hours.
- 5. Roll to 0.300" thick.
- 6. Vacuum anneal 2750°F (1510°C), 2 hours.
- 7. Cross-roll to 0.100" thick.
- 8. Vacuum anneal 2750°F (1510°C), 1 hour.
- 9. Roll to 0.060" thick.
- 10. Stress-relieve 2300°F (1260°C), 1 hour.
- 11. Finish roll to 0.040" thick.

#### Hardness:

339 DPH (34 Rc)

#### TABLE XIV

## PROCESSING HISTORY OF TUNGSTEN SHEET Heat KC1357

### Processing History:

- 1. Extrude 4:1 ratio 3100°F (1705°C) TRW Inc.
- 2. Forge open die 2200°F (1204°C).
- 3. Roll
  - a) Initial 2300°F (1260°C)
  - b) Intermediate 1800°F (982°C)
  - c) Final 1400°F (760°C)
- 4. Stress-relieve 1700°F (927°C).

#### **Hardness**:

487 DPH (48 Rc)

#### TABLE XV

# PROCESSING HISTORY FOR TUNGSTEN-25% RHENIUM SHEET Heat 3.5-75002

### Processing History:

- 1. Stress relieve 0.055" sheet 1 hour 2375°F (1301°C).
- 2. Roll to 0.035".
- 3. Stress-relieve
  - a) Small sheet 2375°F (1301°C).
  - b) Large sheet 2550°F (1399°C).

### <u>Hardness:</u>

639 DPH

#### TABLE XVI

#### PROCESSING HISTORY OF SYLVANIA "A" SHEET

#### Processing History:

- 1. Rolling slabs were made by isostatically pressing powder.
- 2. Roll slabs at 2732-3452°F (1500-1900°C) to 0.032". Total reduction 90%.
- Intermediate annealing none.
- 4. Final stress relief five minutes at 2732°F (1500°C).
- 5. Trim sheet with abrasive saw and chemically clean.

#### Hardness:

579 DPH (54 Rc)

#### APPENDIX II

#### Chemical Analysis

#### Original Material

Table I - Columbium-Base AS-30 and Cb-132M

Table II - TZC

Table III - TZM and Cb Modified TZM

Table IV - T-111
Table V - T-222

Table VI - Tungsten, Tungsten-25% Rhenium, and

Sylvania A

#### Post-Test Analysis

Table VII - Columbium-Base AS-30 and Cb-132M

Table VIII - Molybdenum-Base TZC
Table IX - Molybdenum-Base TZM

Table X - Tantalum-Base T-111

Table XI - Tungsten

Table XII - Tungsten-25% Rhenium

TABLE I
Columbium-Base

	Percent		
•	AS-30	Cb-132M	
Element	Heat C5	Heat KC1454	
С	0.09	0. 16	
Сь	Balance	Balance	
Со	0.010	0.010	
Cu	0.010	0.010	
Fe	0.010	0.010	
H <sub>2</sub>	0.0015	0.0004	
Mn	0.010	0.010	
Мo	0.020	4.72	
$N_2$	0.010	0.0024	
Ni	0.020	0.020	
O <sub>2</sub> Pb	0.0060	0.0004	
Рб	0.005	0.001	
Si	0.020	0.0015	
Ta	-	19. 7	
Ti .	0.030	0.010	
V	0.015	0.015	
W	21.0	15. 6	
Zr	1.04	2. 10	

TABLE II

## TZC

		Percent	
Element	Heat M-80	Heat M-91	Heat 4345
Element Al C Cb Co Cr Cu Fe H <sub>2</sub> Mg Mn Mo N <sub>2</sub> Ni	0.008 .127 0.010 0.0025 0.0025 0.0025 0.005 0.0010 0.0025 0.005 Balance 0.0018 0.005	Heat M-91  0.008 .113 - 0.0025 0.0025 0.0025 0.005 0.0010 0.0025 0.005 Balance 0.0034 0.005	Heat 4345  0.008 0.075 0.010 0.0025 0.0025 0.005 0.0002 0.0005 Balance 0.0009 0.005
0 <sub>2</sub> РЬ	0.0041 0.005	0.0037 0.005 0.005	0.0019 0.005 0.005
Si Sn Ti V	0.005 - 1.02 0.005	0.010 1.17 0.005	0.010 1.19 0.005
Zr	0.17	0.27	0.16

TABLE III

## TZM

	Percent			
Element	Heat 7502	Heat KDTZM-1175	Heat 7463	Cb Mod.
A1	0. 008	0.008	-	0.008
С	0.010	0.035	0.016	0.015
Cb	0.010	0.010	-	1.00
Co	0.0025	0.0025	-	0.0025
$\mathtt{Cr}$	0.0025	0.0025	_	0.0025
Cu	0.0025	0.0025	-	0.0025
Fe	0.005	0.005	0.001	0.005
H <sub>2</sub>	0.0007	0.0009	0.0001	0.0004
Mg	0.0025	0.0025	-	0.0025
Mn	0.005	0.005	-	0.005
Mo	Balance	Balance	Balance	Balance
$N_2$	0.0010	0.0031	0.0001	0.0030
Ni	0.005	0.005	0.001	0.005
02	0.002	0.0034	0.0002	0.0039
Ρb	0.005	0.005	-	0.005
Si	0.005	0.005	0.001	0.005
Sn	0.010	0.010	-	0.010
Ti	0.44	0.61	0.48	0.48
V	0.005	0.005	-	0.005
Zr	0.10	0.12	0.080	0.095

TABLE IV

## <u>T-111</u>

		Percent			
	Heat	Heat	Heat	Heat	Heat
Element	70616	65079	D-1670	MCN02A065	D-1102
	<u></u>				
A1	0.005	-	-	10	<b>-</b>
С	0.0044	0.003	0.001	0.004	0.0034
Cb	0.010	0.05	0.0130	0.06 - 0.07	0.0140
Co	0.0025	0.005	0.001	0.0005	0.001
Cr	0.0025	0.0010	-	0.001	cos
Cu	0.0025	0.0020	-	0.002	-
Fe	0.005	0.005	0.002	0.002	0.001
H <sub>2</sub>	0.0006	0.0004	0.0005	0.00026	0.0003
HÍ	2. 30	2. 30	2. 17	2.3 - 3.3	2. 21 ~ 2. 32
Mg	0.0025	_	-	-	-
Mn	0.005	-	-	ao	. <b>-</b>
Mo	0.010	0.015	0.0150	0.001	0.013
$N_2$	0.0020	0.005	0.0020	0.0020	0.0013
Ni	0.005	0.005	0.001	0.001	0.001
02	0.0055	0.013	0.0072	0.010	0.0020
Рb	-	-	-	on-	-
Si	0.005	0.002	-	0.002	em.
Sn	0.010	-	-	-	COT
Ta	Balance	Balance	Balance	Balance	Balance
Ti	0.010	0.002	-	0.002	wa
V	0.005	0.002	0.001	0.001	0.001
W	8.50	8.70	7.9	8.55 - 8.65	7.78 - 8.20

## TABLE V

### <u>T-222</u>

Element	A1-TA-43	Ta-43-SF-2
	<del></del>	
A1	0.005	0.005
С	0.012	0.012
Cb	0.010	0.010
Co	0.0025	0.0025
Cr	0.0025	0.0025
Cu	0.0025	0.0025
Fe	0.005	0.005
H <sub>2</sub>	0.0011	0.0007
н <del>і</del>	2.93	2.53
Mg	0.0025	0.0025
Mn	0.005	0.005
Mo	0.010	0.010
N <sub>2</sub>	0.0026	0.003
Ni	0.005	0.005
O <sub>2</sub> Pb	0.0035	0.0038
РБ	-	0.005
Si	0.005	-
Sn	0.010	0.010
Ti	-	0.010
V	0.005	-
W	9. 57	8.77

TABLE VI
Tungsten, Tungsten-25% Rhenium, Sylvania A

	Percent		
	Tungsten	W-25% Re	
Element	KC 1357	3.5-75002	<u>Sylvania A</u>
A1	0.005	0,002	0.002
С	0.0058	0.007	0.030
Cb	0.010	0.010	0.010
Со	<u>-</u>	0.010	0.001
Cr	0.010	0.0025	0.001
Cu	0.001	0.001	0.001
Fe	0.0025	0.0025	0.0025
Hf	-	-	0.52
H <sub>2</sub>	0.0003	0.0013	0.0003
Mg	0.001	0.001	0.001
Mn	0.001	0.0015	0.0015
Mo	0.010	0.010	0.010
$N_2$	0.0016	0.0007	0.0017
N <sub>2</sub> Ni	0. 001	0.010	0.001
02	0.0009	0.0061	0.002
Рb	0.002	0.002	0.002
Re	-	24.88	mo .
Si	0.0025	0.0025	0.0025
Sn	0.004	0.004	0.004
Ti	0.002	0.002	0.002
V	0.003	0.003	0.003
W	Balance	Balance	Balance

TABLE VII

Columbium-Base

	Percent		
	AS-30	Cb-132M	
	Test B-6	Test B-13	
	1193 Hours	568 Hours	
Element	2000°F (1093°C)	2056°F (1225°C)	
С	0.07	0.15	
Cb	Balance	Balance	
Co	0.001	0.001	
Cu	0.001	0.005	
Fe	0.003	0.003	
H <sub>2</sub>	0.0009	0.0002	
Mn	0.010	0.001	
Mo	0.001	4.73	
N <sub>2</sub>	0.0017	0.0020	
Ni Ni	0.001	0.001	
O <sub>2</sub>	0.0040	0.0003	
Pb	0.001	0.001	
Si	0.003	0.0015	
Ta	-	19.5	
Ti	_	0.001	
V	0.010	0.001	
	20.48	15.6	
W Zr	1. 16	2.40	

TABLE VIII

TZC Heat M-80

	Percent		
	Test B-5A, B,	Test B-9	Test B-12
	1985 Hours	16,002 Hours	14,239 Hours
<u>Element</u>	2000°F (1093°C)	2000°F (1093°C)	2056°F (1225°C)
A 3	0.000	0.000	0.000
Al	0.008	0.008	0.008
С	0.15	0.050	0.11
Cb	0.010	0.010	0.010
Со	0.0025	0.0025	0.0025
Cr	0.0025	0.0025	0.0025
Cu	0.0025	0.0025	0.0025
Fe	0.005	0.005	0.005
$H_2$	0.0005	0.0001	0.0002
m Mg	0.0025	0.0025	0.0025
Mn	0.005	0.005	0.005
Mo	Balance	Balance	Balance
$N_2$	0.0024	0.0010	0.0007
Ni	0.005	0.005	0.005
O Pb	0.0023	0.0023	0.0027
Рģ	0.005	0.005	0.005
Si	0.005	0.005	0.005
Sn	0.010	0.010	0.010
Ti	1.02	1. 10	1. 15
V	0.005	0.005	0.005
Zr	0.16	0.16	0.17

## TABLE IX

## TZM Heat 7502

Element	Test B-3 10,048 Hours 2000°F (1093°C)
A1	0.008
C	0.012
СЪ	0.010
Cr	0.0025
Cu	0.0025
Fe	0. 005
H <sub>2</sub>	0.0007
Mg	0.0025
Mn	0.005
Mo	Balance
N <sub>2</sub>	0.0040
Ni	0.005
02	0.0031
Ρb	0.005
Si	0.005
Sn	0.010
Ti	0.50
V	-
Zr	0.05

<u>TABLE X</u>

T-111 Heat 70616

	Percent		
	Test S-16	Test S-19	
	1675 Hours	4870 Hours	
Element	2600°F (1426°C)	2200°F (1204°C)	
A1	0.005	~	
С	0.005	0.002	
Cb	0.010	-	
Co	0.0025	0.005	
Cr	0.0025	-	
Cu	0.0025	_	
Fe	0.005	0.005	
H <sub>2</sub>	0.0010	0.0003	
НĪ	2.40	2. 32	
Mg	0.0025		
Mn	0.005	-	
Mo	0.010	0.020	
N <sub>2</sub>	0.0040	0.0006	
Ni	0.005	0.005	
O <sub>2</sub> Pb	0.0010	0.0028	
	0.005	-	
Si	0.002		
Sn	0.010	_	
Ta	Balance	Balance	
Ti	0.010	<u>-</u>	
V	0.005	0.005	
W	8.45	8.79	

TABLE XI
Tungsten Heat KC 1357

	Percent		
	Test S-5	Test S-9	
	32 Hours	3886 Hours	
Element	3200°F (1760°C)	3200°F (1760°C)	
Element			
Al	0.005	0.002	
C	0.0033	0.004	
Cb	0.010	0.010	
Co	-	0.001	
Cr	0.010	0.001	
Cu	0.001	0.001	
Fe	0.0025	0. 0025	
H <sub>2</sub>	0.0005	0.0003	
Mg	0.015	0.001	
<b>M</b> n	0.0015	0.0015	
Mo	0.010	0.010	
	0.0010	0.0006	
N <sub>2</sub> Ni	0.010	0.001	
O <sub>2</sub>	0.0010	0.0037	
Pb	0.002	0.002	
Si	0.0025	0.0025	
Sn	0.004	0.004	
Ti	0.002	0.002	
V	0.003	0.003	
W	Balance	Balance	

TABLE XII

Tungsten-25% Rhenium - Heat 3.5-75002

Element	Test S-4 97 Hours 3200°F (1760°C)	Test S-8 1306 Hours 3200°F (1760°C)
Al	0.005	0.002
С	0.006	0.008
Cb	0.010	0.010
Со		0.001
$\operatorname{Cr}$	0.010	0.001
Cu	0.010	0.001
Fe	0.010	0.0025
H <sub>2</sub>	0.0005	0.0011
Mg	0.005	0.001
Mn	0.010	0.0015
Mo	0.020	0.010
N <sub>2</sub>	0.0010	0.0005
Ni	0.010	0.001
02	0.0010	0.0039
Pb	0.005	0.002
Re	24.90	24. 56
Si	0.015	0.0025
Sn	0.005	0.004
${ m Ti}$	0.005	0.002
V	0.015	0.003
W	Balance	Balance

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